Crystalfontz America, Incorporated

GRAPHIC OLED MODULE SPECIFICATIONS

Crystalfontz Model Number	**CFAL12864L-Y-B6TS**
Hardware Version	**Revision A, December 2009**
Data Sheet Version	**Revision 1.0, December 2009**
Product Pages	http://www.crystalfontz.com/product/CFAL12864LYB6TS.html

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REVISION HISTORY

HARDWARE	
2009/12/28	Current hardware version: **vA**

DATA SHEET	
2009/12/28	Current Data Sheet version: **v1.0** New Data Sheet.

CONTENTS

LIST OF FIGURES

MAIN FEATURES

DEMONSTRATION AND EVALUATION PLATFORM

This module is available installed on a Crystalfontz CFA-10009 Demonstration PCB. The DMO-L12864LYB6TS kit has everything you need to easily demonstrate and experiment with the module.The kit can also be used as a reference for your designs. The *CFA10009 User Guide* can be found at the end of this Data Sheet.

COMPARISON TO LCD (LIQUID CRYSTAL DISPLAY) MODULE

The CFAL12864L-Y-B6TS is a yellow 128 x 64 dot matrix Organic Light-Emitting Diode (OLED) display module. The small size, and ultrathin form factor of the CFAL12864L-Y-B6TS makes it possible to use this OLED module in applications where it would be difficult or impossible to fit a traditional LCD module. Because of the low power requirements, the CFAL12864L-Y-B6TS is suitable in battery powered portable devices such as remote controls and scientific meters (for example, temperature, sound, and gas detection).

Compared to most LCD modules, this OLED module has a quicker response time and an extremely wide viewing angle. At the low end of an STN LCD's temperature range, a module's contrast will typically be poor and the response time will be very slow. Unlike an STN LCD module, contrast does not diminish and response time is good at the lower end of an OLED module's operating temperature range, allowing it to operate in cold environments without a heater.

FEATURES

- ❑ 128 x 64 module consists of a touch screen, an OLED panel, a COF (Chip on Flex) driver IC, and an FFC (Flat Flexible Cable) that mates with a ZIF connector.
- ❑ Module Dimensions
  - Active Area is 2.70" diagonal, 61.41 (W) x 30.69 (H) millimeters (2.42" (W) x 1.21" (H)).
  - Overall module dimension with touch screen FFC (Flat Flexible Cable) folded is 75.58 (W) x 68.00 (H) x 3.90 maximum (D) mm (2.98" (W) x 2.68" (H) x 0.15" maximum (D)).
  - Overall module dimension with touch screen FFC (Flat Flexible Cable) unfolded is 111.30 (W) x 68.00 (H) x 3.90 maximum (D) mm (4.38" (W) x 2.68" (H) x 0.15" maximum (D)).
- ❑ Four-wire analog touch screen.
- ❑ Requires 3v for logic and a separate supply for V_{PANEL}.
- ❑ 8-bit parallel (8080 or 6800) interface or SPI Interface.
- ❑ Built-in Solomon Systech SSD1305 or compatible controller.
- ❑ Emissive monochrome display. Display yellow pixels on dark area or dark pixels on yellow area (if operating with display pixels reversed/inverted).
- ❑ Very high contrast ratio.
- ❑ Extremely wide viewing angle is >160°.
- ❑ Wide temperature range for operation is -20°C to +70°C.
- ❑ RoHS compliant.

MODULE CLASSIFICATION INFORMATION

CFA ❶ L ❷ 128 ❸ 64 ❹ L ❺ - Y ❻ - B6 ❼ TS ❽

❶	Brand	Crystalfontz America, Inc.
❷	Display Type	L – OLED
❸	Number of Pixels (Width)	128 pixels
❹	Number of Pixels (Height)	64 pixels
❺	Model Identifier	L
❻	Display Color	Y – Yellow
❼	Special Code 1	B6 – Manufacturer's code
❽	Special Code 2	TS – Touch Screen

ORDERING INFORMATION

PART NUMBER	COLOR
CFAL12864L-Y-B6TS*	yellow 
Additional modules in this series.	
CFAL12864L-Y-B6	yellow 
CFAL12864L-G-B2	green 
CFAL12864L-G-B2TS*	green
CFAL12864L-Y-B2	yellow 
CFAL12864L-Y-B2TS*	yellow
CFAL12864L-G-B4	green 
CFAL12864L-Y-B4	yellow 
**Touch Screen*	

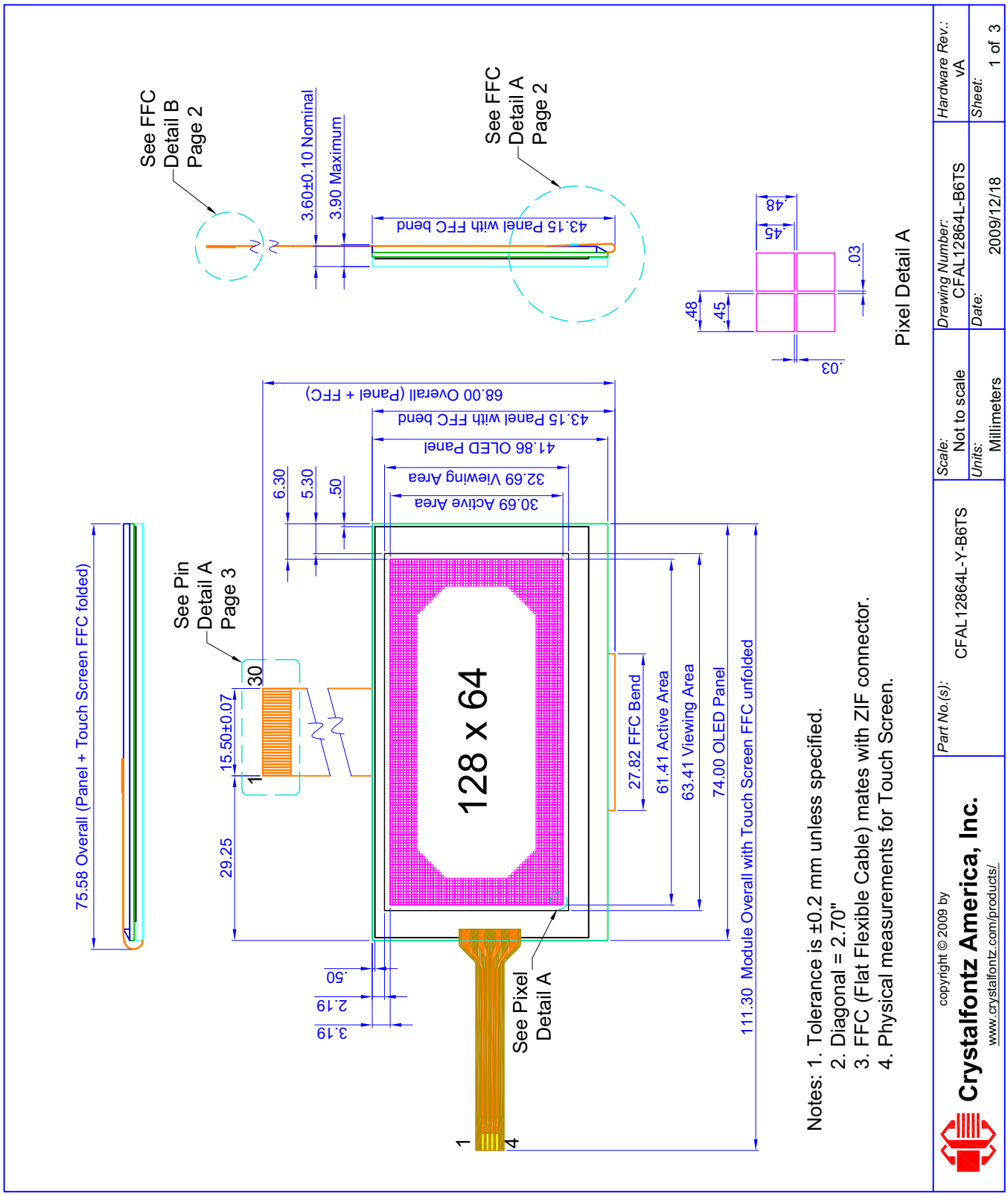
MECHANICAL SPECIFICATIONS

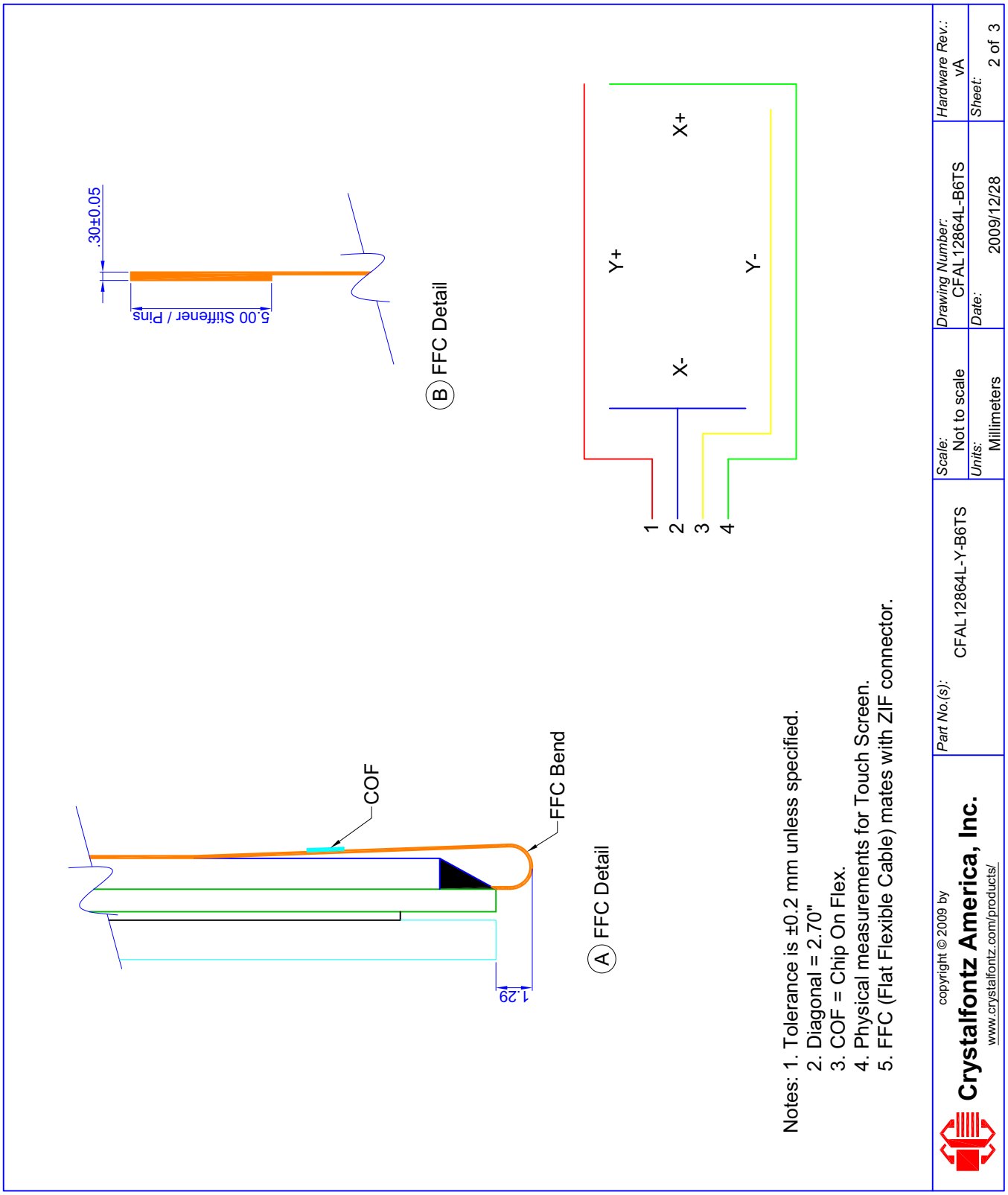
PHYSICAL CHARACTERISTICS

ITEM	SIZE
Pixels	
Number of Pixels	128 x 64 pixels = 8,192 pixels
Pixel Size	0.45 (W) x 0.45 (H) mm
Pixel Pitch	0.48 (W) x 0.48 (H) mm
Viewing Area Width and Height	Millimeters: 63.41 (W) x 32.69 (H) mm Inches: 2.50" (W) x 1.29" (H)
Active Area	
Diagonal	Inches: 2.70"
Width and Height	Millimeters: 61.41 (W) x 30.69 (H) mm Inches: 2.42" (W) x 1.21" (H)
Overall Module Outline Dimensions	
Width with touch screen cable unfolded (FFC)	Millimeters:111.30 mm Inches: 4.38”
Width with touch screen cable folded (FFC)	Millimeters: 75.58 (W) mm Inches: 2.98" (W)
Height (includes Panel FFC)	Millimeters: 68.00 mm Inches: 2.68"
Module Depth	Maximum: Millimeters: 3.9 mm Inches: 0.15" Nominal: Millimeters: 3.6 mm Inches: 0.14"
Module Connector Pitch	0.5 mm
Touch Screen Connector Pitch	1.0 mm
Weight	50 grams (typical)

MODULE OUTLINE DRAWING

Figure 1. Module Outline Drawing (3 pages below)




Y+
X+
X-
Y-
1
2
3
4
B FFC Detail
.30±0.05
5.00 Stiffener / Pins
A FFC Detail
COF
FFC Bend
1.29
Notes: 1. Tolerance is ±0.2 mm unless specified.
2. Diagonal = 2.70"
3. COF = Chip On Flex.
4. Physical measurements for Touch Screen.
5. FFC (Flat Flexible Cable) mates with ZIF connector.
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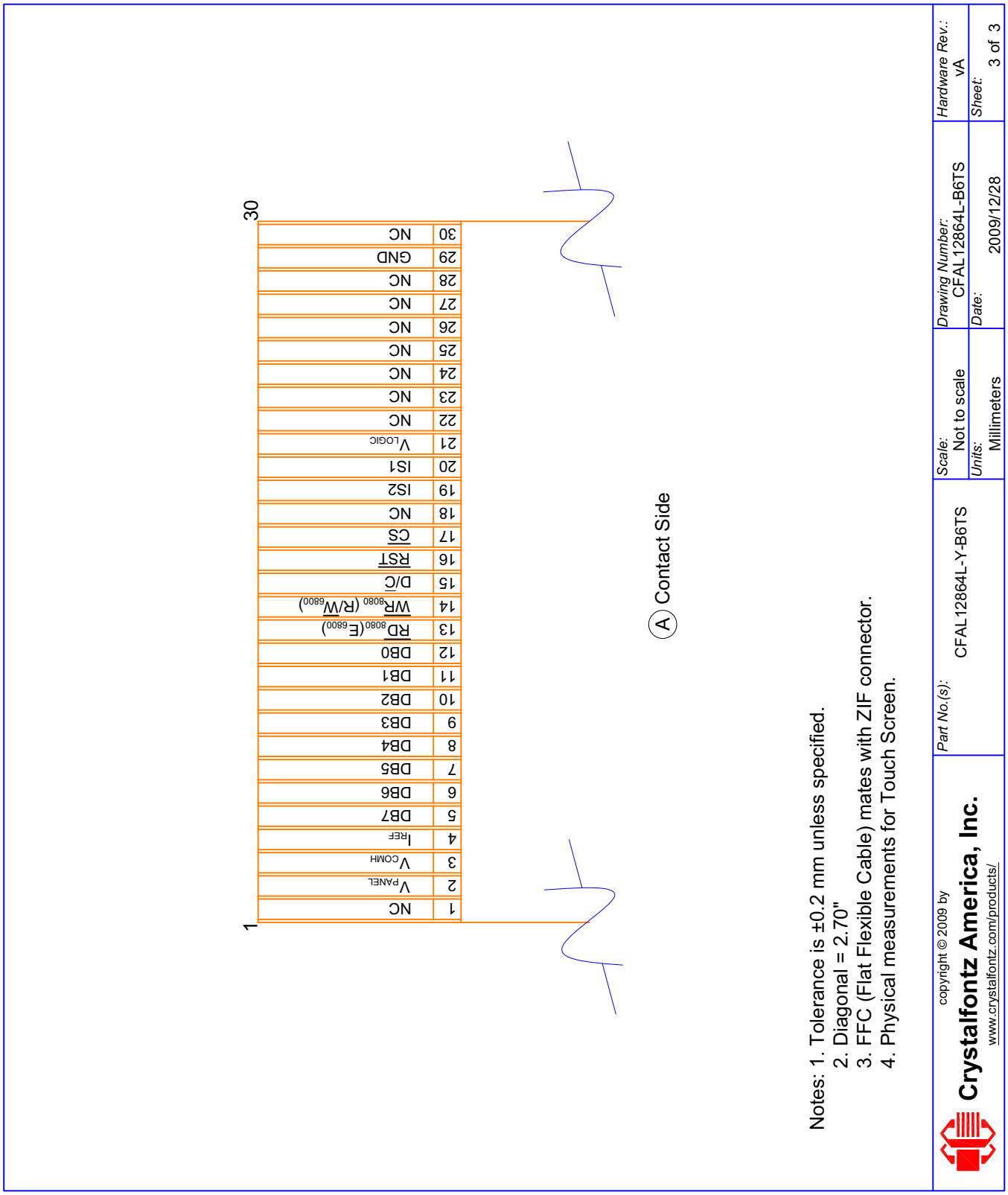
Crystalfontz America, Inc.
www.crystalfontz.com/products/
Part No.(s):
CFAL12864L-Y-B6TS
Scale: Not to scale
Units: Millimeters
Drawing Number: CFAL12864L-B6TS
Date: 2009/12/28
Hardware Rev.: vA
Sheet: 2 of 3


30
1
1 NC
2 VPANEL
3 VCOMH
4 IREF
5 DB7
6 DB6
7 DB5
8 DB4
9 DB3
10 DB2
11 DB1
12 DB0
13 RD8080(E6800)
14 WR8080 (R/W6800)
15 D/C
16 RST
17 CS
18 NC
19 IS2
20 IS1
21 VLOGIC
22 NC
23 NC
24 NC
25 NC
26 NC
27 NC
28 NC
29 GND
30 NC
A Contact Side
Notes: 1. Tolerance is ±0.2 mm unless specified.
2. Diagonal = 2.70"
3. FFC (Flat Flexible Cable) mates with ZIF connector.
4. Physical measurements for Touch Screen.
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Drawing Number: CFAL12864L-B6TS
Date: 2009/12/28
Hardware Rev.: vA
Sheet: 3 of 3

ELECTRICAL SPECIFICATIONS

SYSTEM BLOCK DIAGRAM

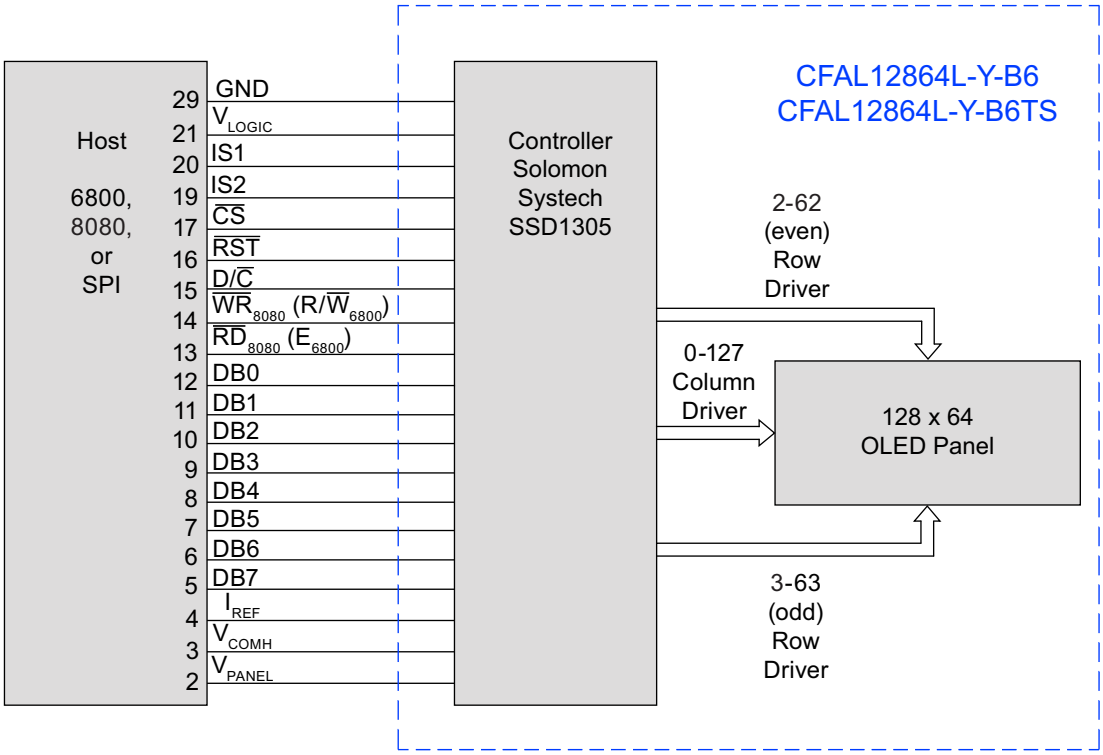


Figure 2. System Block Diagram

CIRCUIT EXAMPLE – V_{PANEL} EXTERNALLY SUPPLIED FOR DISPLAY

The Micrel MIC2290 is one of many possible V_{PANEL} supply solutions.

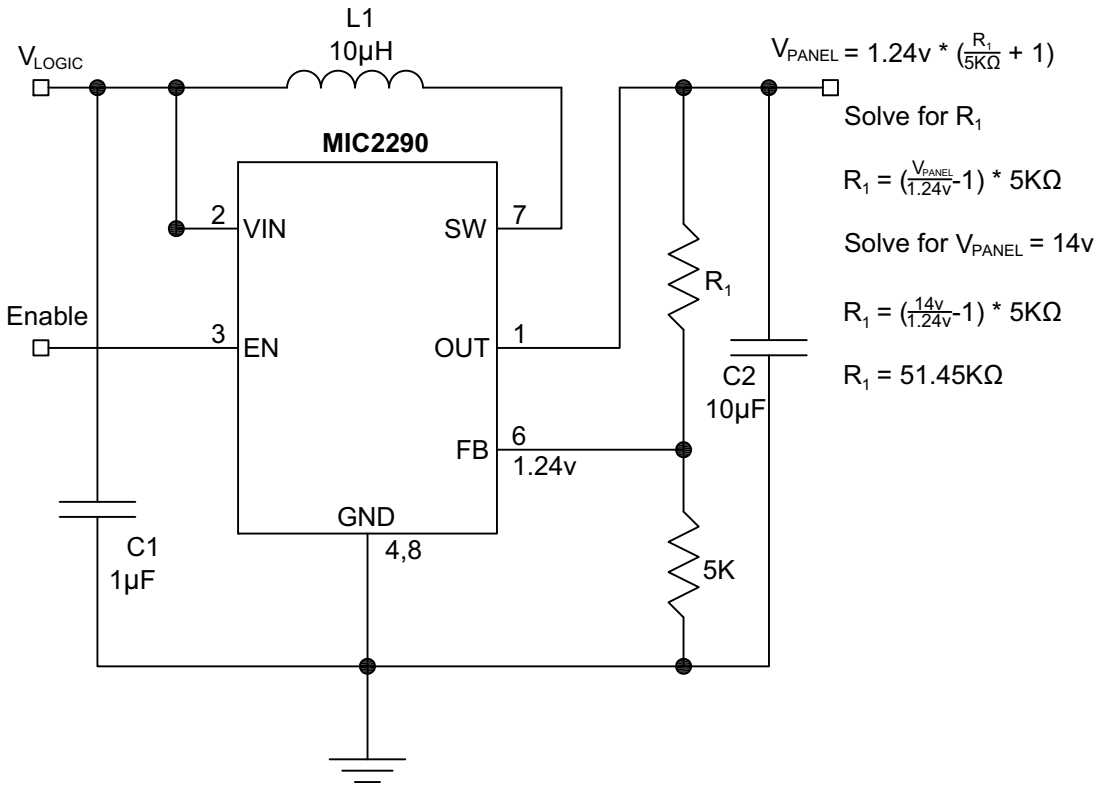


Figure 3. Circuit Example – External Supply for Display

Please refer to the Micrel MIC2290 datasheet for design details. See http://micrel.com/page.do?page=/product-info/products/mic2290.shtml.

POWER UP AND POWER DOWN SEQUENCING

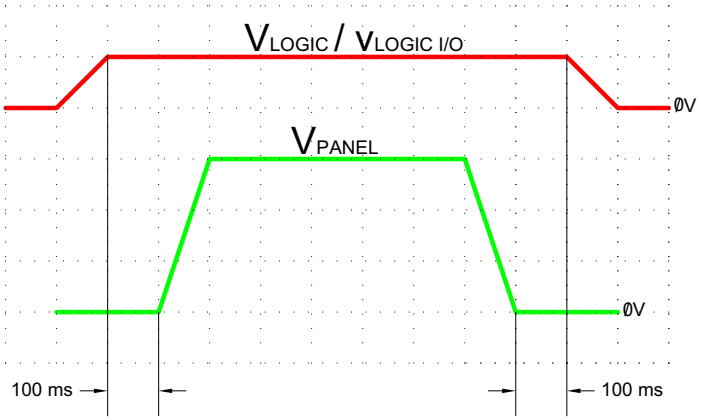


Figure 4. Power Up and Power Down Sequencing

ABSOLUTE MAXIMUM RATINGS

Ambient Temperature (Ta) = 25°C			
ABSOLUTE MAXIMUM RATINGS	**SYMBOL**	**MINIMUM**	**MAXIMUM**
Operating Temperature*	T_{OP}	-20°C	+70°C
Storage Temperature*	T_{ST}	-30°C	+80°C
Humidity	RH	0%	90%
Logic Supply Voltage	V_{LOGIC}	-0.3v	+4.0v
Driver Supply Voltage	V_{PANEL}	+0v	+16v
Operating Current for V_{LOGIC} *Test conditions:* All pixels on V_{LOGIC} = +3.0v V_{PANEL} = +14.0v Frame Rate = 104 Hz Contrast Setting = 0xB0	I_{CC}		60 mA
**Prolonged exposure at temperatures outside of this range may cause permanent damage to the module or decrease product lifetime.*			

DC CHARACTERISTICS

DC CHARACTERISTICS	TEST CONDITION	SYMBOL	MINIMUM	TYPICAL	MAXIMUM
Test Conditions for all tests below: All pixels on V_{LOGIC} = +3.0v V_{PANEL} = +14.0v Frame Rate = 104 Hz Contrast Setting = 0xB0					
Logic Supply Voltage	T_{OP} = -20°C to +70°C	V_{LOGIC}	+2.4v	+3.0v	+3.5v[1]
OLED Driver Supply Voltage[1]	T_{OP} = -20°C to +70°C	V_{PANEL}	+12v	+14v	+14.85v
Input High Voltage		V_{IH}	+0.8v x V_{Logic} For V_{Logic} = +3.0v VIH = +0.8v x +3.0v = +2.4v		V_{Logic}
Input Low Voltage		V_{IL}	0v (GND)		+0.2v x V_{Logic} For V_{Logic} = +3.0v V_{IL} = +0.2v x +3.0v = +0.60v
Output High Voltage	I_{OUT} = 0.5mA 3.3MHz	V_{OH}	+0.9v x V_{Logic} For V_{Logic} = +3.0v V_{OH} = +0.9v x +3.0v = +2.7v		V_{Logic}
Output Low Voltage	I_{OUT} = 0.5mA 3.3MHz	V_{OL}	0v (GND)		+0.1v x V_{Logic} For V_{Logic} = +3.0v V_{OL} = +0.1v x +3.0v = +0.30v

[1] *The V_{PANEL} input must be a stable value with no ripple or noise.*

This is a summary of the module's major operating parameters. For detailed information see APPENDIX D: SOLOMON SYSTECH SSD1305 CONTROLLER SPECIFICATION SHEET (Pg. 35).

DETAILS OF INTERFACE PIN FUNCTION

PIN	SIGNAL	LEVEL	DIRECTION	DESCRIPTION
1	NC			No Connection.
2	V_{PANEL}	+12v to +14.85v		Driver supply voltage. Only high voltage input on chip. Power must be supplied externally. *Note: You must observe power sequencing for this signal.* See Power Up and Power Down Sequencing (Pg. 11). *Power Up* – Display must be powered up and initialized before power is applied to the signal. *Power Down* – Power must be removed from this signal before the display is powered off
3	V_{COMH}		O	High level voltage output for common signals. A low ESR capacitor should be connected between this pin and GND. Do not connect external power supply directly to this pin.
4	I_{REF}		O	Segment output current reference for brightness adjustment. A resistor should be connected between this pin and GND. Used to set the current.
5	DB7	H/L	I/O	Bidirectional databus connects to 8-bit standard host databus. *In serial mode (IS1=0, IS2=0):* DB0 serves as the serial clock input signal (SCL) and DB1 serves as the serial data input pin (SI). DB2-DB7 are high impedance. In serial mode, data can be written to the display but not read. Pin 14 ($\overline{WR}_{8080}$ ($R/\overline{W}_{6800}$) and Pin 13 ($\overline{RD}_{8080}$ (E_{6800}) are unused and should be tied low. *In 6800 Parallel mode:* Pin 14 is used as $R/\overline{W}_{6800}$. Pin 13 is used as E_{6800}. Data is input or output on DB0-DB7. *In 8080 Parallel mode:* Pin14 is used as $\overline{WR}_{8080}$. Pin 13 is used as $\overline{RD}_{8080}$. Data is input or output on DB0-DB7.
6	DB6	H/L	I/O	
7	DB5	H/L	I/O	
8	DB4	H/L	I/O	
9	DB3	H/L	I/O	
10	DB2	H/L	I/O	
11	DB1	H/L	I/O	
12	DB0	H/L	I/O	

Continued on next page.

PIN	SIGNAL	LEVEL	DIRECTION	DESCRIPTION
13	$\overline{RD}_{8080}$ (E_{6800})	H/L	I	Host interface input. *8080 Host:* Active low. Signal on the databus is latched at the rising edge of $\overline{RD}$ signal. *6800 Host:* Enable control signal input active high. *E = High:* Read or Write Active *E = Low:* No Read or Write Active *SPI (serial) mode:* Connect to ground.
14	$\overline{WR}_{8080}$ ($R/\overline{W}_{6800}$)	H/L	I	Host interface input. *8080 Host:* Active low. Signal on the databus is latched at the rising edge of $\overline{WR}$ signal. *6800 Host:* read/write control signal output *R/$\overline{W}$ = High:* Read (Host←Module) *R/$\overline{W}$ = Low:* Write (Host→Module) *SPI (serial) mode:* Connect to ground.
15	D/$\overline{C}$	H/L	I	Data/Command control. Determines whether data bits are data or command. *1 – High:* Addresses the data register. *2 – Low:* Addresses the command register.
16	$\overline{RST}$	H/L	I	Reset signal. *Low:* Display controller is reset. The $\overline{RST}$ pin should be pulsed low shortly after power is applied. *High:* The $\overline{RST}$ pin should be brought high for normal operation.
17	$\overline{CS}$	H/L	I	Chip select input. *Low:* Controller chip is selected. Communications with the host is possible. *High:* Controller chip is not selected. Host interface signals are ignored by the controller.
18	NC			No Connection.

Continued on next page.

<table>
<tr><th>PIN</th><th>SIGNAL</th><th>LEVEL</th><th>DIRECTION</th><th>DESCRIPTION</th></tr>
<tr><td>19</td><td>IS2</td><td>H/L</td><td>I</td><td rowspan="2"><table><tr><th>IS1</th><th>IS2</th><th>Interface Mode</th></tr><tr><td>0</td><td>0</td><td>Serial</td></tr><tr><td>0</td><td>1</td><td>6800 Parallel</td></tr><tr><td>1</td><td>0</td><td>Not Allowed</td></tr><tr><td>1</td><td>1</td><td>8080 Parallel</td></tr></table></td></tr>
<tr><td>20</td><td>IS1</td><td>H/L</td><td>I</td></tr>
<tr><td>21</td><td>V_{LOGIC}</td><td></td><td></td><td>Power supply input. Must be connected to an external source.</td></tr>
<tr><td>22-28</td><td>NC</td><td></td><td></td><td>No Connection.</td></tr>
<tr><td>29</td><td>GND</td><td></td><td></td><td>Ground.</td></tr>
<tr><td>30</td><td>NC</td><td></td><td></td><td>No Connection.</td></tr>
</table>

PHOTO REFERENCE FOR PIN FUNCTIONS

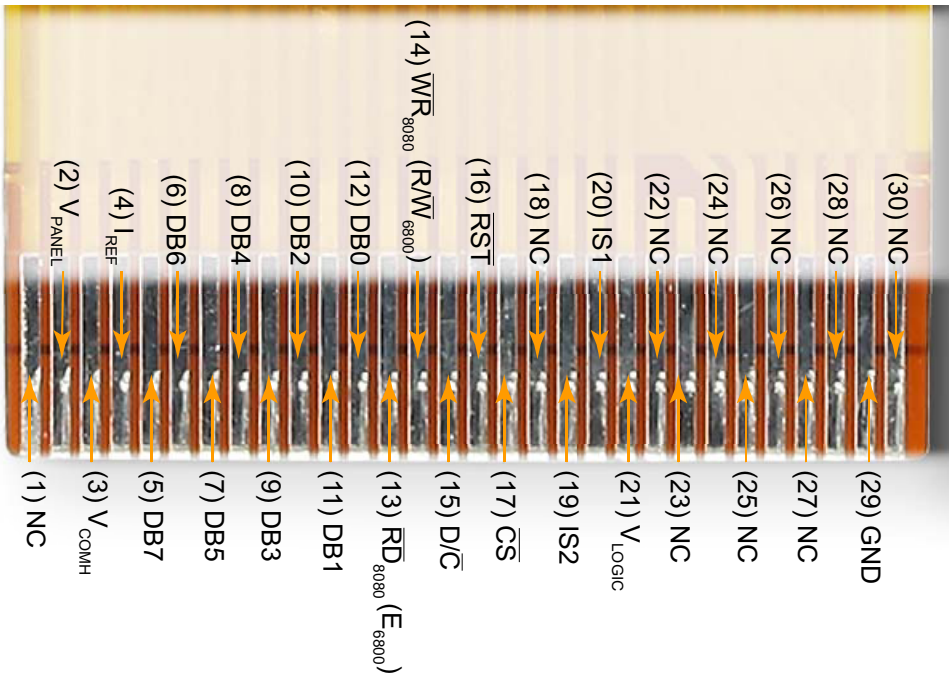


Figure 5. Photo Reference for Pin Functions

ESD (ELECTRO-STATIC DISCHARGE)

The circuitry is industry standard CMOS logic and susceptible to ESD damage. Please use industry standard antistatic precautions as you would for any other static sensitive devices such as expansion cards, motherboards, or integrated circuits. Ground your body, work surfaces, and equipment.

OPTICAL SPECIFICATIONS

OPTICAL CHARACTERISTICS

ITEM	SYMBOL	TEST CONDITION	TYPICAL
Measurements taken at 1/64 duty, 104 Hz Frame Rate, and 0xB0 Contrast Setting.			
Viewing Angle			>160°
Dark Room Contrast Ratio[1]	CR	80 cd/m^2	>100:1
Response Time[2]			<1 ms
Luminous Intensity (IV)	L_{BR}	with polarizer	34 cd/m^2
Duty	1/64		
Aperture	87.8%		

[1] *Contrast Ratio = (brightness with pixels light)/(brightness with pixels dark).*

[2] *Response Time: The amount of time it takes a pixel to change from active to inactive or back again.*

[3] Aperture rate is defined by dividing an effective display area with unit pixel area.

Definition of Viewing Angle

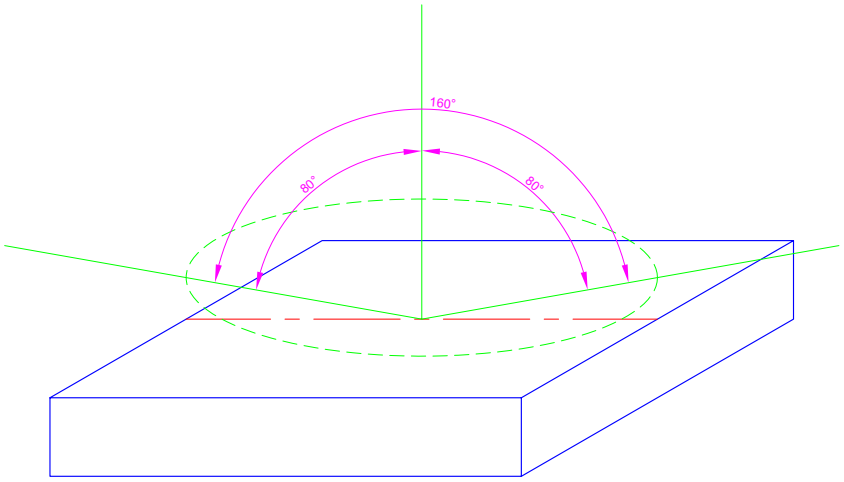


Figure 6. CFAL12864L-Y-B6TS has a 160° Viewing Angle

OLED CONTROLLER INTERFACE

This module uses a Solomon Systech SSD1305 controller. For your reference, we added the controller Data Sheet as an appendix to this Data Sheet. See APPENDIX D: SOLOMON SYSTECH SSD1305 CONTROLLER SPECIFICATION SHEET (Pg. 35).

MODULE RELIABILITY AND LONGEVITY

MODULE RELIABILITY

ITEM	SPECIFICATION
CFAL12864L-Y-B6TS	10,000 hours >50% of initial brightness at typical brightness for a new module.

OLED displays are an emissive technology. Each pixel is susceptible to dimming based on its individual use (burn-in). Frequently used pixels will dim more quickly than pixels that are not used as often. Please avoid using a bright, static, high-contrast image for a long time. If you want to leave the display powered on, please use scrolling text or alternating images to "wear level" the pixels. To conserve power and display lifetime, turn off or dim the display when it is not in use.

MODULE LONGEVITY (EOL/REPLACEMENT POLICY)

Crystalfontz is committed to making all of our modules available for as long as possible. For each module we introduce, we intend to offer it indefinitely. We do not preplan a module's obsolescence. The majority of modules we have introduced are still available.

We recognize that discontinuing a module may cause problems for some customers. However, rapidly changing technologies, component availability, or low customer order levels may force us to discontinue ("End of Life", EOL) a module. For example, we must occasionally discontinue a module when a supplier discontinues a component or a manufacturing process becomes obsolete. When we discontinue a module, we will do our best to find an acceptable replacement module with the same fit, form, and function.

In most situations, you will not notice a difference when comparing a "fit, form, and function" replacement module to the discontinued module. However, sometimes a change in component or process for the replacement module results in a slight variation, perhaps an improvement, over the previous design.

Although the replacement module is still within the stated Data Sheet specifications and tolerances of the discontinued module, changes may require modification to your circuit and/or firmware. Possible changes include:

- *Controller.* A new controller may require minor changes in your code.
- *Component tolerances.* Module components have manufacturing tolerances. In extreme cases, the tolerance stack can change the visual or operating characteristics.

Please understand that we avoid changing a module whenever possible; we only discontinue a module if we have no other option. We will post Part Change Notices on the product's webpage as soon as possible. If interested, you can subscribe to future part change notifications.

CARE AND HANDLING PRECAUTIONS

For optimum operation of the module and to prolong its life, please follow the precautions below.? Excessive voltage will shorten the life of the module. You must drive the display within the specified voltage limit. (See Absolute Maximum Ratings (Pg. 12).

ESD (ELECTRO-STATIC DISCHARGE)

The circuitry is industry standard CMOS logic and susceptible to ESD damage. Please use industry standard antistatic precautions as you would for any other static sensitive devices such as expansion cards, motherboards, or integrated circuits. Ground your body, work surfaces, and equipment.

DESIGN AND MOUNTING

- To protect the touch screen from damage, CFAL12864L-Y-B6TS ships with a protective film over the touch screen. Please peel off the protective film slowly. Peeling off the protective film abruptly may generate static electricity.
- The touch screen is made out of plastic and can be scratched or damaged. Please handle carefully.
- To avoid damage, your bezel must be smooth where it touches the touch screen. Your bezel should not apply undue force to the touch screen.
- To avoid shorting, your mounting bezel should be at least 3 mm from the Active Area of the touch screen.

- Sharp bends can damage the touch screen FFC (Flat Flex Cable). Limit bend radius to at least R5.

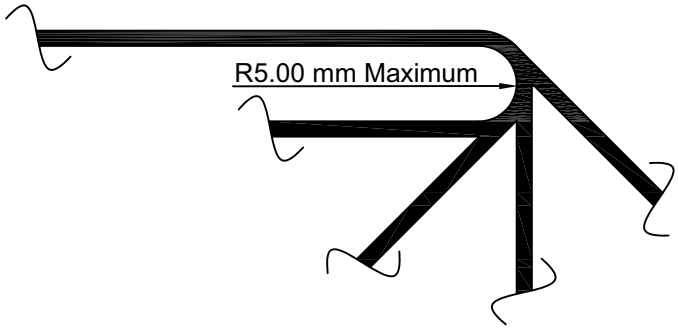


Figure 7. Limit Bend Radius of Touch Screen FFC

- Do not disassemble or modify the module.
- Do not reverse polarity to the power supply connections. Reversing polarity will immediately ruin the module.
- Use care to keep the exposed terminals clean. Contamination, including fingerprints, may make soldering difficult and the reliability of the soldered connection poor.
- The FFC (Flat Flex Cable) mates with a ZIF connector. Click here to see a typical connector sold by Digi-Key.
- Sharp bends can damage the OLED panel FFC. Do not crease FFC. Do not bend FFC tightly against the edge of the OLED panel.
- Do not repeatedly bend the OLED panel FFC beyond its elastic region.

AVOID SHOCK, IMPACT, TORQUE, OR TENSION

- Do not expose the module to strong mechanical shock, impact, torque, or tension.
- Do not drop, toss, bend, or twist the module.
- Do not place weight or pressure on the module.

CLEANING

- The touch screen is plastic. The plastic can be scratched or damaged. To clean the front of the touch screen, gently wipe it with a nonabrasive soft dry cloth. If the touch screen is still not clean, use a nonabrasive soft cloth moistened with isopropyl alcohol.
- Use the removable protective film to remove smudges (for example, fingerprints) and any foreign matter. If you no longer have the protective film, use standard transparent office tape (for example, Scotch® brand “Crystal Clear Tape”). If the touch screen is dusty, you may carefully blow it off with clean, dry, oil-free compressed air.

OPERATION

- We do not recommend connecting this module to a PC's parallel port as an "end product.” This module is not "user friendly" and connecting it to a PC's parallel port is often difficult, frustrating, and can result in a "dead" display due to mishandling. For more information, see our forum thread at http://www.crystalfontz.com/forum/showthread.php?s=&threadid=3257.
- Your circuit should be designed to protect the module from ESD and power supply transients.
- Observe the operating temperature limitations: from -20°C minimum to +70°C maximum with minimal fluctuations. Operation outside of these limits may shorten the life and/or harm the display.
- Operate away from dust, moisture, and direct sunlight.

STORAGE AND RECYCLING

- Store in an ESD-approved container away from dust, moisture, and direct sunlight, fluorescent lamps, or any ultraviolet ray.
- Observe the storage temperature limitations: from -30°C minimum to +80°C maximum with minimal fluctuations. Rapid temperature changes can cause moisture to form, resulting in permanent damage.
- Do not allow weight to be placed on the modules while they are in storage.
- Please recycle your outdated Crystalfontz modules at an approved facility.

APPENDIX A: QUALITY ASSURANCE STANDARDS

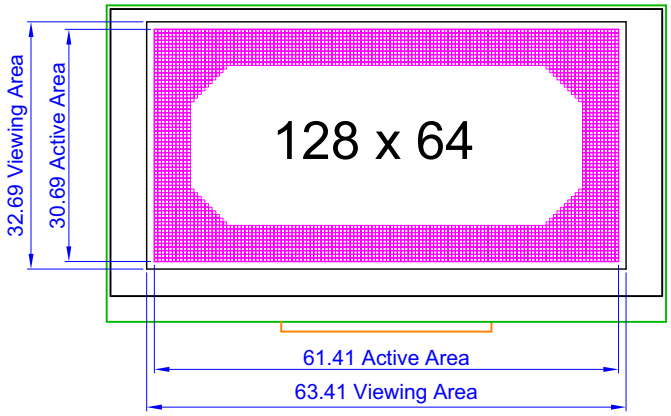
INSPECTION CONDITIONS

- Environment
  - Temperature: 25±5°C
  - Humidity: 30~85% RH (noncondensing)
- For visual inspection of active display area
  - Source lighting: two 20-Watt or one 40-Watt fluorescent light
  - Display adjusted for best contrast
  - Viewing distance: 30±5 cm (about 12 inches)
  - Viewing angle: inspect at 45° angle of vertical line right and left, top and bottom

COLOR DEFINITIONS

We try to describe the appearance of our modules as accurately as possible. For the photos, we adjust for optimal appearance. Actual display appearance may vary due to (1) different operating conditions, (2) small variations of component tolerances, (3) inaccuracies of our camera, (4) color interpretation of the photos on your monitor, and/or (5) personal differences in the perception of color.

DEFINITION OF ACTIVE AREA AND VIEWING AREA



ACCEPTANCE SAMPLING

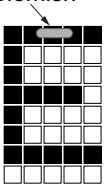
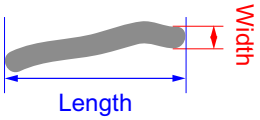
DEFECT TYPE	AQL*
Major	≤.65%
Minor	<1.0%
* Acceptable Quality Level: maximum allowable error rate or variation from standard	

DEFECTS CLASSIFICATION

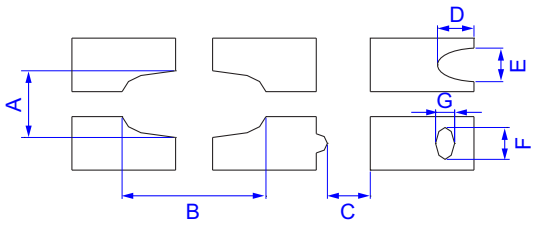
Defects are defined as:

- Major Defect: results in failure or substantially reduces usability of unit for its intended purpose.
- Minor Defect: deviates from standards but is not likely to reduce usability for its intended purpose.

ACCEPTANCE STANDARDS

#	DEFECT TYPE	CRITERIA			MAJOR / MINOR
1	Electrical defects	1. No display, display malfunctions, or shorted segments. 2. Current consumption exceeds specifications.			Major
2	Viewing area defect	Viewing area does not meet specifications.			Major
3	Blemishes or foreign matter on display segments	Blemish 	*Defect Size*	*Acceptable Qty*	Minor
			≤0.30 mm	3	
			≤2 defects within 10 mm of each other		
4	Dark lines or scratches in display area 	*Defect Width*	*Defect Length*	*Acceptable Qty*	Minor
		≤0.03 mm	≤3.0 mm	3	
		0.03 to 0.05	≤2.0 mm	2	
		0.05 to 0.08	≤2.0 mm	1	
		0.08 to 0.10	≤3.0 mm	0	
		≥0.10	>3.0 mm	0	

ACCEPTANCE STANDARDS

<table>
<tr><th>#</th><th>DEFECT TYPE</th><th colspan="3">CRITERIA</th><th>MAJOR / MINOR</th></tr>
<tr><td rowspan="5">5</td><td rowspan="5">Bubbles between polarizer film and glass</td><td colspan="2">Defect Size</td><td>Acceptable Qty</td><td rowspan="5">Minor</td></tr>
<tr><td colspan="2">≤0.20 mm</td><td>Ignore</td></tr>
<tr><td colspan="2">0.20 to 0.40 mm</td><td>3</td></tr>
<tr><td colspan="2">0.40 to 0.60 mm</td><td>2</td></tr>
<tr><td colspan="2">≥0.60 mm</td><td>0</td></tr>
<tr><td rowspan="6">6</td><td rowspan="6">Display pattern defect</td><td colspan="3"> 
</td><td rowspan="6">Minor</td></tr>
<tr><td>Pixel Size</td><td colspan="2">Acceptable Qty</td></tr>
<tr><td>((A+B)/2)≤0.20 mm</td><td colspan="2" rowspan="4">≤3 total defects
≤2 pinholes per digit</td></tr>
<tr><td>C>0 mm</td></tr>
<tr><td>((D+E)/2)≤0.25 mm</td></tr>
<tr><td>((F+G)/2)≤0.25 mm</td></tr>
<tr><td>7</td><td>PCB defects</td><td colspan="3">1. Oxidation or contamination on connectors.*
2. Wrong parts, missing parts, or parts not in specification.*
3. Jumpers set incorrectly.
4. Solder (if any) on bezel, LED pad, zebra pad, or screw hole pad is not smooth.
*Minor if display functions correctly. Major if the display fails.</td><td>Minor</td></tr>
<tr><td>8</td><td>Soldering defects</td><td colspan="3">1. Unmelted solder paste.
2. Cold solder joints, missing solder connections, or oxidation.*
3. Solder bridges causing short circuits.*
4. Residue or solder balls.
5. Solder flux is black or brown.
*Minor if display functions correctly. Major if the display fails.</td><td>Minor</td></tr>
</table>

APPENDIX B: SAMPLE CODE

SOURCES FOR DRIVER LIBRARIES

Graphic driver libraries may save a lot of time and help you develop a more professional product. Possible library sources are easyGUI, en.radzio.dxp.pl, Gwentech, Micriμm, RAMTEX, and Segger emWin.

SAMPLE CODE

The code shows the boot screen logo, first normally, then inverted. You can download the complete source from this link: http://www.crystalfontz.com/products/document/2021/Demonstration_Code.zip.

Note: Please observe V_{PANEL} sequencing as described in Details of Interface Pin Function (Pg. 14). See also Power Up and Power Down Sequencing (Pg. 11).

```
#include <avr/io.h>
#include <util/delay.h>

// all on PORTC
#define LCD_CD  PC7
#define LCD_RW  PC6// 6800 mode name
#define LCD_E     PC5   // 6800 mode name
#define LCD_WR  PC6// 8080 mode name
#define LCD_RD  PC5// 8080 mode name
#define LCD_CS  PC4
#define LCD_RES PC2

#define CLR_CD PORTC &= ~(1<<LCD_CD);
#define SET_CD PORTC |=  (1<<LCD_CD);

#define CLR_CS PORTC &= ~(1<<LCD_CS);
#define SET_CS PORTC |=  (1<<LCD_CS);

#define CLR_RESET PORTC &= ~(1<<LCD_RES);
#define SET_RESET PORTC |=  (1<<LCD_RES);

// 6800 mode pin functions
#define CLR_RW PORTC &= ~(1 << LCD_RW);  // 6800 mode
#define SET_RW PORTC |=  (1 << LCD_RW);  // 6800 mode
#define CLR_E  PORTC &= ~(1 << LCD_E);   // 6800 mode
#define SET_E  PORTC |=  (1 << LCD_E);   // 6800 mode

// 8080 mode pin functions
#define CLR_WR PORTC &= ~(1 << LCD_WR);  // 8080 mode
#define SET_WR PORTC |=  (1 << LCD_WR);  // 8080 mode
#define CLR_RD PORTC &= ~(1 << LCD_RD);  // 8080 mode
#define SET_RD PORTC |=  (1 << LCD_RD);  // 8080 mode

#define MODE68000

// for bmp function
typedef uint8_t bitmap_t[8][128];

void delay(uint32_t twait)
{
        while (twait--)
        asm volatile ("nop");
}
```

```
// ********************************************************************************************* //
uint8_t boot_logo[8][128] =
{
        See full code listing
};
// ********************************************************************************************* //
void oled_cmd(uint8_t cmd)
{

        PORTA = cmd;// set up data on bus
        CLR_CS;   // chip selected
        CLR_CD;   // command mode

#ifdef MODE6800

        CLR_RW;

        // clock E
        SET_E;
        CLR_E;

#else

        SET_RD;

        // clock WR
        CLR_WR;
        SET_WR;

#endif

        SET_CS;   // unselect chip
}
// ********************************************************************************************* //
void oled_data(uint8_t dat)
{
        PORTA = dat;// set up data on bus
        SET_CD;       // data mode
        CLR_CS;       // chip selected

#ifdef MODE6800

        CLR_RW;

        // clock E
        SET_E;
        CLR_E;

#else           // 8080 mode

        SET_RD;

        // clock WR
        CLR_WR;
        SET_WR;

#endif

        SET_CS;       // unselect chip
}
// ********************************************************************************************* //
void lcd_clr(uint8_t color)
{
        int i,p;
```

```
        oled_cmd(0x40);

        for (p=0;p<8;p++) // pages
        {
                oled_cmd(0xB0 + p);   // set page address
                oled_cmd(0x10);       // set high column address
                oled_cmd(0x00);       // set low column address
                for (i=0;i<132;i++)
                {
                        oled_data(color);
                }
        }
}
// ********************************************************************************************* //
void bmp(bitmap_t b)
{
        unsigned int j=0;
        unsigned int page=0;

        oled_cmd(0x00);       // set high column address
        oled_cmd(0x10);       // set low column address

        oled_cmd(0xB0);  // set page address

        for(page=0;page<8;page++)
        {
                for(j=0;j<128;j++)
                {
                        oled_data(b[page][j]);
                }
                // 132x64 logically, lazy, pad the data sent
                oled_data(0);
                oled_data(0);
                oled_data(0);
                oled_data(0);
        }
}
// ********************************************************************************************* //
void init_OLED()
{
        PORTD = 0;     // all off
        DDRD |= (1<<3);// VPP output

        DDRA = 0xFF;    // set PORTA for output

#ifdef MODE6800
        PORTC = 0b11011110;
#else
        PORTC = 0b11111110;
#endif
        DDRC = 0xFE;

        DDRD |= 0x06;// oled pins output

        delay(20000L);

        // reset the display
        CLR_RESET;
        delay(10000);
        SET_RESET;

        delay(20000);

        // enable VPP
        PORTD |= (1<<3);
```

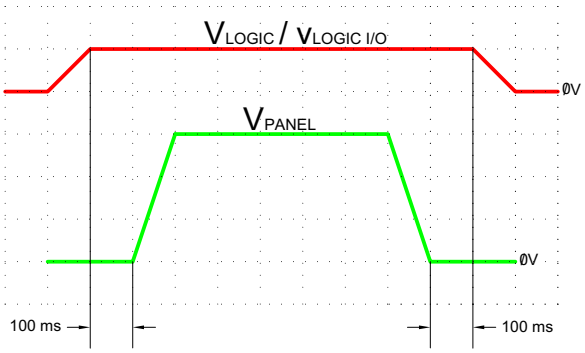
```
        delay(200000L);

        oled_cmd(0xA8);     // Set multiplex ratio
        oled_cmd(0x3F);     // set for 64

        oled_cmd(0x20);     // Set Memory Addressing Mode
        oled_cmd(0x00);     // Horizontal

        oled_cmd(0x81);    // Contrast control mode set
        oled_cmd(0x88);    // (0x00 - 0xFF valid)

        oled_cmd(0xAF);    // Display on

        delay(5000L);

        lcd_clr(0x00);     // clear display
}
// ************************************************************************************** //
int main( void )
{
        init_OLED();

        delay(200000L);

        while (1)
        {
                oled_cmd(0xA6);    // Display normal
                bmp(boot_logo);
                delay(5000000L);
                oled_cmd(0xA7);    // Display inverted
                bmp(boot_logo);
                delay(5000000L);
        }

        return 0;
}
```

APPENDIX C: OLED MODULE TERMS AND SYMBOLS

Crystalfontz Symbol	Equivalents	Description
C		Capacitor
cd/m^2	nit	Candela meter squared is the standard unit of measurement for luminous intensity (photometric brightness).
CIE		A color model based on human perception developed by the CIE (Commission Internationale de l'Eclairage) committee.
CLS		Clock select pin.
COF	COT TAB	Chip On Flex. Controller is on the FPC. Similar in appearance to "TAB." The flex circuit on COF is typically much thinner than the flex of a "flex tail."
COG		Chip On Glass. Controller is on the glass panel.
COM		Common driver. Common signal output for OLED display.
CR		Contrast Ratio = (brightness with pixels light)/(brightness with pixels dark).
$\overline{CS}$	CS# CSB	Chip select input. *Low:* Controller chip is selected. Communications with host is possible. *High:* Controller chip is not selected. Host interface signals are ignored by the controller.
D		Diode
DB0 ~ DB*n*	D0 ~ D*n*	Bidirectional databus connects to 8-bit or 16-bit standard host databus. When SPI (serial interface) is selected, DB0 serves as the serial clock input signal (SCL or SCLK) and DB1 serves as the serial data input signal (SI or SDIN). DB2 to DBn are set to high impedance.
D/$\overline{C}$	RS A0 CD or D/C#	Data/Command control. Determines whether data bits are data or command. *1 – High*: Addresses the data register. *0 – Low:* Addresses the command register.
ESD		Electro-Static Discharge. Sudden and brief electrical current that flows between two objects. ESD between a human and a TFT module can cause permanent damage.
FB		Feedback input for the booster circuit. Use to adjust booster output voltage level, V_{PANEL}.
FFC		Flat Flex Cable. Used for Touch Screen connection. Also called "pigtail."

<table>
<tr><th>Crystalfontz Symbol</th><th>Equivalents</th><th>Description</th></tr>
<tr><td>FG</td><td></td><td>Frame Ground.</td></tr>
<tr><td>FPC</td><td></td><td>Flexible Printed Circuit. Also called “flex tail.” Typically much thicker than the “flex” film of COF (Chip On Flex).</td></tr>
<tr><td>GDR</td><td></td><td>Gate Drive. Output signal drives the gate of the external NMOS of the booster circuit.</td></tr>
<tr><td>GND</td><td>V_{SS}</td><td>Ground. Must be connected to an external ground.</td></tr>
<tr><td>I_{LOGIC}</td><td>I_{DD}</td><td>Operating current for V_{LOGIC}.</td></tr>
<tr><td>$I_{LOGIC, SLEEP}$</td><td>$I_{DD, SLEEP}$</td><td>Sleep mode current for V_{LOGIC}.</td></tr>
<tr><td>I_{PANEL}</td><td>I_{CC}</td><td>Supply current for V_{PANEL}.</td></tr>
<tr><td>$I_{PANEL, SLEEP}$</td><td>$I_{CC, SLEEP}$</td><td>Sleep mode current for V_{PANEL}.</td></tr>
<tr><td>I_{REF}</td><td></td><td>Segment output current reference for brightness adjustment. A resistor should be connected between this pin and GND. Used to set the current.</td></tr>
<tr><td>I/O</td><td></td><td>Input/Output.</td></tr>
<tr><td>IS1</td><td>BS1
C86
M80</td><td rowspan="2"><table><tr><th>IS1</th><th>IS2</th><th>Interface Mode</th></tr><tr><td>0</td><td>0</td><td>SPI (Serial), if available</td></tr><tr><td>0</td><td>1</td><td>6800 Parallel, if available</td></tr><tr><td>1</td><td>0</td><td>Not Allowed</td></tr><tr><td>1</td><td>1</td><td>8080 Parallel</td></tr></table></td></tr>
<tr><td>IS2</td><td>BS2
P/S
MS
$\overline{MS}$
M/S#</td></tr>
<tr><td>$L_{BRNORMAL}$</td><td>IV</td><td>Luminous Intensity Brightness, NORMAL operation.</td></tr>
<tr><td>$L_{BRSTANDBY}$</td><td>IV</td><td>Luminous Intensity Brightness, STANDBY.</td></tr>
<tr><td>mm</td><td></td><td>Millimeter or millimetre. Unit of length equal to one thousandth of a meter.
1 millimeter = 0.0394 inches.</td></tr>
<tr><td>mW</td><td></td><td>Milliwatt is equal to one thousandth of a Watt.
Watts = Volts x Amps.</td></tr>
<tr><td>NC</td><td>nc</td><td>No Connection.</td></tr>
<tr><td>OLED</td><td></td><td>Organic light-emitting diode.</td></tr>
<tr><td>$P_{OPERATION}$</td><td>P_T</td><td>Normal mode Power consumption.</td></tr>
<tr><td>$P_{STANDBY}$</td><td></td><td>Standby mode Power consumption.</td></tr>
<tr><td>Q</td><td></td><td>Transistor, including FET and MOSFET.</td></tr>
</table>

Crystalfontz Symbol	Equivalents	Description
R		Resistor
$\overline{RD}_{8080}$ (E_{6800})	$\overline{RD}$ (E) E ($\overline{RD}$) E RDB	Host interface input. *8080 Host:* Active low. Signal on the databus is latched at the rising edge of $\overline{RD}$. *6800 Host (if available):* Enable control signal input active high. E = *High:* Read or Write operation is active. E = *Low:* No operation.
RH	Rh	Relative Humidity.
RoHS		Restriction of Hazardous Substances Directive, an environmental standard.
$\overline{RST}$	$\overline{RES}$ RST# RES# RSTB	Reset signal. *Low:* Display controller is reset. The $\overline{RST}$ pin should be pulsed low shortly after power is applied. *High:* The $\overline{RST}$ pin should be brought high for normal operation.
SCL	SCK	Serial Clock signal.
SEG		Segment driver. Segment signal output for OLED display.
SENSE		Source current for external NMOS of booster circuit.
SI	SDA MOSI	Serial data Input signal.
SW		Switch output drives the gate of the external NMOS of the booster circuit.
Ta	TA	“Ambient temperature” is the temperature of the air that surrounds a component.
T_{OP}		Operating temperature.
T_{ST}	T_{STG}	Storage Temperature.
V_{BREF}		Internal voltage reference for booster circuit. A decoupling capacitor, typically 1µF, should be connected to GND.
V_{COMH}		High level voltage output for common signals. A low ESR capacitor should be connected between this pin and GND. Do not connect external power supply directly to this pin.
V_{IH}	V_{ICH}	High level input voltage.

Crystalfontz Symbol	Equivalents	Description
V_{IL}	V_{LCH}	Low level input voltage.
V_{LOGIC}	V_{DD} V_{DD1} V_{CC} (if it has PCB)	Power supply input. Must be connected to an external source.
$V_{LOGIC\ I/O}$	$V_{DD\ I/O}$ $V_{I/O}$ V_{CCIO}	Supply voltage for I/O signals.
V_{OH}	V_{OHC}	High level output voltage.
V_{OL}	V_{OLC}	Low level output voltage.
V_{PANEL}	V_{PP} V_{CC} (if no PCB)	Driver supply voltage. Only high voltage input on chip. Power must be supplied externally. *Note: You must observe power sequencing for this signal.* *Power Up* – Display must be powered up and initialized before power is applied to the signal. *Power Down* – Power must be removed from this signal before the display is powered off. 

Crystalfontz Symbol	Equivalents	Description
V_{REF}		Voltage reference pin for pre-charge voltage in driving OLED device. Voltage should be set to match with the OLED driving voltage in current drive phase. It can either be supplied externally or by connecting to $V_{PANEL.}$
V_{SL}		Segment voltage reference pin. This pin should be left open.
$\overline{WR}_{8080}$ (#R/$\overline{W}_{6800}$)	R/$\overline{W}$ ($\overline{WR}$) $\overline{WR}$ (R/$\overline{W}$) R/W# WRB	Host interface input. *8080 Host:* Active low. Signal on the databus is latched at the rising edge of $\overline{WR}$ signal. *#6800 Host (if available):* Read/Write control signal output. *R/$\overline{W}$* = High: Read (Host←Module) *R/$\overline{W}$* = Low: Write (Host→Module)

APPENDIX D: SOLOMON SYSTECH SSD1305 CONTROLLER SPECIFICATION SHEET

The complete *Advance Information 132 x 64 Dot Matrix OLED/PLED Segment/Common Driver with Controll*er Data Sheet revision 1.9 (70 pages) follows.

SSD1305

Advance Information

132 x 64 Dot Matrix
OLED/PLED Segment/Common Driver with Controller

Appendix: IC Revision history of SSD1305 Specification

Version	Change Items	Effective Date
1.0	Change to Advance Info.	27-Mar-06
1.1	Revise command 91h Add a note on the capacitor value in Section 13 Application Example Add I2C Interface	28-Apr-06
1.2	Revise CL pin description in Table 7-1 Revise Figure 10-6	26-Jun-06
1.3	Revise section 8.1.2 & Section 13 Add Figure 10-7	17-Aug-06
1.4	Remove software reset command (E2h) Revise command 26h/27h/29h/2Ah (Set time interval between each scroll step)	06-Sep-06
1.5	Revise Figure 14-1 Application Example Revise Die thickness to 457um from 475um	22-Sep-06
1.6	Revise "Bump Size" of pin "127-147, 294-314" Revise Figure 10-6 ,Figure 8-5 , Figure 13-4	21-Dec-06
1.7	Add light sensitive note In Section 11 – Maximum ratings Revise Note 2 in Section 8.10 Power ON/OFF sequence by adding the word "disable" Add China RoHS disclaimer at the last page.	16-May-07
1.8	For SPI/6800/8080 MCU interface, change the Rise / Fall time (tR/tF) to max. 40ns Revise typo in SSD1305T6R1 dwg on P.68 pitch: From 0.85 change to 0.845	02-Aug-07
1.9	Add SSD1305Z3 in ordering information & add die tray Revise CL pin to "connected to VSS" in Section 8.3 Revise typo in page 42 : from "upper column address is 00h" to "upper column address is 10h"	23-May-08
2.0	Add IC revision history on spec	27-Oct-08

CONTENTS

TABLES

FIGURES

1 GENERAL DESCRIPTION

The SSD1305 is a CMOS OLED/PLED driver with controller for organic/polymer light emitting diode dot-matrix graphic display system. It consists of 132 segments and 64 commons that can support a maximum display resolution of 132x64. There are 4-color selections to support monochrome or area color OLED/PLED. This IC is designed for Common Cathode type OLED panel.

The SSD1305 embeds with contrast control, display RAM and oscillator, which reduces the number of external components and power consumption. It has 256-step brightness control and separate power for I/O interface logic. It is suitable for many compact portable applications, such as mobile phone sub-display, calculator and MP3 player, etc.

2 FEATURES

- Resolution: 132 x 64 dot matrix panel
- Area color support with 4 Color Selection and 64 steps per color
- Power supply:
  - V_{DD} = 2.4V to 3.5V for IC logic
  - V_{CC} = 7.0V to 15.0V for Panel driving
  - V_{DDIO} = 1.6V to V_{DD} for MCU interface
- Segment maximum source current: 320uA
- Common maximum sink current: 45mA
- Embedded 132 x 64 bit SRAM display buffer
- 256-step Contrast Control
- 8-bit 6800-series Parallel Interface, 8-bit 8080-series Parallel Interface, Serial Peripheral Interface, I^2C Interface
- Row Re-mapping and Column Re-mapping
- Continuous Horizontal, Vertical and Diagonal Scrolling
- Dim Mode operations
- Programmable Frame Frequency and Multiplexing Ratio
- On-Chip Oscillator
- Low power consumption
- Wide range of operating temperatures: -40 to 85 °C

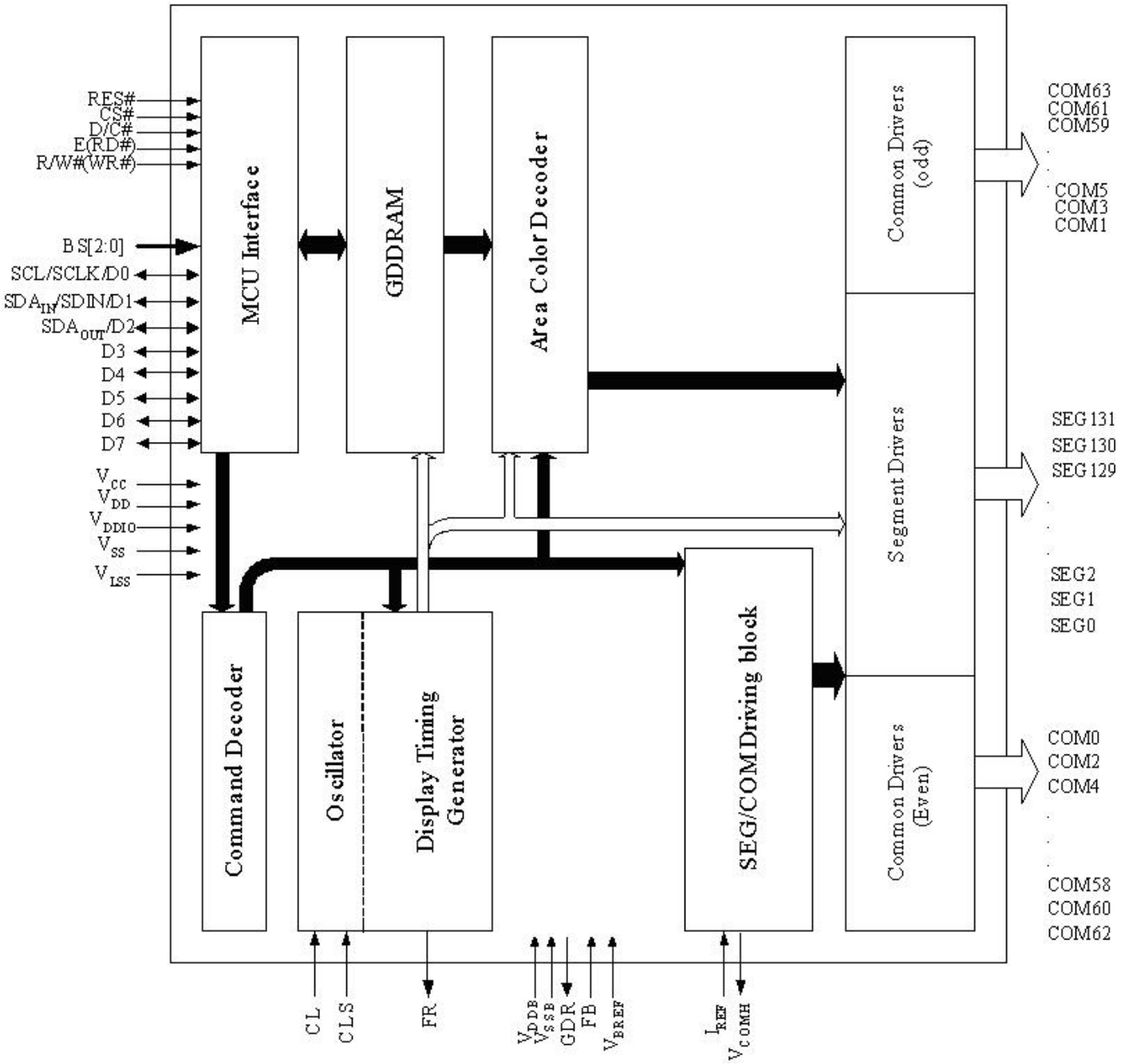
3 ORDERING INFORMATION

Table 3-1 : Ordering Information

Ordering Part Number	SEG	COM	Package Form	Reference	Remark
SSD1305Z	132	64	Gold Bump Die	Page 10, 66	• Min SEG pad pitch: 52um • Min COM pad pitch: 45um
SSD1305T6R1	132	64	TAB	Page 13 ,67	• 35mm film, 4 sprocket hole • Folding TAB • 8-bit 80 / 8-bit 68 / SPI / I^2C interface • SEG lead pitch 0.120mm x 0.998 =0.11976mm • COM lead pitch 0.120mm x 0.998 =0.11976mm
SSD1305T7R1	132	64	TAB	Page 15, 69	• 35mm film, 4 sprocket hole • Folding TAB • 8-bit 80 / 8-bit 68 / SPI / I^2C interface • SEG lead pitch 0.120mm x 0.998 =0.11976mm • COM lead pitch 0.120mm x 0.998 =0.11976mm
SSD1305Z3	132	64	Gold Bump Die	Page 70	• Die Thickness : 300 um ± 25 um

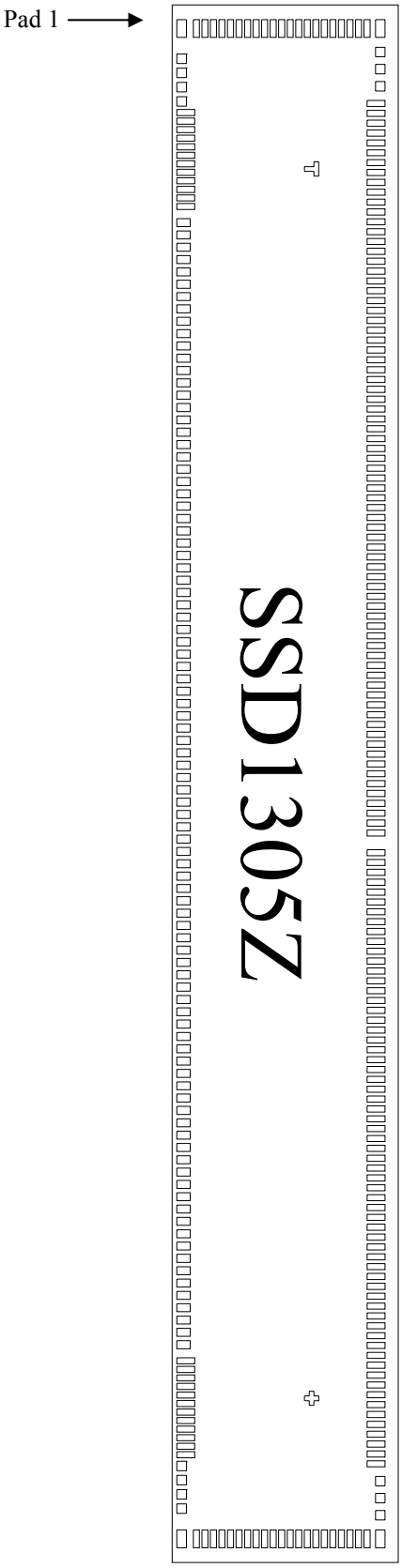
4 BLOCK DIAGRAM

Figure 4-1 : SSD1305 Block Diagram



5 DIE PAD FLOOR PLAN

Figure 5-1 : SSD1305Z Die Drawing

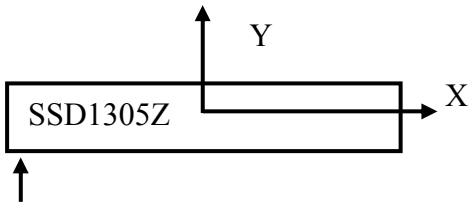


Alignment marks
(For details dimension please see p.9)

	Position	Size
T shape	(-3240, 139)	75um x 75um
+ shape	(3240, 139)	75um x 75um

Die Size	8.2mm x 1.2mm
Die Thickness	457 um ± 25 um
Min I/O pad pitch	65 um
Min SEG pad pitch	52 um
Min COM pad pitch	45 um
Bump Height	Nominal 15 um

Bump Size		
Pad #	**X [um]**	**Y [um]**
1, 126, 148, 293	94	50
18-109	42	70
2-5, 122-125, 149-151, 290-292	50	50
6-17, 110-121,152-289	32	94
127-147, 294-314	94	32



Pad 1,2,3,…->126
Gold Bumps face up

Figure 5-2 : SSD1305Z Alignment Marks Dimension

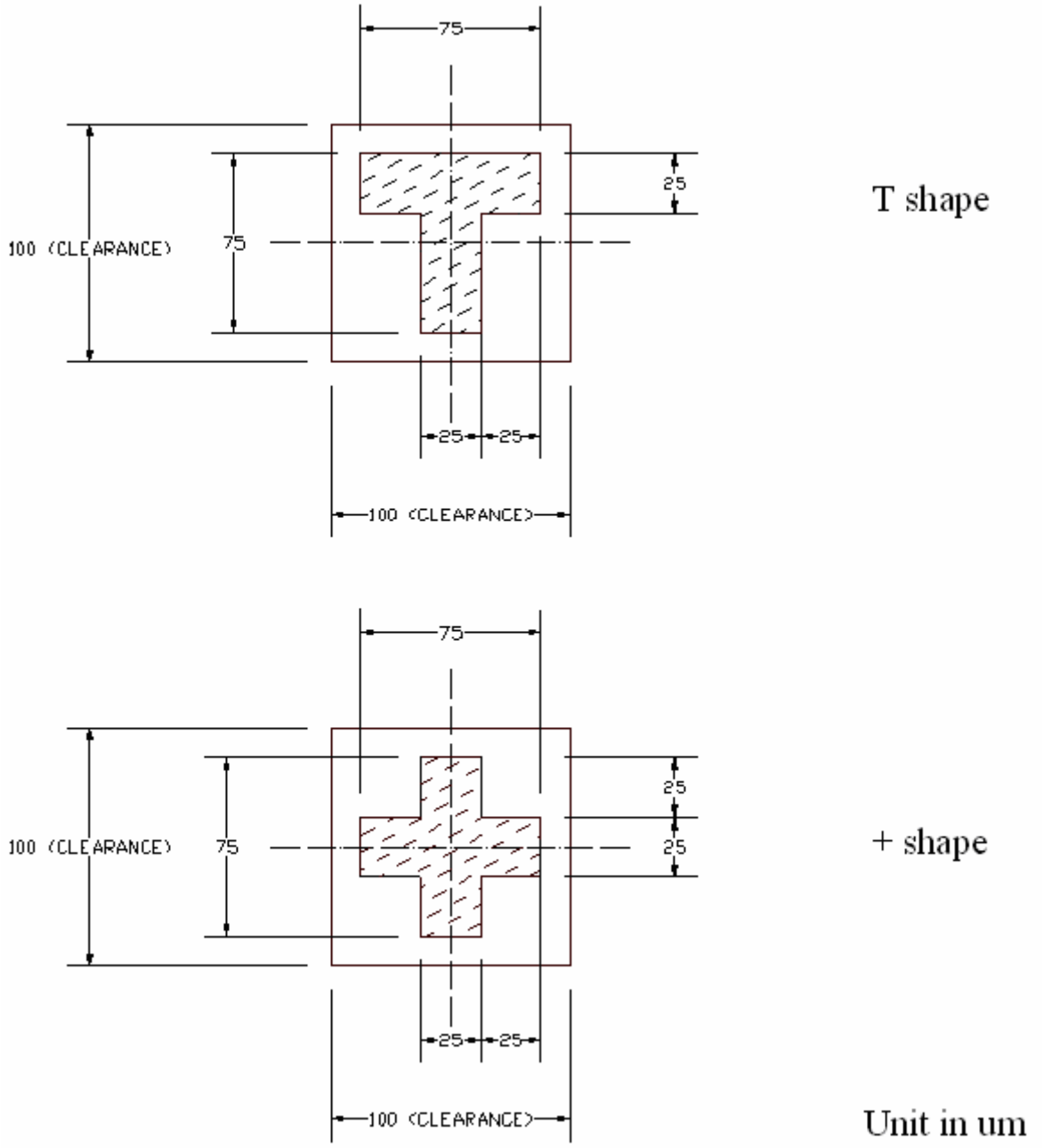


Table 5-1 : SSD1305Z Bump Die Pad Coordinates

Pad no.	Pad Name	X-pos	Y-pos
1	NC	-3980.5	-546.0
2	NC	-3821.5	-546.0
3	NC	-3746.5	-546.0
4	NC	-3671.5	-546.0
5	NC	-3596.5	-546.0
6	COM53	-3537.5	-524.0
7	COM54	-3492.5	-524.0
8	COM55	-3447.5	-524.0
9	COM56	-3402.5	-524.0
10	COM57	-3357.5	-524.0
11	COM58	-3312.5	-524.0
12	COM59	-3267.5	-524.0
13	COM60	-3222.5	-524.0
14	COM61	-3177.5	-524.0
15	COM62	-3132.5	-524.0
16	COM63	-3087.5	-524.0
17	NC	-3042.5	-524.0
18	NC	-2957.5	-536.0
19	VCC	-2892.5	-536.0
20	VCC	-2827.5	-536.0
21	VCC	-2762.5	-536.0
22	VCOMH	-2697.5	-536.0
23	VLSS	-2632.5	-536.0
24	VLSS	-2567.5	-536.0
25	VLSS	-2502.5	-536.0
26	VSS	-2437.5	-536.0
27	VSS	-2372.5	-536.0
28	TR11	-2307.5	-536.0
29	TR10	-2242.5	-536.0
30	TR9	-2177.5	-536.0
31	TR8	-2112.5	-536.0
32	TR7	-2047.5	-536.0
33	TR6	-1982.5	-536.0
34	VSS	-1917.5	-536.0
35	TR5	-1852.5	-536.0
36	TR4	-1787.5	-536.0
37	TR3	-1722.5	-536.0
38	TR2	-1657.5	-536.0
39	TR1	-1592.5	-536.0
40	TR0	-1527.5	-536.0
41	VSS	-1462.5	-536.0
42	VSSB	-1397.5	-536.0
43	GDR	-1332.5	-536.0
44	GDR	-1267.5	-536.0
45	VDDB	-1202.5	-536.0
46	VDDB	-1137.5	-536.0
47	VDDB	-1072.5	-536.0
48	FB	-1007.5	-536.0
49	VBREF	-942.5	-536.0
50	BGGND	-877.5	-536.0
51	VSS	-812.5	-536.0
52	VDDB	-747.5	-536.0
53	VCIR	-682.5	-536.0
54	VCIR	-617.5	-536.0
55	VDD	-552.5	-536.0
56	VDD	-487.5	-536.0
57	VDD	-422.5	-536.0
58	VDD	-357.5	-536.0
59	VDDIO	-292.5	-536.0
60	VDDIO	-227.5	-536.0
61	VDDIO	-162.5	-536.0
62	VCC	-97.5	-536.0
63	VCC	-32.5	-536.0
64	VCC	32.5	-536.0
65	VDDIO	97.5	-536.0
66	BS0	162.5	-536.0
67	VSS	227.5	-536.0
68	BS1	292.5	-536.0
69	VDDIO	357.5	-536.0
70	BS2	422.5	-536.0
71	VSS	487.5	-536.0
72	FR	552.5	-536.0
73	CL	617.5	-536.0
74	VSS	682.5	-536.0
75	CS#	747.5	-536.0
76	RES#	812.5	-536.0
77	D/C#	877.5	-536.0
78	VSS	942.5	-536.0
79	R/W#(WR#)	1007.5	-536.0
80	E(RD#)	1072.5	-536.0
81	VDDIO	1137.5	-536.0
82	D0	1202.5	-536.0
83	D1	1267.5	-536.0
84	D2	1332.5	-536.0
85	D3	1397.5	-536.0
86	VSS	1462.5	-536.0
87	D4	1527.5	-536.0
88	D5	1592.5	-536.0
89	D6	1657.5	-536.0
90	D7	1722.5	-536.0
91	VSS	1787.5	-536.0
92	CLS	1852.5	-536.0
93	VDDIO	1917.5	-536.0
94	VDDIO	1982.5	-536.0
95	VDD	2047.5	-536.0
96	VDD	2112.5	-536.0
97	VDD	2177.5	-536.0
98	IREF	2242.5	-536.0
99	VCOMH	2307.5	-536.0
100	VCC	2372.5	-536.0
101	VCC	2437.5	-536.0
102	VCC	2502.5	-536.0
103	VCC	2567.5	-536.0
104	VCC	2632.5	-536.0
105	VCC	2697.5	-536.0
106	VLSS	2762.5	-536.0
107	VLSS	2827.5	-536.0
108	VLSS	2892.5	-536.0
109	NC	2957.5	-536.0
110	NC	3042.5	-524.0
111	COM31	3087.5	-524.0
112	COM30	3132.5	-524.0
113	COM29	3177.5	-524.0
114	COM28	3222.5	-524.0
115	COM27	3267.5	-524.0
116	COM26	3312.5	-524.0
117	COM25	3357.5	-524.0
118	COM24	3402.5	-524.0
119	COM23	3447.5	-524.0
120	COM22	3492.5	-524.0
121	COM21	3537.5	-524.0
122	NC	3596.5	-546.0
123	NC	3671.5	-546.0
124	NC	3746.5	-546.0
125	NC	3821.5	-546.0
126	NC	3980.5	-546.0
127	COM20	3980.5	-468.4
128	COM19	3980.5	-423.4
129	COM18	3980.5	-378.4
130	COM17	3980.5	-333.4
131	COM16	3980.5	-288.4
132	COM15	3980.5	-243.4
133	COM14	3980.5	-198.4
134	COM13	3980.5	-153.4
135	COM12	3980.5	-108.4
136	COM11	3980.5	-63.4
137	COM10	3980.5	-18.4
138	COM9	3980.5	26.6
139	COM8	3980.5	71.6
140	COM7	3980.5	116.6
141	COM6	3980.5	161.6
142	COM5	3980.5	206.6
143	COM4	3980.5	251.6
144	COM3	3980.5	296.6
145	COM2	3980.5	341.6
146	COM1	3980.5	386.6
147	COM0	3980.5	431.6
148	NC	3980.5	501.1
149	NC	3856.5	501.1
150	NC	3766.5	501.1
151	NC	3676.5	501.1
152	NC	3585.2	479.1
153	NC	3533.3	479.1
154	NC	3481.3	479.1
155	SEG0	3429.4	479.1
156	SEG1	3377.4	479.1
157	SEG2	3325.5	479.1
158	SEG3	3273.5	479.1
159	SEG4	3221.5	479.1
160	SEG5	3169.6	479.1
161	SEG6	3117.6	479.1
162	SEG7	3065.7	479.1
163	SEG8	3013.7	479.1
164	SEG9	2961.7	479.1
165	SEG10	2909.8	479.1
166	SEG11	2857.8	479.1
167	SEG12	2805.9	479.1
168	SEG13	2753.9	479.1
169	SEG14	2701.9	479.1
170	SEG15	2650.0	479.1
171	SEG16	2598.0	479.1
172	SEG17	2546.1	479.1
173	SEG18	2494.1	479.1
174	SEG19	2442.1	479.1
175	SEG20	2390.2	479.1
176	SEG21	2338.2	479.1
177	SEG22	2286.3	479.1
178	SEG23	2234.3	479.1
179	SEG24	2182.3	479.1
180	SEG25	2130.4	479.1
181	SEG26	2078.4	479.1
182	SEG27	2026.5	479.1
183	SEG28	1974.5	479.1
184	SEG29	1922.5	479.1
185	SEG30	1870.6	479.1
186	SEG31	1818.6	479.1
187	SEG32	1766.7	479.1
188	SEG33	1714.7	479.1
189	SEG34	1662.7	479.1
190	SEG35	1610.8	479.1
191	SEG36	1558.8	479.1
192	SEG37	1506.9	479.1
193	SEG38	1454.9	479.1
194	SEG39	1402.9	479.1
195	SEG40	1351.0	479.1
196	SEG41	1299.0	479.1
197	SEG42	1247.1	479.1
198	SEG43	1195.1	479.1
199	SEG44	1143.1	479.1
200	SEG45	1091.2	479.1
201	SEG46	1039.2	479.1
202	SEG47	987.3	479.1
203	SEG48	935.3	479.1
204	SEG49	883.3	479.1
205	SEG50	831.4	479.1
206	SEG51	779.4	479.1
207	SEG52	727.5	479.1
208	SEG53	675.5	479.1
209	SEG54	623.5	479.1
210	SEG55	571.6	479.1
211	SEG56	519.6	479.1
212	SEG57	467.7	479.1
213	SEG58	415.7	479.1
214	SEG59	363.7	479.1
215	SEG60	259.8	479.1
216	SEG61	207.9	479.1
217	SEG62	155.9	479.1
218	SEG63	103.9	479.1
219	SEG64	52.0	479.1
220	SEG65	0.0	479.1
221	SEG66	-52.0	479.1
222	SEG67	-103.9	479.1
223	SEG68	-155.9	479.1
224	SEG69	-207.8	479.1
225	SEG70	-259.8	479.1
226	SEG71	-311.8	479.1
227	SEG72	-363.7	479.1
228	SEG73	-415.7	479.1
229	SEG74	-467.6	479.1
230	SEG75	-519.6	479.1
231	SEG76	-571.6	479.1
232	SEG77	-623.5	479.1
233	SEG78	-675.5	479.1
234	SEG79	-727.4	479.1
235	SEG80	-779.4	479.1
236	SEG81	-831.4	479.1
237	SEG82	-883.3	479.1
238	SEG83	-935.3	479.1
239	SEG84	-987.2	479.1
240	SEG85	-1039.2	479.1
241	SEG86	-1091.2	479.1
242	SEG87	-1143.1	479.1
243	SEG88	-1195.1	479.1
244	SEG89	-1247.0	479.1
245	SEG90	-1299.0	479.1
246	SEG91	-1351.0	479.1
247	SEG92	-1402.9	479.1
248	SEG93	-1454.9	479.1
249	SEG94	-1506.8	479.1
250	SEG95	-1558.8	479.1
251	SEG96	-1610.8	479.1
252	SEG97	-1662.7	479.1
253	SEG98	-1714.7	479.1
254	SEG99	-1766.6	479.1
255	SEG100	-1818.6	479.1
256	SEG101	-1870.6	479.1
257	SEG102	-1922.5	479.1
258	SEG103	-1974.5	479.1
259	SEG104	-2026.4	479.1
260	SEG105	-2078.4	479.1
261	SEG106	-2130.4	479.1
262	SEG107	-2182.3	479.1
263	SEG108	-2234.3	479.1
264	SEG109	-2286.2	479.1
265	SEG110	-2338.2	479.1
266	SEG111	-2390.2	479.1
267	SEG112	-2442.1	479.1
268	SEG113	-2494.1	479.1
269	SEG114	-2546.0	479.1
270	SEG115	-2598.0	479.1
271	SEG116	-2650.0	479.1
272	SEG117	-2701.9	479.1
273	SEG118	-2753.9	479.1
274	SEG119	-2805.8	479.1
275	SEG120	-2857.8	479.1
276	SEG121	-2909.8	479.1
277	SEG122	-2961.7	479.1
278	SEG123	-3013.7	479.1
279	SEG124	-3065.6	479.1
280	SEG125	-3117.6	479.1
281	SEG126	-3169.6	479.1
282	SEG127	-3221.5	479.1
283	SEG128	-3273.5	479.1
284	SEG129	-3325.4	479.1
285	SEG130	-3377.4	479.1
286	SEG131	-3429.4	479.1
287	NC	-3481.3	479.1
288	NC	-3533.3	479.1
289	NC	-3585.2	479.1
290	NC	-3676.5	501.1
291	NC	-3766.5	501.1
292	NC	-3856.5	501.1
293	NC	-3980.5	501.1
294	COM32	-3980.5	431.6
295	COM33	-3980.5	386.6
296	COM34	-3980.5	341.6
297	COM35	-3980.5	296.6
298	COM36	-3980.5	251.6
299	COM37	-3980.5	206.6
300	COM38	-3980.5	161.6
301	COM39	-3980.5	116.6
302	COM40	-3980.5	71.6
303	COM41	-3980.5	26.6
304	COM42	-3980.5	-18.4
305	COM43	-3980.5	-63.4
306	COM44	-3980.5	-108.4
307	COM45	-3980.5	-153.4
308	COM46	-3980.5	-198.4
309	COM47	-3980.5	-243.4
310	COM48	-3980.5	-288.4
311	COM49	-3980.5	-333.4
312	COM50	-3980.5	-378.4
313	COM51	-3980.5	-423.4
314	COM52	-3980.5	-468.4

6 PIN ARRANGEMENT

6.1 SSD1305T6R1 pin assignment

Figure 6-1 : SSD1305T6R1 Pin Assignment

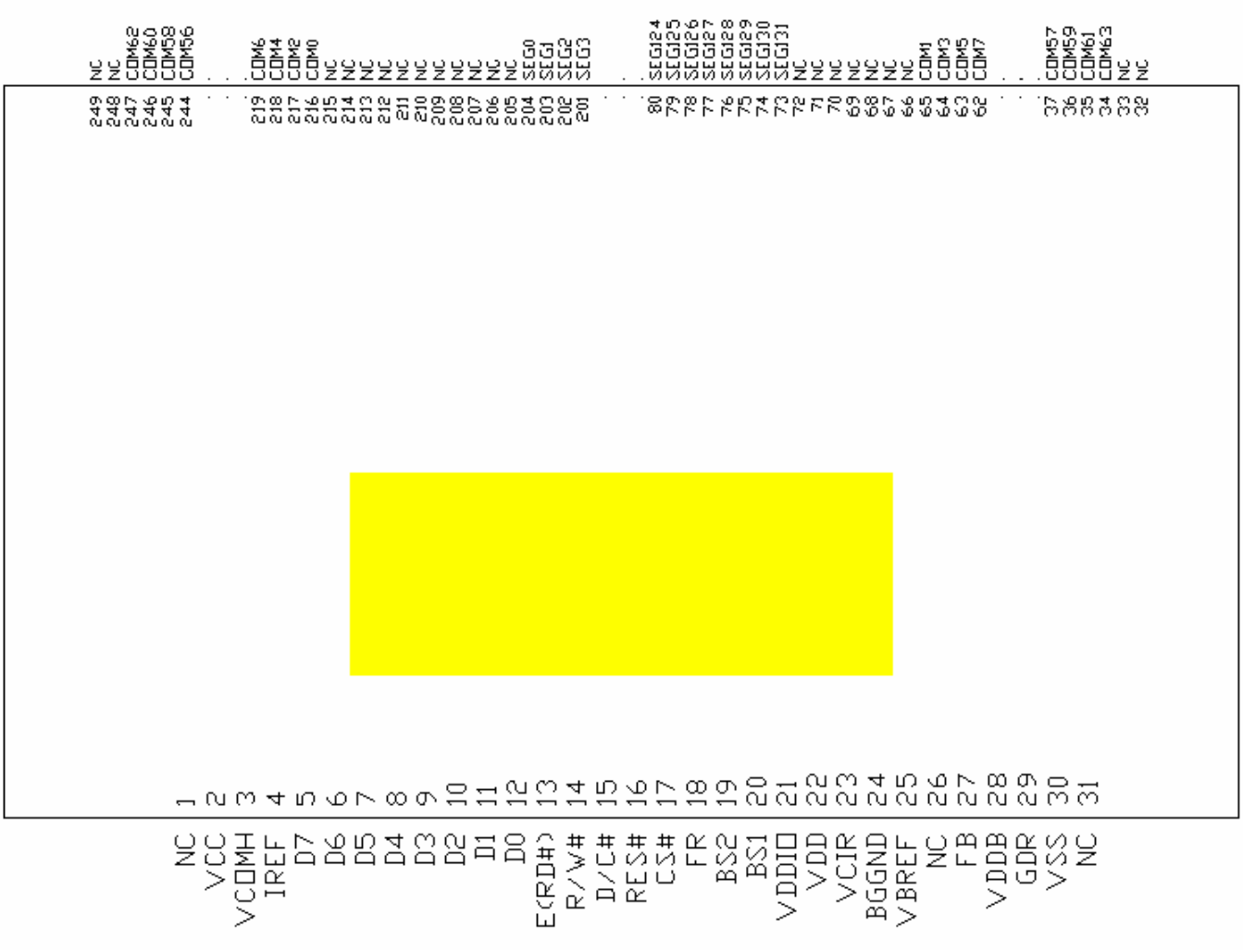


Table 6-1 : SSD1305T6R1 Pin Assignment Table

Pin #	Name
1	NC
2	VCC
3	VCOMH
4	IREF
5	D7
6	D6
7	D5
8	D4
9	D3
10	D2
11	D1
12	D0
13	E(RD#)
14	R/W#
15	D/C#
16	RES#
17	CS#
18	FR
19	BS2
20	BS1
21	VDDIO
22	VDD
23	VCIR
24	BGGND
25	VBREF
26	NC
27	FB
28	VDDB
29	GDR
30	VSS
31	NC
32	NC
33	NC
34	COM63
35	COM61
36	COM59
37	COM57
38	COM55
39	COM53
40	COM51
41	COM49
42	COM47
43	COM45
44	COM43
45	COM41
46	COM39
47	COM37
48	COM35
49	COM33
50	COM31
51	COM29
52	COM27
53	COM25
54	COM23
55	COM21
56	COM19
57	COM17
58	COM15
59	COM13
60	COM11
61	COM9
62	COM7
63	COM5
64	COM3
65	COM1
66	NC
67	NC
68	NC
69	NC
70	NC
71	NC
72	NC
73	SEG131
74	SEG130
75	SEG129
76	SEG128
77	SEG127
78	SEG126
79	SEG125
80	SEG124

Pin #	Name
81	SEG123
82	SEG122
83	SEG121
84	SEG120
85	SEG119
86	SEG118
87	SEG117
88	SEG116
89	SEG115
90	SEG114
91	SEG113
92	SEG112
93	SEG111
94	SEG110
95	SEG109
96	SEG108
97	SEG107
98	SEG106
99	SEG105
100	SEG104
101	SEG103
102	SEG102
103	SEG101
104	SEG100
105	SEG99
106	SEG98
107	SEG97
108	SEG96
109	SEG95
110	SEG94
111	SEG93
112	SEG92
113	SEG91
114	SEG90
115	SEG89
116	SEG88
117	SEG87
118	SEG86
119	SEG85
120	SEG84
121	SEG83
122	SEG82
123	SEG81
124	SEG80
125	SEG79
126	SEG78
127	SEG77
128	SEG76
129	SEG75
130	SEG74
131	SEG73
132	SEG72
133	SEG71
134	SEG70
135	SEG69
136	SEG68
137	SEG67
138	SEG66
139	SEG65
140	SEG64
141	SEG63
142	SEG62
143	SEG61
144	SEG60
145	SEG59
146	SEG58
147	SEG57
148	SEG56
149	SEG55
150	SEG54
151	SEG53
152	SEG52
153	SEG51
154	SEG50
155	SEG49
156	SEG48
157	SEG47
158	SEG46
159	SEG45
160	SEG44

Pin #	Name
161	SEG43
162	SEG42
163	SEG41
164	SEG40
165	SEG39
166	SEG38
167	SEG37
168	SEG36
169	SEG35
170	SEG34
171	SEG33
172	SEG32
173	SEG31
174	SEG30
175	SEG29
176	SEG28
177	SEG27
178	SEG26
179	SEG25
180	SEG24
181	SEG23
182	SEG22
183	SEG21
184	SEG20
185	SEG19
186	SEG18
187	SEG17
188	SEG16
189	SEG15
190	SEG14
191	SEG13
192	SEG12
193	SEG11
194	SEG10
195	SEG9
196	SEG8
197	SEG7
198	SEG6
199	SEG5
200	SEG4
201	SEG3
202	SEG2
203	SEG1
204	SEG0
205	NC
206	NC
207	NC
208	NC
209	NC
210	NC
211	NC
212	NC
213	NC
214	NC
215	NC
216	COM0
217	COM2
218	COM4
219	COM6
220	COM8
221	COM10
222	COM12
223	COM14
224	COM16
225	COM18
226	COM20
227	COM22
228	COM24
229	COM26
230	COM28
231	COM30
232	COM32
233	COM34
234	COM36
235	COM38
236	COM40
237	COM42
238	COM44
239	COM46
240	COM48

Pin #	Name
241	COM50
242	COM52
243	COM54
244	COM56
245	COM58
246	COM60
247	COM62
248	NC
249	NC

6.2 SSD1305T7R1 pin assignment

Figure 6-2 : SSD1305T7R1 Pin Assignment

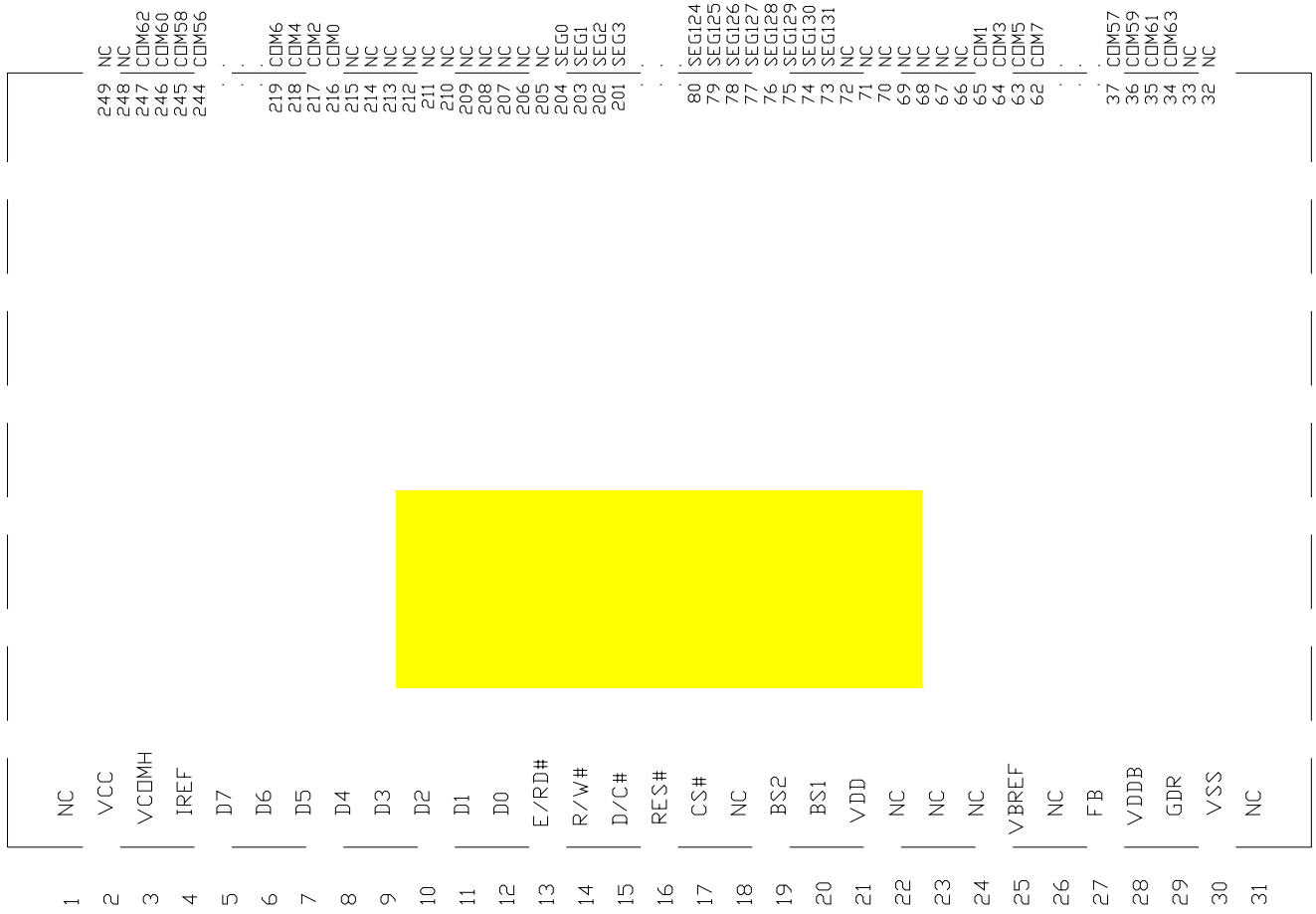


Table 6-2 : SSD1305T7R1 Pin Assignment

Pin #	Name
1	NC
2	VCC
3	VCOMH
4	IREF
5	D7
6	D6
7	D5
8	D4
9	D3
10	D2
11	D1
12	D0
13	E/RD#
14	R/W#
15	D/C#
16	RES#
17	CS#
18	NC
19	BS2
20	BS1
21	VDD
22	NC
23	NC
24	NC
25	VBREF
26	NC
27	FB
28	VDDB
29	GDR
30	VSS
31	NC
32	NC
33	NC
34	COM63
35	COM61
36	COM59
37	COM57
38	COM55
39	COM53
40	COM51
41	COM49
42	COM47
43	COM45
44	COM43
45	COM41
46	COM39
47	COM37
48	COM35
49	COM33
50	COM31
51	COM29
52	COM27
53	COM25
54	COM23
55	COM21
56	COM19
57	COM17
58	COM15
59	COM13
60	COM11
61	COM9
62	COM7
63	COM5
64	COM3
65	COM1
66	NC
67	NC
68	NC
69	NC
70	NC
71	NC
72	NC
73	SEG131
74	SEG130
75	SEG129
76	SEG128
77	SEG127
78	SEG126
79	SEG125
80	SEG124

Pin #	Name
81	SEG123
82	SEG122
83	SEG121
84	SEG120
85	SEG119
86	SEG118
87	SEG117
88	SEG116
89	SEG115
90	SEG114
91	SEG113
92	SEG112
93	SEG111
94	SEG110
95	SEG109
96	SEG108
97	SEG107
98	SEG106
99	SEG105
100	SEG104
101	SEG103
102	SEG102
103	SEG101
104	SEG100
105	SEG99
106	SEG98
107	SEG97
108	SEG96
109	SEG95
110	SEG94
111	SEG93
112	SEG92
113	SEG91
114	SEG90
115	SEG89
116	SEG88
117	SEG87
118	SEG86
119	SEG85
120	SEG84
121	SEG83
122	SEG82
123	SEG81
124	SEG80
125	SEG79
126	SEG78
127	SEG77
128	SEG76
129	SEG75
130	SEG74
131	SEG73
132	SEG72
133	SEG71
134	SEG70
135	SEG69
136	SEG68
137	SEG67
138	SEG66
139	SEG65
140	SEG64
141	SEG63
142	SEG62
143	SEG61
144	SEG60
145	SEG59
146	SEG58
147	SEG57
148	SEG56
149	SEG55
150	SEG54
151	SEG53
152	SEG52
153	SEG51
154	SEG50
155	SEG49
156	SEG48
157	SEG47
158	SEG46
159	SEG45
160	SEG44

Pin #	Name
161	SEG43
162	SEG42
163	SEG41
164	SEG40
165	SEG39
166	SEG38
167	SEG37
168	SEG36
169	SEG35
170	SEG34
171	SEG33
172	SEG32
173	SEG31
174	SEG30
175	SEG29
176	SEG28
177	SEG27
178	SEG26
179	SEG25
180	SEG24
181	SEG23
182	SEG22
183	SEG21
184	SEG20
185	SEG19
186	SEG18
187	SEG17
188	SEG16
189	SEG15
190	SEG14
191	SEG13
192	SEG12
193	SEG11
194	SEG10
195	SEG9
196	SEG8
197	SEG7
198	SEG6
199	SEG5
200	SEG4
201	SEG3
202	SEG2
203	SEG1
204	SEG0
205	NC
206	NC
207	NC
208	NC
209	NC
210	NC
211	NC
212	NC
213	NC
214	NC
215	NC
216	COM0
217	COM2
218	COM4
219	COM6
220	COM8
221	COM10
222	COM12
223	COM14
224	COM16
225	COM18
226	COM20
227	COM22
228	COM24
229	COM26
230	COM28
231	COM30
232	COM32
233	COM34
234	COM36
235	COM38
236	COM40
237	COM42
238	COM44
239	COM46
240	COM48

Pin #	Name
241	COM50
242	COM52
243	COM54
244	COM56
245	COM58
246	COM60
247	COM62
248	NC
249	NC

7 PIN DESCRIPTION

Key: I = Input, O =Output, IO = Bi-directional (input/output), P = Power pin

Table 7-1 : Pin Description

Pin Name	Pin Type	Description
V_{DD}	P	Power supply pin for core logic operation.
V_{DDIO}	P	Power supply for interface logic level. It should be match with MCU interface voltage level. V_{DDIO} must always be equal or lower than V_{DD}.
V_{CC}	P	Power supply for panel driving voltage. This is also the most positive power voltage supply pin.
V_{SS}	P	This is a ground pin.
V_{LSS}	P	This is an analog ground pin. It should be connected to V_{SS} externally.
V_{COMH}	O	The pin for COM signal deselected voltage level. A capacitor should be connected between this pin and V_{SS}.
BGGND	P	This pin must be connected to ground.
V_{DDB}	P	This is a reserved pin. It must be connected to V_{DD}.
V_{SSB}	P	This is a reserved pin. It must be connected to V_{SS}.
GDR	O	This is a reserved pin. It should be kept NC (i.e. Float during normal operation).
FB	I	This is a reserved pin. It should be kept NC (i.e. Float during normal operation).
V_{BREF}	P	This is a reserved pin. It should be kept NC (i.e. Float during normal operation).
V_{CIR}	O	This is a reserved pin. It should be kept NC (i.e. Float during normal operation).
BS[2:0]	I	MCU bus interface selection pins. Please refer to Table 7-2 for the details of setting.
I_{REF}	I	This is segment output current reference pin. A resistor should be connected between this pin and V_{SS} to maintain the I_{REF} current at 10uA. Please refer to Figure 8-18 for the details of resistor value.
FR	O	This pin outputs RAM write synchronization signal. Proper timing between MCU data writing and frame display timing can be achieved to prevent tearing effect. It should be kept NC if it is not used. Please refer to Section 8.4 for details usage.
CL	I	This is external clock input pin. When internal clock is enabled (i.e. HIGH in CLS pin), this pin is not used and should be connected to V_{SS}. When internal clock is disabled (i.e. LOW in CLS pin), this pin is the external clock source input pin.
CLS	I	This is internal clock enable pin. When it is pulled HIGH (i.e. connect to V_{DDIO}), internal clock is enabled. When it is pulled LOW, the internal clock is disabled; an external clock source must be connected to the CL pin for normal operation.
RES#	I	This pin is reset signal input. When the pin is LOW, initialization of the chip is executed. Keep this pin HIGH (i.e. connect to V_{DDIO}) during normal operation.

Pin Name	Pin Type	Description
CS#	I	This pin is the chip select input. (active LOW)
D/C#	I	This is Data/Command control pin. When it is pulled HIGH (i.e. connect to V_{DDIO}), the data at D[7:0] is treated as data. When it is pulled LOW, the data at D[7:0] will be transferred to the command register. In I^2C mode, this pin acts as SA0 for slave address selection. For detail relationship to MCU interface signals, please refer to the Timing Characteristics Diagrams: Figure 13-1 to Figure 13-5.
E (RD#)	I	When interfacing to a 6800-series microprocessor, this pin will be used as the Enable (E) signal. Read/write operation is initiated when this pin is pulled HIGH (i.e. connect to V_{DDIO}) and the chip is selected. When connecting to an 8080-microprocessor, this pin receives the Read (RD#) signal. Read operation is initiated when this pin is pulled LOW and the chip is selected. When serial interface is selected, this pin must be connected to V_{SS}.
R/W#(WR#)	I	This is read / write control input pin connecting to the MCU interface. When interfacing to a 6800-series microprocessor, this pin will be used as Read/Write (R/W#) selection input. Read mode will be carried out when this pin is pulled HIGH (i.e. connect to V_{DDIO}) and write mode when LOW. When 8080 interface mode is selected, this pin will be the Write (WR#) input. Data write operation is initiated when this pin is pulled LOW and the chip is selected. When serial interface is selected, this pin must be connected to V_{SS}.
D[7:0]	IO	These are 8-bit bi-directional data bus to be connected to the microprocessor's data bus. When serial interface mode is selected, D0 will be the serial clock input: SCLK; D1 will be the serial data input: SDIN and D2 should be left opened. When I^2C mode is selected, D2, D1 should be tied together and serve as SDA_{out}, SDA_{in} in application and D0 is the serial clock input, SCL.
TR0-TR11	-	Testing reserved pins. It should be kept NC.
SEG0 ~ SEG131	O	These pins provide Segment switch signals to OLED panel. They are in high impedance stage when display is OFF.
COM0 ~ COM63	O	These pins provide Common switch signals to OLED panel. They are in high impedance state when display is OFF.
NC	-	This is dummy pin. Do not group or short NC pins together.

Table 7-2 : MCU Bus Interface Pin Selection

Pin Name	I^2C Interface	6800-parallel interface (8 bit)	8080-parallel interface (8 bit)	Serial interface
BS0	0	0	0	0
BS1	1	0	1	0
BS2	0	1	1	0

Note
(1) 0 is connected to V_{SS}
(2) 1 is connected to V_{DDIO}

8 FUNCTIONAL BLOCK DESCRIPTIONS

8.1 MCU Interface selection

SSD1305 MCU interface consist of 8 data pins and 5 control pins. The pin assignment at different interface mode is summarized in Table 8-1. Different MCU mode can be set by hardware selection on BS[2:0] pins (please refer to Table 7-2 for BS[2:0] setting).

Table 8-1 : MCU interface assignment under different bus interface mode

Pin Name / Bus Interface	Data/Command Interface								Control Signal				
	D7	**D6**	**D5**	**D4**	**D3**	**D2**	**D1**	**D0**	**E**	**R/W#**	**CS#**	**D/C#**	**RES#**
8-bit 8080	D[7:0]								RD#	WR#	CS#	D/C#	RES#
8-bit 6800	D[7:0]								E	R/W#	CS#	D/C#	RES#
SPI	Tie LOW					NC	SDIN	SCLK	Tie LOW		CS#	D/C#	RES#
I^2C	Tie LOW					SDA_{OUT}	SDA_{IN}	SCL	Tie LOW			SA0	RES#

8.1.1 MCU Parallel 6800-series Interface

The parallel interface consists of 8 bi-directional data pins (D[7:0]), R/W#, D/C#, E and CS#.

A LOW in R/W# indicates WRITE operation and HIGH in R/W# indicates READ operation.
A LOW in D/C# indicates COMMAND read/write and HIGH in D/C# indicates DATA read/write.
The E input serves as data latch signal while CS# is LOW. Data is latched at the falling edge of E signal.

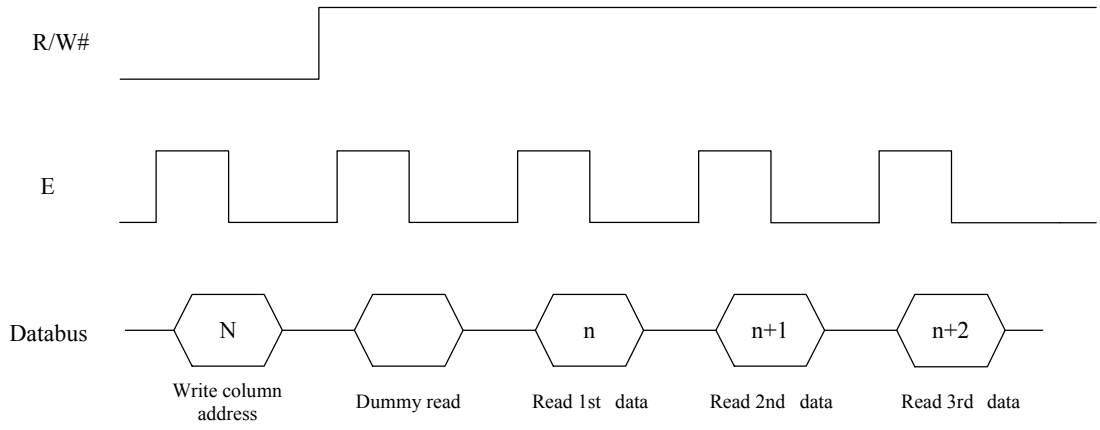
Table 8-2 : Control pins of 6800 interface

Function	E	R/W#	CS#	D/C#
Write command	↓	L	L	L
Read status	↓	H	L	L
Write data	↓	L	L	H
Read data	↓	H	L	H

Note
(1) ↓ stands for falling edge of signal
H stands for HIGH in signal
L stands for LOW in signal

In order to match the operating frequency of display RAM with that of the microprocessor, some pipeline processing is internally performed which requires the insertion of a dummy read before the first actual display data read. This is shown in Figure 8-1.

Figure 8-1 : Data read back procedure - insertion of dummy read



8.1.2 MCU Parallel 8080-series Interface

The parallel interface consists of 8 bi-directional data pins (D[7:0]), RD#, WR#, D/C# and CS#.

A LOW in D/C# indicates COMMAND read/write and HIGH in D/C# indicates DATA read/write.
A rising edge of RD# input serves as a data READ latch signal while CS# is kept LOW.
A rising edge of WR# input serves as a data/command WRITE latch signal while CS# is kept LOW.

Figure 8-2 : Example of Write procedure in 8080 parallel interface mode

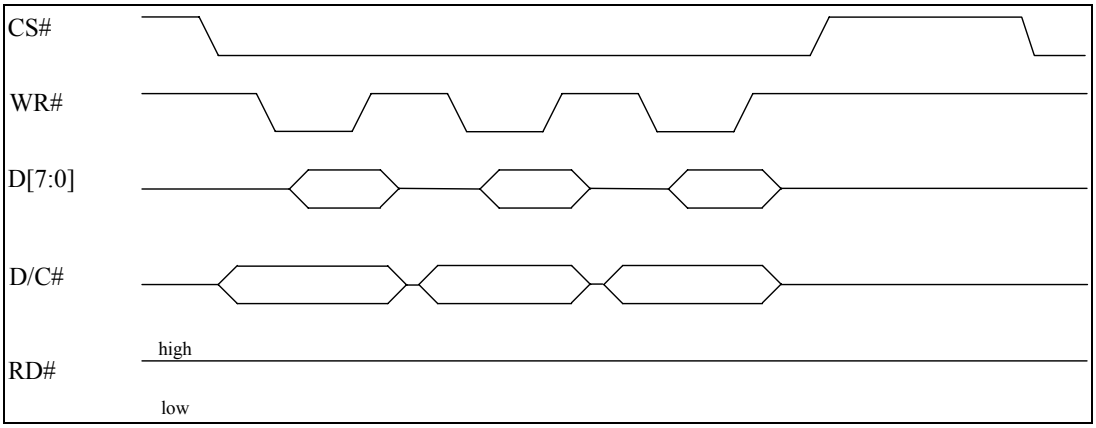


Figure 8-3 : Example of Read procedure in 8080 parallel interface mode

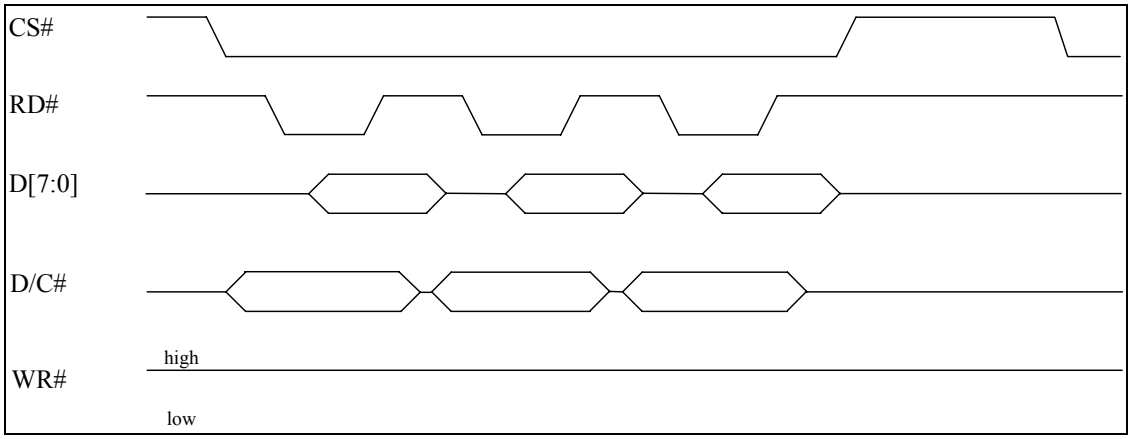


Table 8-3 : Control pins of 8080 interface (Form 1)

Function	RD#	WR#	CS#	D/C#
Write command	H	↑	L	L
Read status	↑	H	L	L
Write data	H	↑	L	H
Read data	↑	H	L	H

Note
(1) ↑ stands for rising edge of signal
(2) H stands for HIGH in signal
(3) L stands for LOW in signal
(4) Refer to Figure 13-2 for Form 1 8080-Series MPU Parallel Interface Timing Characteristics

Alternatively, RD# and WR# can be keep stable while CS# serves as the data/command latch signal.

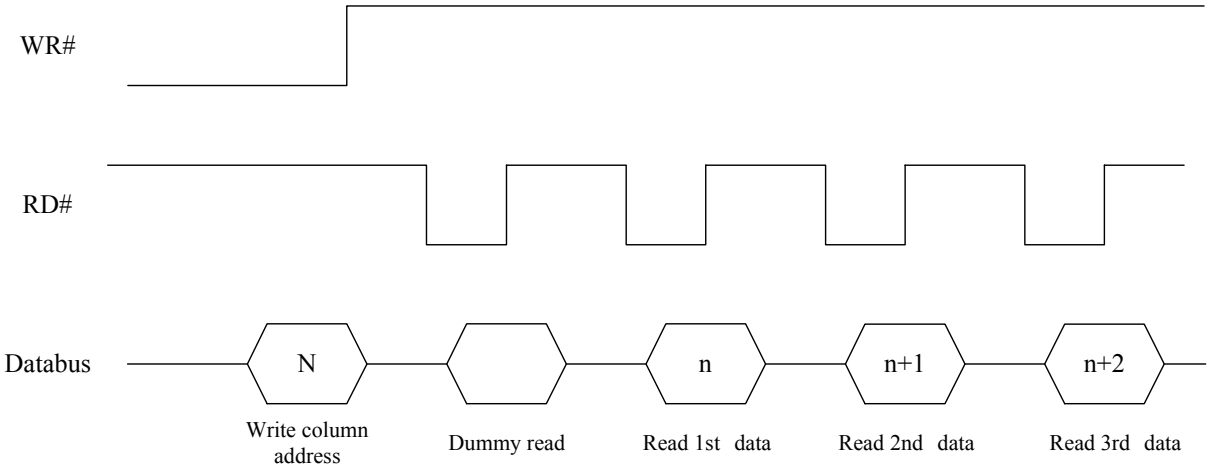
Table 8-4 : Control pins of 8080 interface (Form 2)

Function	RD#	WR#	CS#	D/C#
Write command	H	L	↑	L
Read status	L	H	↑	L
Write data	H	L	↑	H
Read data	L	H	↑	H

Note
(1) ↑ stands for rising edge of signal
(2) H stands for HIGH in signal
(3) L stands for LOW in signal
(4) Refer to Figure 13-3 for Form 2 8080-Series MPU Parallel Interface Timing Characteristics

In order to match the operating frequency of display RAM with that of the microprocessor, some pipeline processing is internally performed which requires the insertion of a dummy read before the first actual display data read. This is shown in Figure 8-4.

Figure 8-4 : Display data read back procedure - insertion of dummy read



8.1.3 MCU Serial Interface

The serial interface consists of serial clock SCLK, serial data SDIN, D/C#, CS#. In SPI mode, D0 acts as SCLK, D1 acts as SDIN. For the unused data pins, D2 should be left open. The pins from D3 to D7, E and R/W# can be connected to an external ground.

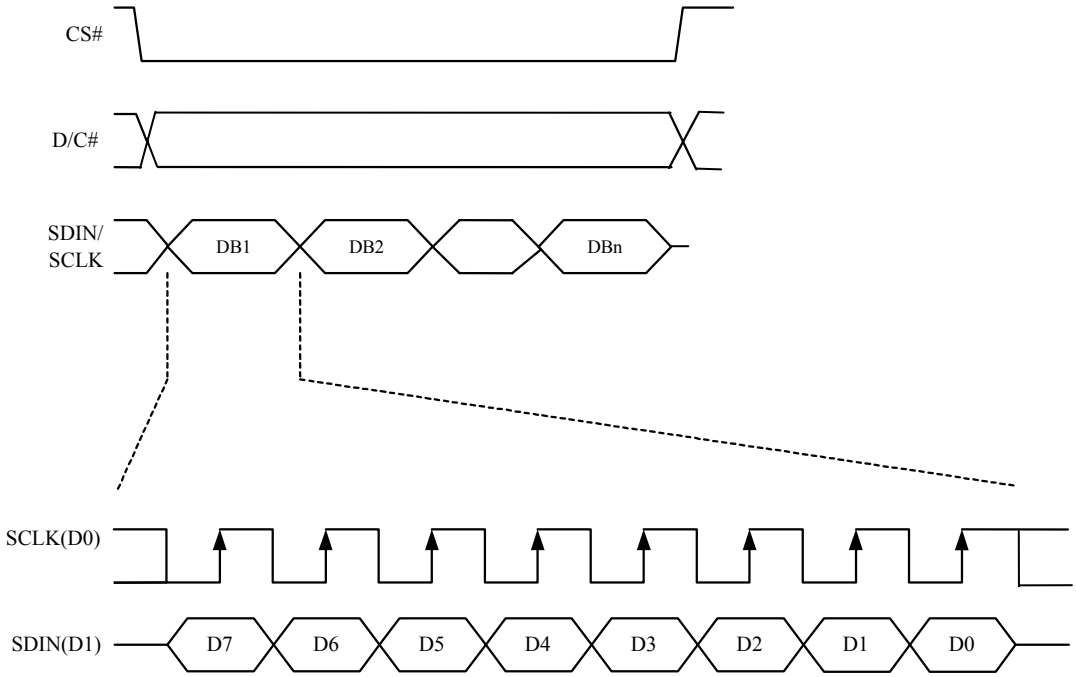
Table 8-5 : Control pins of Serial interface

Function	E(RD#)	R/W#(WR#)	CS#	D/C#	D0
Write command	Tie LOW	Tie LOW	L	L	↑
Write data	Tie LOW	Tie LOW	L	H	↑

Note
(1) ↑ stands for rising edge of signal
(2) H stands for HIGH in signal
(3) L stands for LOW in signal

SDIN is shifted into an 8-bit shift register on every rising edge of SCLK in the order of D7, D6, ... D0. D/C# is sampled on every eighth clock and the data byte in the shift register is written to the Graphic Display Data RAM (GDDRAM) or command register in the same clock.
Under serial mode, only write operations are allowed.

Figure 8-5 : Write procedure in SPI mode



8.1.4 MCU I^2C Interface

The I^2C communication interface consists of slave address bit SA0, I^2C-bus data signal SDA (SDA_{OUT}/D_2 for output and SDA_{IN}/D_1 for input) and I^2C-bus clock signal SCL (D_0). Both the data and clock signals must be connected to pull-up resistors. RES# is used for the initialization of device.

a) Slave address bit (SA0)
SSD1305 has to recognize the slave address before transmitting or receiving any information by the I^2C-bus. The device will respond to the slave address following by the slave address bit ("SA0" bit) and the read/write select bit ("R/W#" bit) with the following byte format,
b_7 b_6 b_5 b_4 b_3 b_2 b_1 b_0
0 1 1 1 1 0 SA0 R/W#
"SA0" bit provides an extension bit for the slave address. Either "0111100" or "0111101", can be selected as the slave address of SSD1305. D/C# pin acts as SA0 for slave address selection.
"R/W#" bit is used to determine the operation mode of the I^2C-bus interface. R/W#=1, it is in read mode. R/W#=0, it is in write mode.

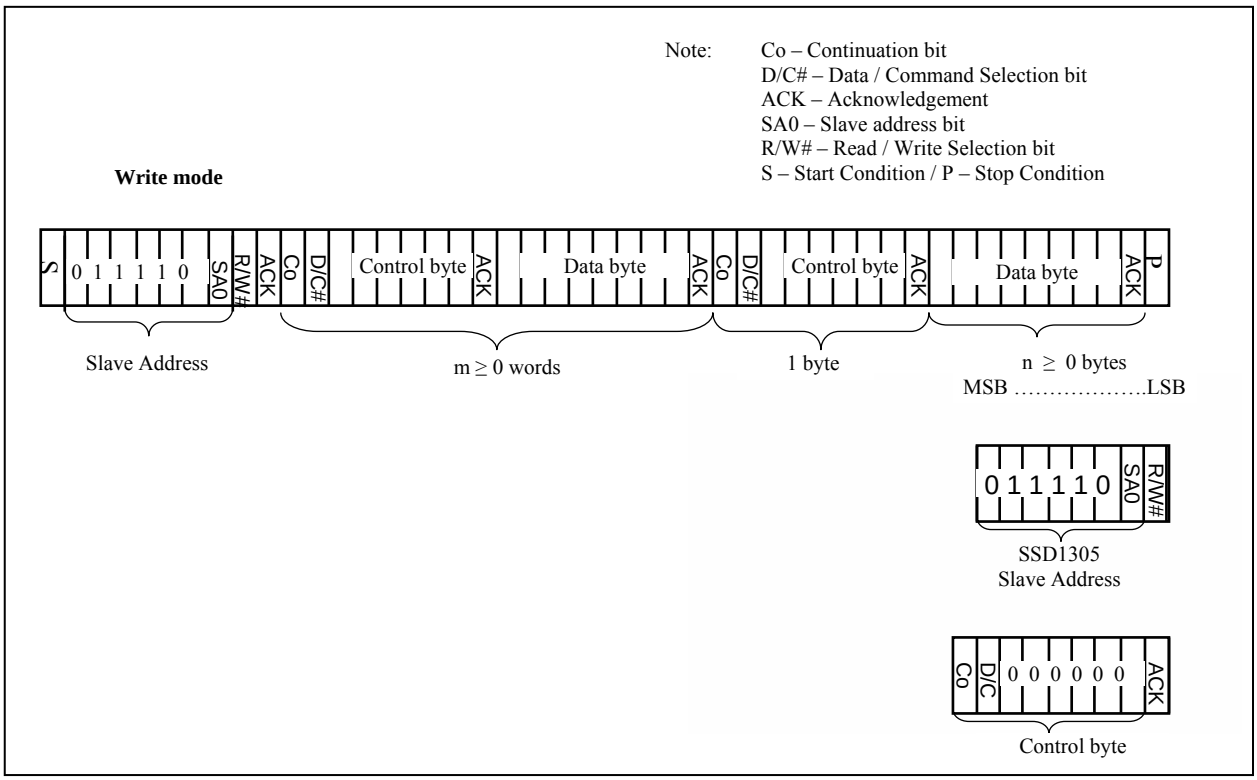
b) I^2C-bus data signal (SDA)
SDA acts as a communication channel between the transmitter and the receiver. The data and the acknowledgement are sent through the SDA.
It should be noticed that the ITO track resistance and the pulled-up resistance at "SDA" pin becomes a voltage potential divider. As a result, the acknowledgement would not be possible to attain a valid logic 0 level in "SDA".
"SDA_{IN}" and "SDA_{OUT}" are tied together and serve as SDA. The "SDA_{IN}" pin must be connected to act as SDA. The "SDA_{OUT}" pin may be disconnected. When "SDA_{OUT}" pin is disconnected, the acknowledgement signal will be ignored in the I^2C-bus.

c) I^2C-bus clock signal (SCL)
The transmission of information in the I^2C-bus is following a clock signal, SCL. Each transmission of data bit is taken place during a single clock period of SCL.

8.1.4.1 I^2C-bus Write data

The I^2C-bus interface gives access to write data and command into the device. Please refer to Figure 8-6 for the write mode of I^2C-bus in chronological order.

Figure 8-6 : I^2C -bus data format



8.1.4.2 Write mode for I^2C

1) The master device initiates the data communication by a start condition. The definition of the start condition is shown in Figure 8-7. The start condition is established by pulling the SDA from HIGH to LOW while the SCL stays HIGH.
2) The slave address is following the start condition for recognition use. For the SSD1305, the slave address is either “b0111100” or “b0111101” by changing the SA0 to LOW or HIGH (D/C pin acts as SA0).
3) The write mode is established by setting the R/W# bit to logic “0”.
4) An acknowledgement signal will be generated after receiving one byte of data, including the slave address and the R/W# bit. Please refer to the Figure 8-8 for the graphical representation of the acknowledge signal. The acknowledge bit is defined as the SDA line is pulled down during the HIGH period of the acknowledgement related clock pulse.
5) After the transmission of the slave address, either the control byte or the data byte may be sent across the SDA. A control byte mainly consists of Co and D/C# bits following by six “0” ‘s.
    a. If the Co bit is set as logic “0”, the transmission of the following information will contain data bytes only.
    b. The D/C# bit determines the next data byte is acted as a command or a data. If the D/C# bit is set to logic “0”, it defines the following data byte as a command. If the D/C# bit is set to logic “1”, it defines the following data byte as a data which will be stored at the GDDRAM. The GDDRAM column address pointer will be increased by one automatically after each data write.
6) Acknowledge bit will be generated after receiving each control byte or data byte.
7) The write mode will be finished when a stop condition is applied. The stop condition is also defined in Figure 8-7. The stop condition is established by pulling the “SDA in” from LOW to HIGH while the “SCL” stays HIGH.

Figure 8-7 : Definition of the Start and Stop Condition

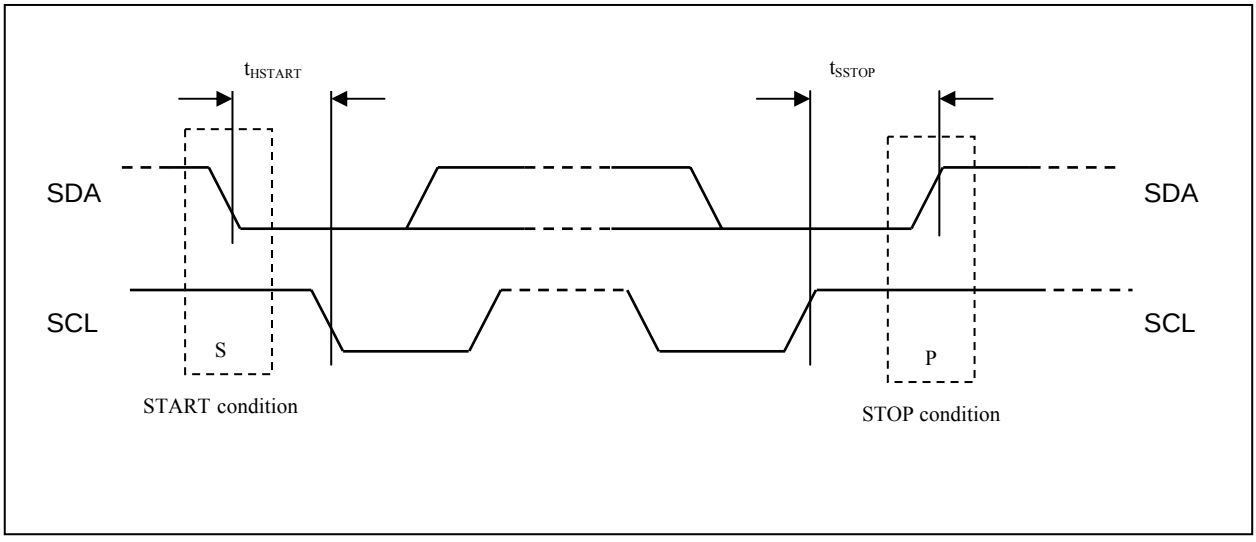
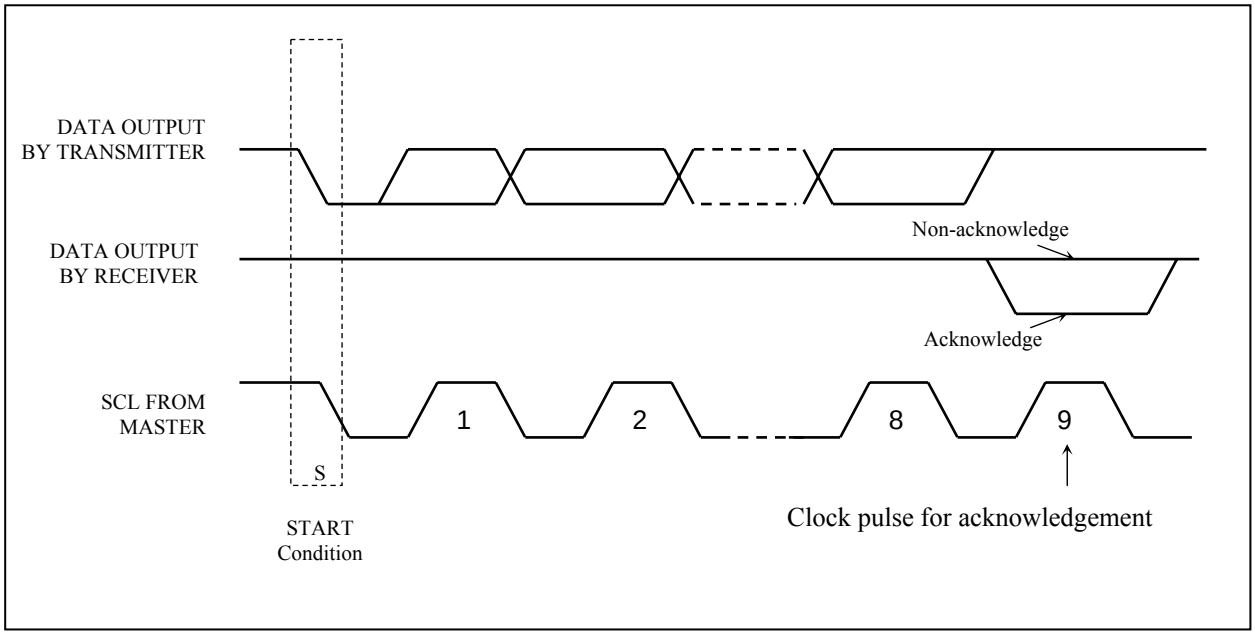


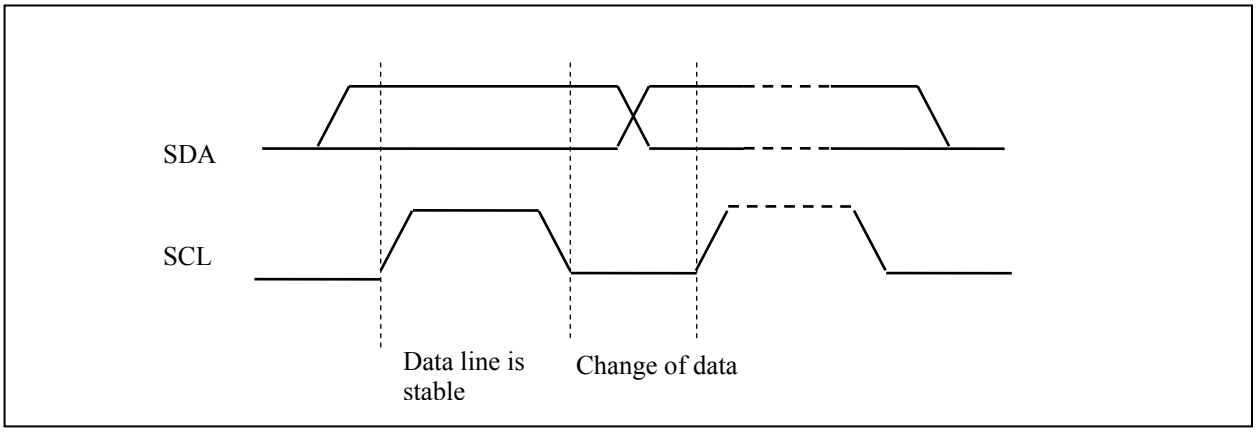
Figure 8-8 : Definition of the acknowledgement condition



Please be noted that the transmission of the data bit has some limitations.

1. The data bit, which is transmitted during each SCL pulse, must keep at a stable state within the "HIGH" period of the clock pulse. Please refer to the Figure 8-9 for graphical representations. Except in start or stop conditions, the data line can be switched only when the SCL is LOW.
2. Both the data line (SDA) and the clock line (SCL) should be pulled up by external resistors.

Figure 8-9 : Definition of the data transfer condition



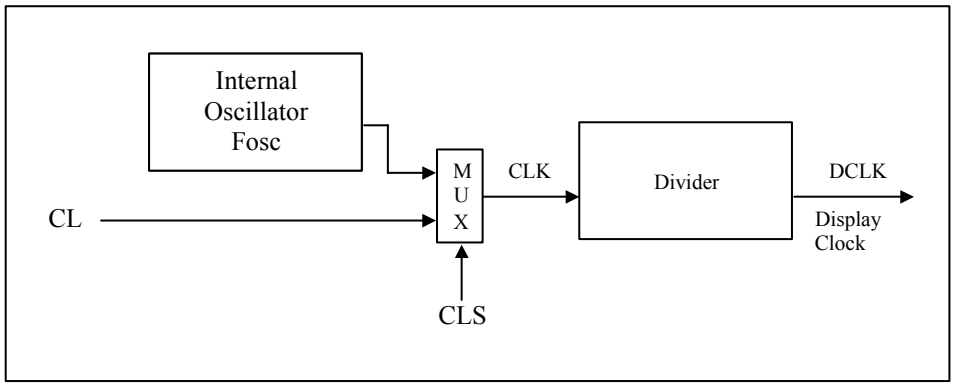
8.2 Command Decoder

This module determines whether the input data is interpreted as data or command. Data is interpreted based upon the input of the D/C# pin.

If D/C# pin is HIGH, D[7:0] is interpreted as display data written to Graphic Display Data RAM (GDDRAM). If it is LOW, the input at D[7:0] is interpreted as a command. Then data input will be decoded and written to the corresponding command register.

8.3 Oscillator Circuit and Display Time Generator

Figure 8-10 : Oscillator Circuit and Display Time Generator



This module is an on-chip LOW power RC oscillator circuitry. The operation clock (CLK) can be generated either from internal oscillator or external source CL pin. This selection is done by CLS pin. If CLS pin is pulled HIGH, internal oscillator is chosen and CL should be connected to V_{SS}. Pulling CLS pin LOW disables internal oscillator and external clock must be connected to CL pins for proper operation. When the internal oscillator is selected, its output frequency Fosc can be changed by command D5h A[7:4].

The display clock (DCLK) for the Display Timing Generator is derived from CLK. The division factor "D" can be programmed from 1 to 16 by command D5h

$$DCLK = F_{OSC} / D$$

The frame frequency of display is determined by the following formula.

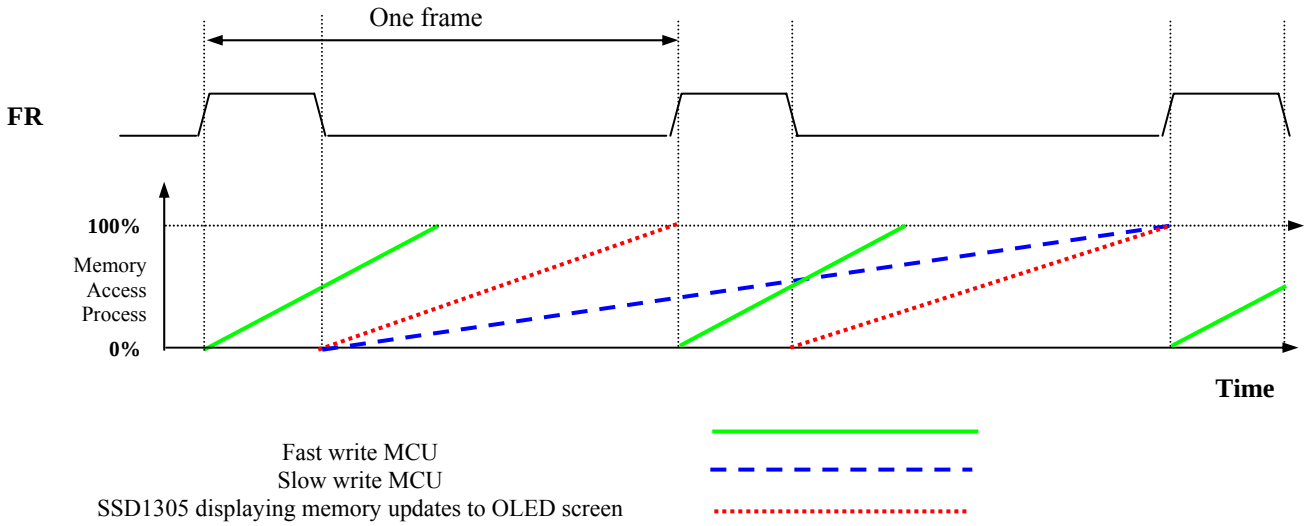
$$F_{FRM} = \frac{F_{osc}}{D \times K \times \text{No. of Mux}}$$

where

- D stands for clock divide ratio. It is set by command D5h A[3:0]. The divide ratio has the range from 1 to 16.
- K is the number of display clocks per row. The value is derived by
  K = Phase 1 period + Phase 2 period + BANK0 pulse width
  = 2 + 2 + 50 = 54 at power on reset
  (Please refer to Section 8.6 "Segment Drivers / Common Drivers" for the details of the "Phase")
- Number of multiplex ratio is set by command A8h. The power on reset value is 63 (i.e. 64MUX).
- F_{OSC} is the oscillator frequency. It can be changed by command D5h A[7:4]. The higher the register setting results in higher frequency.

8.4 FR synchronization

FR synchronization signal can be used to prevent tearing effect.



The starting time to write a new image to OLED driver is depended on the MCU writing speed. If MCU can finish writing a frame image within one frame period, it is classified as fast write MCU. For MCU needs longer writing time to complete (more than one frame but within two frames), it is a slow write one.

For fast write MCU: MCU should start to write new frame of ram data just after rising edge of FR pulse and should be finished well before the rising edge of the next FR pulse.

For slow write MCU: MCU should start to write new frame ram data after the falling edge of the 1st FR pulse and must be finished before the rising edge of the 3rd FR pulse.

8.5 Reset Circuit

When RES# input is LOW, the chip is initialized with the following status:

1. Display is OFF
2. 132 x 64 Display Mode
3. Normal segment and display data column address and row address mapping (SEG0 mapped to address 00h and COM0 mapped to address 00h)
4. Shift register data clear in serial interface
5. Display start line is set at display RAM address 0
6. Column address counter is set at 0
7. Normal scan direction of the COM outputs
8. Contrast control register is set at 80h
9. Normal display mode (Equivalent to A4h command)

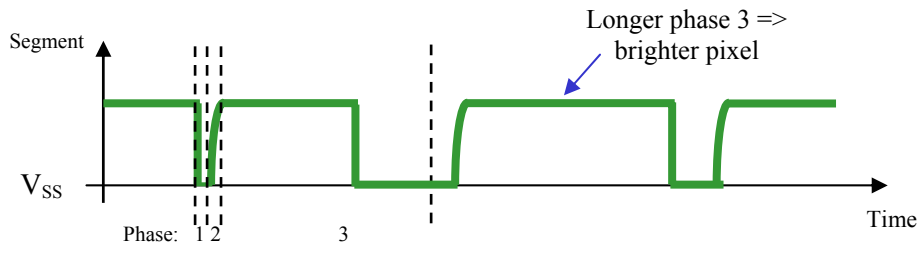
8.6 Segment Drivers / Common Drivers

Segment drivers deliver 132 current sources to drive the OLED panel. The driving current can be adjusted from 0 to 320uA with 256 steps. Common drivers generate voltage-scanning pulses.

The segment driving waveform is divided into three phases:

1. In phase 1, the OLED pixel charges of previous image are discharged in order to prepare for next image content display.
2. In phase 2, the OLED pixel is driven to the targeted voltage. The pixel is driven to attain the corresponding voltage level from V_{SS}. The period of phase 2 can be programmed in length from 1 to 15 DCLKs. If the capacitance value of the pixel of OLED panel is larger, a longer period is required to charge up the capacitor to reach the desired voltage.
3. In phase 3, the OLED driver switches to use current source to drive the OLED pixels and this is the current drive stage. SSD1305 employs PWM (Pulse Width Modulation) method to control the brightness of area color A, B, C, D color individually. The longer the waveform in current drive stage is, the brighter is the pixel and vice versa.

Figure 8-11 : Segment Output Waveform in three phases

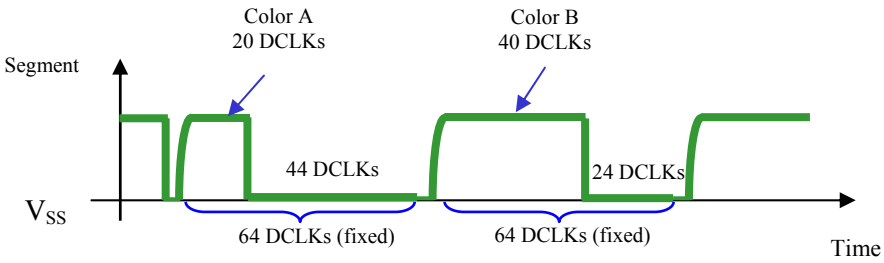


After finishing phase 3, the driver IC will go back to phase 1 to display the next row image data. This three-step cycle is run continuously to refresh image display on OLED panel.

The length of phase 3 for area colors: A,B,C and monochrome BANK0 can be configured by command 91h "Set Look Up Table". There are 64 steps available for each color but the one of color D is fixed at 64. The unit of the step is in DCLK.

For example, the look up table for area color A, B, is set to 20, 40 DCLKs respectively. Color B is set to be brighter than color A. Then the result segment output waveform of these two colors is shown below.

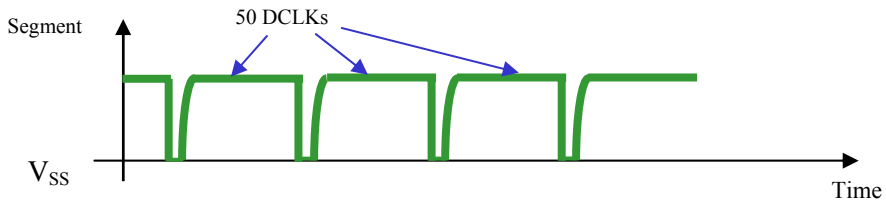
Figure 8-12 : Segment Output Waveform for two different colors LUT setting



In phase 3, the segment output waveforms under the monochrome mode and area color mode are different.

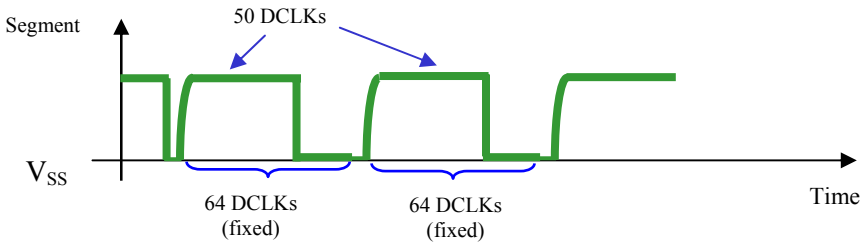
In monochrome mode, if the length of current drive pulse width is set to 50, after finishing 50 DCLKs in current drive phase, the driver IC will go back to phase 1 for next row display.

Figure 8-13 : Example of Segment Output Waveform of monochrome display section under monochrome mode



In area color mode, the phase 3 of both BANK0 and area color banks (BANK1 to BANK32) are fixed into 64 DCLKs. For instance, if the length of the pulse width is set to 50, then after the end of 50 DCLKs of current drive phase, the segment waveform will be gone to V_{SS} level and the driver is still in current drive phase. This phase will be end after 64 DCLKs from the start of the phase is passed. And then the drive goes back to phase 1 for next row display. Figure 8-14 shows the example of the segment output waveform of area color display section when the pulse width of area color is set to 50.

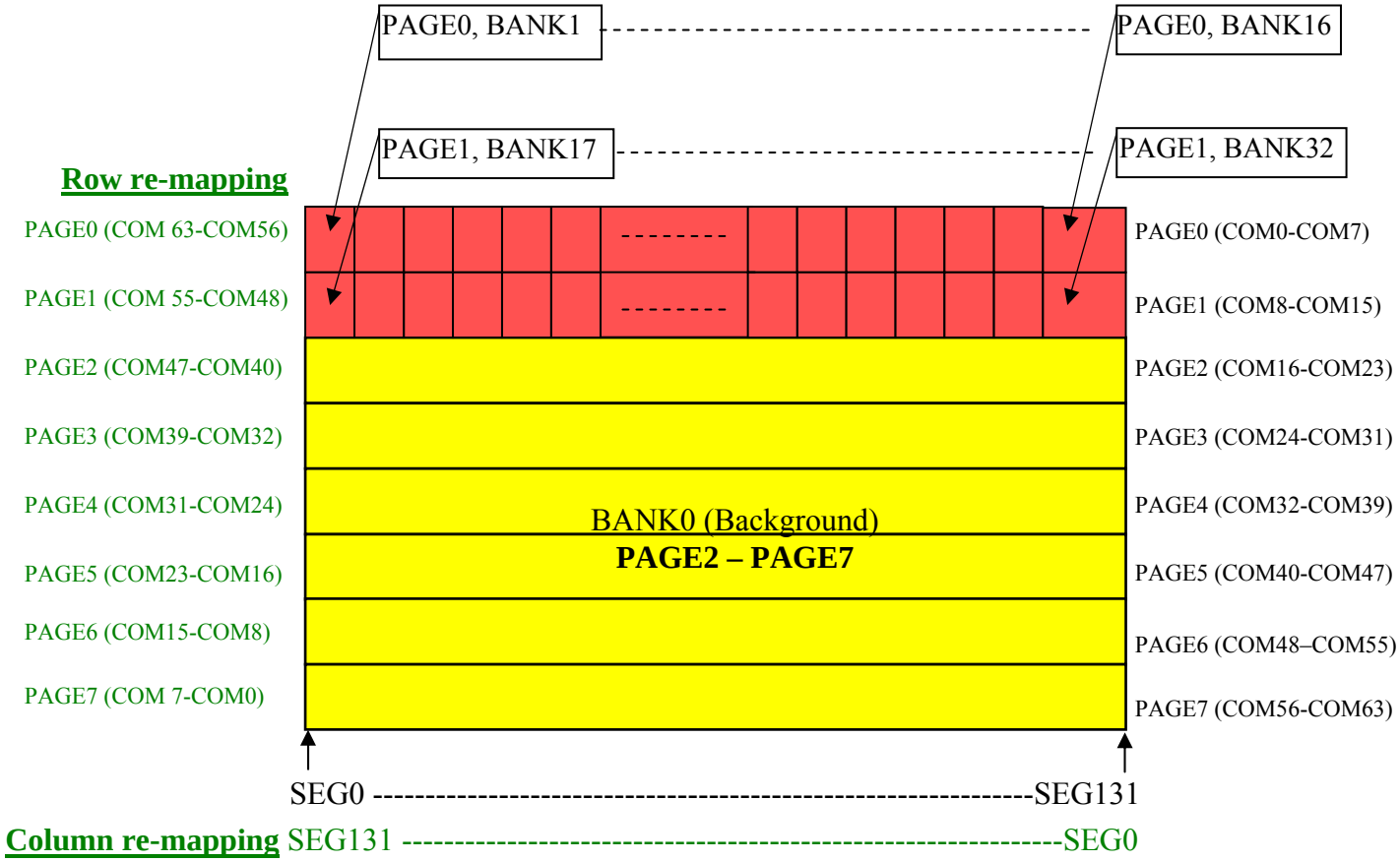
Figure 8-14 : Example of Segment Output Waveform of area color display section under area color mode



8.7 Graphic Display Data RAM (GDDRAM)

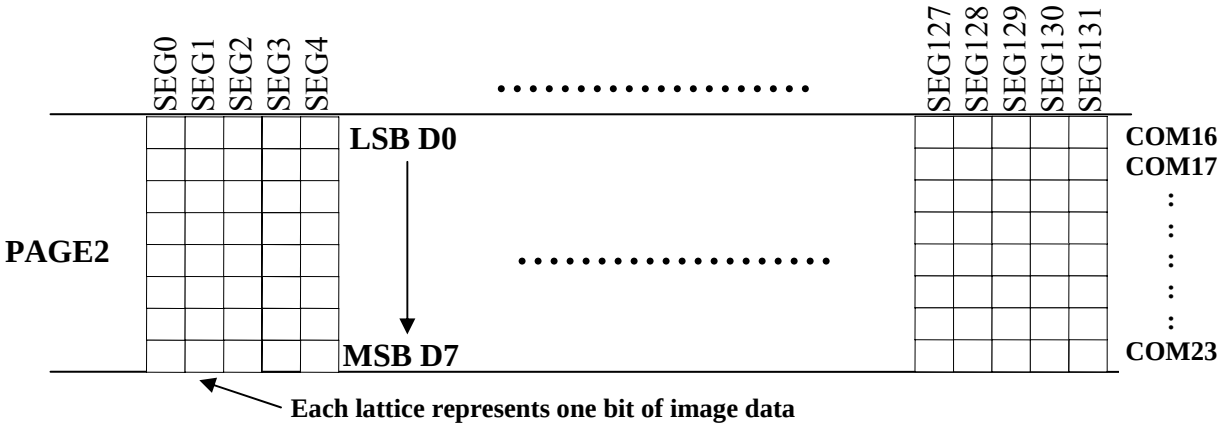
The GDDRAM is a bit mapped static RAM holding the bit pattern to be displayed. The size of the RAM is 132 x 64 bits and the RAM is divided into eight pages, from PAGE0 to PAGE7, as shown in Figure 8-15. In GDDRAM, PAGE0 and PAGE1 are belonged to area color section with resolution 132x16. PAGE2 to PAGE7 are used for monochrome 132x48 dot matrix display.

Figure 8-15 : GDDRAM pages structure of SSD1305



When one data byte is written into GDDRAM, all the rows image data of the same page of the current column are filled (i.e. the whole column (8 bits) pointed by the column address pointer is filled.). Data bit D0 is written into the top row, while data bit D7 is written into bottom row as shown in Figure 8-16.

Figure 8-16 : Enlargement of GDDRAM (No row re-mapping and column-remapping)

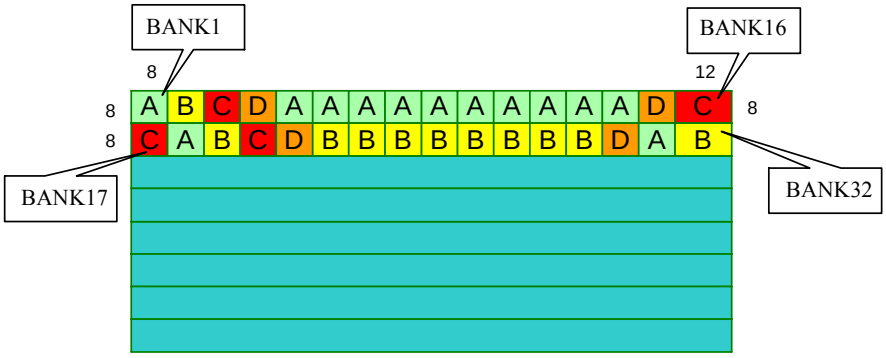


For mechanical flexibility, re-mapping on both Segment and Common outputs can be selected by software as shown in Figure 8-15.
For vertical shifting of the display, an internal register storing the display start line can be set to control the portion of the RAM data to be mapped to the display (command D3h).

8.8 Area Color Decoder

The 132x64 display matrix is divided into 8 pages. The first two pages, PAGE0 and PAGE1, are divided into 32 banks. BANK16 and BANK32 consist of a display area of 12x8 pixels. Other banks (BANK0 to BANK15 & BANK17 to BANK31) have matrices of 8x8 pixels. Each bank can be programmed to any one of the four colors (color A, B, C and D) as the example shown in Figure 8-17. Detailed operation can be referred to command 92h in Table 9-1.

Figure 8-17 : Example of area color assignment on a 132x64 OLED panel



8.9 SEG/COM Driving block

This block is used to derive the incoming power sources into the different levels of internal use voltage and current.

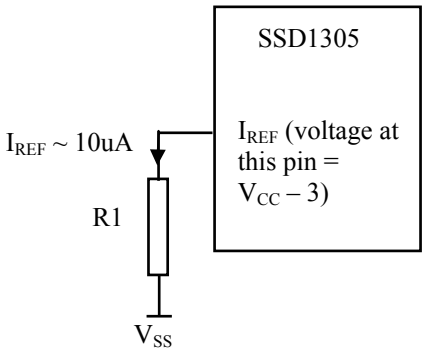
- V_{CC} is the most positive voltage supply.
- V_{COMH} is the Common deselected level. It is internally regulated.
- V_{LSS} is the ground path of the analog and panel current.
- I_{REF} is a reference current source for segment current drivers I_{SEG}. The relationship between reference current and segment current of a color is:

  I_{SEG} = Contrast / 256 x I_{REF} x scale factor

  in which
  the contrast (0~255) is set by Set Contrast command 81h; and
  the scale factor is 32 by default.

  The magnitude of I_{REF} is controlled by the value of resistor, which is connected between I_{REF} pin and Vss as shown in Figure 8-18. It is recommended to set I_{REF} to 10uA+/- 2uA so as to achieve I_{SEG} = 320uA at maximum contrast 255.

Figure 8-18 : I_{REF} Current Setting by Resistor Value



Since the voltage at I_{REF} pin is V_{CC} – 3V, the value of resistor R1 can be found as below.

R1 = (Voltage at I_{REF} – V_{SS}) / I_{REF} = (V_{CC} – 3) / 10uA ≈ 910kΩ for V_{CC} = 12V.

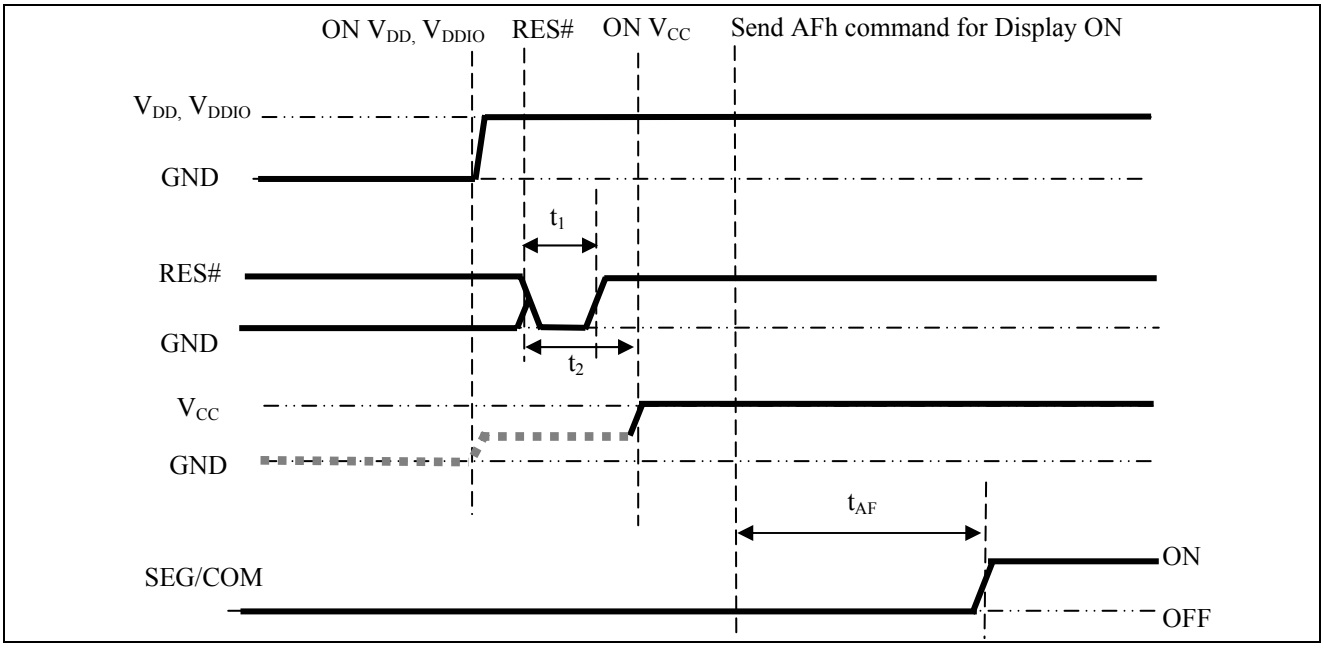
8.10 Power ON and OFF sequence

The following figures illustrate the recommended power ON and power OFF sequence of SSD1305 (assume V_{DD} and V_{DDIO} are at the same voltage level).

Power ON sequence:

1. Power ON $V_{DD,}$ $V_{DDIO.}$
2. After V_{DD}, V_{DDIO} become stable, set RES# pin LOW (logic low) for at least 3us (t_1) [4] and then HIGH (logic high).
3. After set RES# pin LOW (logic low), wait for at least 3us (t_2). Then Power ON $V_{CC.}$ [1]
4. After V_{CC} become stable, send command AFh for display ON. SEG/COM will be ON after 100ms (t_{AF}).

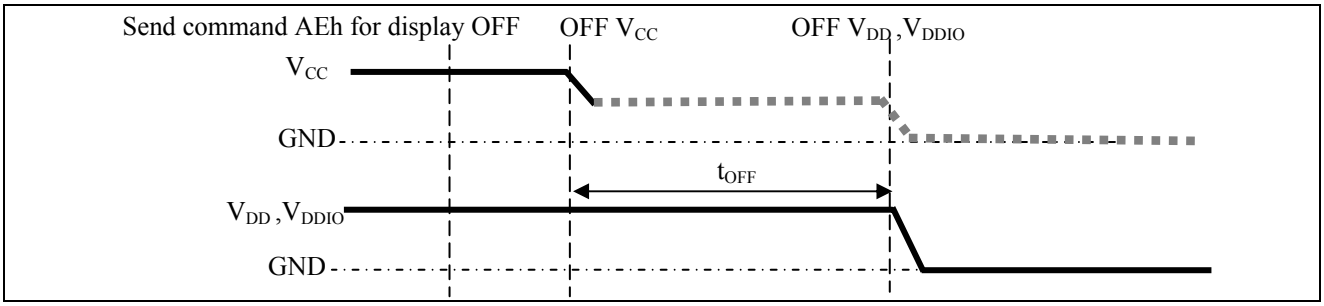
Figure 8-19 : The Power ON sequence



Power OFF sequence:

1. Send command AEh for display OFF.
2. Power OFF $V_{CC.}$ [1], [2], [3]
3. Wait for t_{OFF}. Power OFF $V_{DD,}$ $V_{DDIO.}$.(where Minimum t_{OFF}=0ms [5] , Typical t_{OFF}=100ms)

Figure 8-20 : The Power OFF sequence



Note:

[1] Since an ESD protection circuit is connected between V_{DD}, V_{DDIO} and V_{CC}, V_{CC} becomes lower than V_{DD} whenever V_{DD}, V_{DDIO} is ON and V_{CC} is OFF as shown in the dotted line of V_{CC} in Figure 8-19 and Figure 8-20.

[2] V_{CC} should be kept float (disable) when it is OFF.

[3] Power Pins (V_{DD} , V_{CC}) can never be pulled to ground under any circumstance.

[4] The register values are reset after t_1.

[5] V_{DD} should not be Power OFF before V_{CC} Power OFF.

9 COMMAND TABLE

Table 9-1: Command Table

(D/C#=0, R/W#(WR#) = 0, E(RD#=1) unless specific setting is stated)

Fundamental Command Table											
D/C#	**Hex**	**D7**	**D6**	**D5**	**D4**	**D3**	**D2**	**D1**	**D0**	**Command**	**Description**
0	00~0F	0	0	0	0	X_3	X_2	X_1	X_0	Set Lower Column Start Address for Page Addressing Mode	Set the lower nibble of the column start address register for Page Addressing Mode using X[3:0] as data bits. The initial display line register is reset to 0000b after RESET.
0	10~1F	0	0	0	1	X_3	X_2	X_1	X_0	Set Higher Column Start Address for Page Addressing Mode	Set the higher nibble of the column start address register for Page Addressing Mode using X[3:0] as data bits. The initial display line register is reset to 0000b after RESET.
0 0	20 A[1:0]	0 *	0 *	1 *	0 *	0 *	0 *	0 A_1	0 A_0	Set Memory Addressing Mode	A[1:0] = 00b, Horizontal Addressing Mode A[1:0] = 01b, Vertical Addressing Mode A[1:0] = 10b, Page Addressing Mode (RESET) A[1:0] = 11b, Invalid
0 0 0	21 A[7:0] B[7:0]	0 A_7 B_7	0 A_6 B_6	1 A_5 B_5	0 A_4 B_4	0 A_3 B_3	0 A_2 B_2	0 A_1 B_1	1 A_0 B_0	Set Column Address	Setup column start and end address A[7:0] : Column start address, range : 0-131d, (RESET=0d) B[7:0]: Column end address, range : 0-131d, (RESET =131d)
0 0 0	22 A[2:0] B[2:0]	0 * *	0 * *	1 * *	0 * *	0 * *	0 A_2 B_2	1 A_1 B_1	0 A_0 B_0	Set Page Address	Setup page start and end address A[2:0] : Page start Address, range : 0-7d, (RESET = 0d) B[2:0] : Page end Address, range : 0-7d, (RESET = 7d)
0	40~7F	0	1	X_5	X_4	X_3	X_2	X_1	X_0	Set Display Start Line	Set display RAM display start line register from 0-63 using $X_5X_3X_2X_1X_0$. Display start line register is reset to 000000b during RESET.
0 0	81 A[7:0]	1 A_7	0 A_6	0 A_5	0 A_4	0 A_3	0 A_2	0 A_1	1 A_0	Set Contrast Control For BANK0	Double byte command to select 1 out of 256 contrast steps. Contrast increases as the value increases. (RESET = 80h)
0 0	82 A[7:0]	1 A_7	0 A_6	0 A_5	0 A_4	0 A_3	0 A_2	1 A_1	0 A_0	Set Brightness For Area Color Banks	Double byte command to select 1 out of 256 brightness steps. Brightness increases as the value increases. (RESET = 80h)
0 0 0 0 0	91 X[5:0] A[5:0] B[5:0] C[5:0]	1 * * * *	0 * * * *	0 X_5 A_5 B_5 C_5	1 X_4 A_4 B_4 C_4	0 X_3 A_3 B_3 C_3	0 X_2 A_2 B_2 C_2	0 X_1 A_1 B_1 C_1	1 X_0 A_0 B_0 C_0	Set Look Up Table (LUT)	Set current drive pulse width of BANK0, Color A, B and C. BANK0: X[5:0] = 31… 63; for pulse width set to 32 ~ 64 clocks (RESET = 110001b) Color A: A[5:0] same as above (RESET = 111111b) Color B: B[5:0] same as above (RESET = 111111b) Color C: C[5:0] same as above (RESET = 111111b) **Note** (1) Color D pulse width is fixed at 64 clocks pulse.

Fundamental Command Table											
D/C#	**Hex**	**D7**	**D6**	**D5**	**D4**	**D3**	**D2**	**D1**	**D0**	**Command**	**Description**
0 0 0 0 0	92 A[7:0] B[7:0] C[7:0] D[7:0]	1 A_7 B_7 C_7 D_7	0 A_6 B_6 C_6 D_6	0 A_5 B_5 C_5 D_5	1 A_4 B_4 C_4 D_4	0 A_3 B_3 C_3 D_3	0 A_2 B_2 C_2 D_2	1 A_1 B_1 C_1 D_1	0 A_0 B_0 C_0 D_0	Set Bank Color of BANK1 to BANK16 (PAGE0)	Set the bank color of BANK1~BANK16 to any one of the 4 colors : A, B, C and D . A[1:0] : 00b, 01b, 10b, or 11b for Color = A, B, C or D of BANK1 A[3:2] : 00b, 01b, 10b, or 11b for Color = A, B, C or D of BANK2 : : D[5:4]: 00b, 01b, 10b, or 11b for Color = A, B, C or D of BANK15 D[7:6]: 00b, 01b, 10b, or 11b for Color = A, B, C or D of BANK16
0 0 0 0 0	93 A[7:0] B[7:0] C[7:0] D[7:0]	1 A_7 B_7 C_7 D_7	0 A_6 B_6 C_6 D_6	0 A_5 B_5 C_5 D_5	1 A_4 B_4 C_4 D_4	0 A_3 B_3 C_3 D_3	0 A_2 B_2 C_2 D_2	1 A_1 B_1 C_1 D_1	1 A_0 B_0 C_0 D_0	Set Bank Color of BANK17~BANK32 (PAGE1)	Set the bank color of BANK17~BANK32 to any one of the 4 colors: A, B, C and D. A[1:0] : 00b, 01b, 10b, or 11b for Color = A, B, C or D of BANK17 A[3:2] : 00b, 01b, 10b, or 1b1 for Color = A, B, C or D of BANK18 : : D[5:4]: 00b, 01b, 10b, or 11b for Color = A, B, C or D of BANK31 D[7:6]: 00b, 01b, 10b, or 11b for Color = A, B, C or D of BANK32
0	A0/A1	1	0	1	0	0	0	0	X_0	Set Segment Re-map	X[0]=0b: column address 0 is mapped to SEG0 (RESET) X[0]=1b: column address 131 is mapped to SEG0
0	A4/A5	1	0	1	0	0	1	0	X_0	Entire Display ON	X_0=0b: Resume to RAM content display (RESET) Output follows RAM content X_0=1b: Entire display ON Output ignores RAM content
0	A6/A7	1	0	1	0	0	1	1	X_0	Set Normal/Inverse Display	X[0]=0b: Normal display (RESET) 0 in RAM: OFF in display panel 1 in RAM: ON in display panel X[0]=1b: inverse display 0 in RAM: ON in display panel 1 in RAM: OFF in display panel
0 0	A8 A[5:0]	1 *	0 *	1 A_5	0 A_4	1 A_3	0 A_2	0 A_1	0 A_0	Set Multiplex Ratio	Set MUX ratio to N+1 MUX N=A[5:0] : from 16MUX to 64MUX, RESET= 111111b (i.e. 64MUX) A[5:0] from 0 to 14 are invalid entry.
0	AA	1	0	1	0	1	0	1	0	Reserved	Reserved
0 0 0 0	AB A[3:0] B[7:0] C[7:0]	1 * B_7 C_7	0 * B_6 C_6	1 * B_5 C_5	0 * B_4 C_4	1 A_3 B_3 C_3	0 A_2 B_2 C_2	1 A_1 B_1 C_1	1 A_0 B_0 C_0	Dim mode setting	A[3:0] : Reserved (set as 0000b) B [7:0] : Set contrast for BANK0, valid range 0-255d, please refer to command 81h C [7:0] : Set brightness for color bank, valid range 0-255d, please refer to command 82h

Fundamental Command Table											
D/C#	**Hex**	**D7**	**D6**	**D5**	**D4**	**D3**	**D2**	**D1**	**D0**	**Command**	**Description**
0 0	AD A[7:0]	1 1	0 0	1 0	0 0	1 1	1 1	0 1	1 A_0	Master Configuration	A[0]=0b, Select external V_{CC} supply (RESET) A[0]=1b, Reserved
0	AC AE AF	1	0	1	0	1	1	A_1	A_0	Set Display ON/OFF	ACh = Display ON in dim mode AEh = Display OFF (sleep mode) (RESET) AFh = Display ON in normal mode
0	B0~B7	1	0	1	1	0	X_2	X_1	X_0	Set Page Start Address for Page Addressing Mode	Set GDDRAM Page Start Address (PAGE0~PAGE7) for Page Addressing Mode using X[2:0].
0	C0/C8	1	1	0	0	X_3	0	0	0	Set COM Output Scan Direction	X[3]=0b: normal mode (RESET) Scan from COM0 to COM[N –1] X[3]=1b: remapped mode. Scan from COM[N~1] to COM0 Where N is the Multiplex ratio.
0 0	D3 A[5:0]	1 *	1 *	0 A_5	1 A_4	0 A_3	0 A_2	1 A_1	1 A_0	Set Display Offset	Set vertical shift by COM from 0~63. The value is reset to 00h after RESET.
0	D5 A[7:0]	1 A_7	1 A_6	0 A_5	1 A_4	0 A_3	1 A_2	0 A_1	1 A_0	Set Display Clock Divide Ratio/Oscillator Frequency	A[3:0] : Define the divide ratio (D) of the display clocks (DCLK): Divide ratio= A[3:0] + 1, RESET is 0000b (divide ratio = 1) A[7:4] : Set the Oscillator Frequency, F_{OSC}. Oscillator Frequency increases with the value of A[7:4] and vice versa. RESET is 0111b Range:0000b~1111b Frequency increases as setting value increases. Refer to section 10.1.23 for details.
0 0	D8	1 0	1 0	0 X_5	1 X_4	1 0	0 X_2	0 0	0 X_0	Set Area Color Mode ON/OFF & Low Power Display Mode	X[5:4]= 00b (RESET) : monochrome mode X[5:4]= 11b Area Color enable X[2]=0b and X[0]=0b: Normal power mode(RESET) X[2]=1b and X[0]=1b: Set low power display mode
0 0	D9 A[7:0]	1 A_7	1 A_6	0 A_5	1 A_4	1 A_3	0 A_2	0 A_1	1 A_0	Set Pre-charge Period	A[3:0] : Phase 1 period of up to 15 DCLK clocks (RESET=2h); 0 is invalid entry A[7:4] : Phase 2 period of up to 15 DCLK clocks (RESET=2h); 0 is invalid entry
0 0	DA	1 0	1 0	0 X_5	1 X_4	1 0	0 0	1 1	0 0	Set COM Pins Hardware Configuration	X[4]=0b, Sequential COM pin configuration X[4]=1b(RESET), Alternative COM pin configuration X[5]=0b(RESET), Disable COM Left/Right remap X[5]=1b, Enable COM Left/Right remap Please refer to Table 10-3 for details.

Fundamental Command Table

D/C#	Hex	D7	D6	D5	D4	D3	D2	D1	D0	Command	Description
0 0	DB A[5:2]	1 0	1 0	0 A_5	1 A_4	1 A_3	0 A_2	1 0	1 0	Set V_{COMH} Deselect Level	<table><tr><th>A[5:2]</th><th>Hex code</th><th>V_{COMH} deselect level</th></tr><tr><td>0000b</td><td>00h</td><td>~ 0.43 x V_{CC}</td></tr><tr><td>1101b</td><td>34h</td><td>~ 0.77 x V_{CC} (RESET)</td></tr><tr><td>1111b</td><td>3Ch</td><td>~ 0.83 x V_{CC}</td></tr></table>
0	E0	1	1	1	0	0	0	0	0	Enter Read Modify Write	Enter the Read Modify Write mode. Details please refer to section 10.1.28.
0	E3	1	1	1	0	0	0	1	1	NOP	Command for no operation
0	EE	1	1	1	0	1	1	1	0	Exit Read Modify Write	Exit the Read Modify Write mode (Please refer to command E0h)

Graphic Acceleration Command Table

D/C#	Hex	D7	D6	D5	D4	D3	D2	D1	D0	Command	Description
0	26/27	0	0	1	0	0	1	1	X_0	Horizontal Scroll Setup	X[0]=0, Right Horizontal Scroll X[0]=1, Left Horizontal Scroll A[2:0] : Set number of column scroll offset 000b No horizontal scroll 001b Horizontal scroll by 1 column 010b Horizontal scroll by 2 columns 011b Horizontal scroll by 3 columns 100b Horizontal scroll by 4 columns Other values are invalid. B[2:0] : Define start page address 000b – PAGE0 | 011b – PAGE3 | 110b – PAGE6 001b – PAGE1 | 100b – PAGE4 | 111b – PAGE7 010b – PAGE2 | 101b – PAGE5 C[2:0] : Set time interval between each scroll step in terms of frame frequency 000b – 6 frames | 100b – 3 frames 001b – 32 frames | 101b – 4 frames 010b – 64 frames | 110b – 2 frame 011b – 128 frames | 111b – Invalid D[2:0] : Define end page address 000b – PAGE0 | 011b – PAGE3 | 110b – PAGE6 001b – PAGE1 | 100b – PAGE4 | 111b – PAGE7 010b – PAGE2 | 101b – PAGE5 The value of D[2:0] must be larger or equal to B[2:0]
0	A[2:0]	*	*	*	*	*	A_2	A_1	A_0		
0	B[2:0]	*	*	*	*	*	B_2	B_1	B_0		
0	C[2:0]	*	*	*	*	*	C_2	C_1	C_0		
0	D[2:0]	*	*	*	*	*	D_2	D_1	D_0		
0	29/2A	0	0	1	0	1	0	X_1	X_0	Continuous Vertical and Horizontal Scroll Setup	X_1X_0=01b : Vertical and Right Horizontal Scroll X_1X_0=10b : Vertical and Left Horizontal Scroll A[2:0] : Set number of column scroll offset 000b No horizontal scroll 001b Horizontal scroll by 1 column 010b Horizontal scroll by 2 columns 011b Horizontal scroll by 3 columns 100b Horizontal scroll by 4 columns Other values are invalid. B[2:0] : Define start page address 000b – PAGE0 | 011b – PAGE3 | 110b – PAGE6 001b – PAGE1 | 100b – PAGE4 | 111b – PAGE7 010b – PAGE2 | 101b – PAGE5 C[2:0] : Set time interval between each scroll step in terms of frame frequency 000b – 6 frames | 100b – 3 frames 001b – 32 frames | 101b – 4 frames 010b – 64 frames | 110b – 2 frame 011b – 128 frames | 111b – Invalid D[2:0] : Define end page address 000b – PAGE0 | 011b – PAGE3 | 110b – PAGE6 001b – PAGE1 | 100b – PAGE4 | 111b – PAGE7 010b – PAGE2 | 101b – PAGE5 The value of D[2:0] must be larger or equal to B[2:0] E[5:0] : Vertical scrolling offset e.g. E[5:0]= 01h refer to offset =1 row E[5:0] =3Fh refer to offset =63 rows
0	A[2:0]	*	*	*	*	*	A_2	A_1	A_0		
0	B[2:0]	*	*	*	*	*	B_2	B_1	B_0		
0	C[2:0]	*	*	*	*	*	C_2	C_1	C_0		
0	D[2:0]	*	*	*	*	*	D_2	D_1	D_0		
0	E[5:0]	*	*	E_5	E_4	E_3	E_2	E_1	E_0		

Graphic Acceleration Command Table											
D/C#	**Hex**	**D7**	**D6**	**D5**	**D4**	**D3**	**D2**	**D1**	**D0**	**Command**	**Description**
0	2E	0	0	1	0	1	1	1	0	Deactivate scroll	Stop scrolling that is configured by command 26h/27h/29h/2Ah. **Note** (1) After sending 2Eh command to deactivate the scrolling action, the ram data needs to be rewritten.
0	2F	0	0	1	0	1	1	1	1	Activate scroll	Start scrolling that is configured by the scrolling setup commands :26h/27h/29h/2Ah with the following valid sequences: Valid command sequence 1: 26h ;2Fh. Valid command sequence 2: 27h ;2Fh. Valid command sequence 3: 29h ;2Fh. Valid command sequence 4: 2Ah ;2Fh. For example, if "26h; 2Ah; 2Fh." commands are issued, the setting in the last scrolling setup command, i.e. 2Ah in this case, will be executed. In other words, setting in the last scrolling setup command overwrites the setting in the previous scrolling setup commands.
0 0 0	A3 A[5:0] B[6:0]	1 * *	0 * B_6	1 A_5 B_5	0 A_4 B_4	0 A_3 B_3	0 A_2 B_2	1 A_1 B_1	1 A_0 B_0	Set Vertical Scroll Area	A[5:0] : Set No. of rows in top fixed area. The No. of rows in top fixed area is referenced to the top of the GDDRAM (i.e. row 0).[RESET = 0] B[6:0] : Set No. of rows in scroll area. This is the number of rows to be used for vertical scrolling. The scroll area starts in the first row below the top fixed area. [RESET = 64] **Note** (1) A[5:0]+B[6:0] <= MUX ratio (2) B[6:0] <= MUX ratio (3a) Vertical scrolling offset (E[5:0] in 29h/2Ah) < B[6:0] (3b) Set Display Start Line (X5X4X3X2X1X0 of 40h~7Fh) < B[6:0] (4) The last row of the scroll area shifts to the first row of the scroll area. (5) For 64d MUX display A[5:0] = 0, B[6:0]=64 : whole area scrolls A[5:0]= 0, B[6:0] < 64 : top area scrolls A[5:0] + B[6:0] < 64 : central area scrolls A[5:0] + B[6:0] = 64 : bottom area scrolls Please refer to Figure 10-14 for details.

Note
(1) "*" stands for "Don't care".

Table 9-2 : Read Command Table

Bit Pattern	Command	Description
$D_7D_6D_5D_4D_3D_2D_1D_0$	Status Register Read	D[7] : Reserve D[6] : "1" for display OFF / "0" for display ON D[5] : Reserve D[4] : Reserve D[3] : Reserve D[2] : Reserve D[1] : Reserve D[0] : Reserve

Note
(1) Patterns other than those given in the Command Table are prohibited to enter the chip as a command; as unexpected results can occur.

9.1 Data Read / Write

To read data from the GDDRAM, select HIGH for both the R/W# (WR#) pin and the D/C# pin for 6800-series parallel mode and select LOW for the E (RD#) pin and HIGH for the D/C# pin for 8080-series parallel mode. No data read is provided in serial mode operation.
In normal data read mode the GDDRAM column address pointer will be increased automatically by one after each data read.
Also, a dummy read is required before the first data read.
To write data to the GDDRAM, select LOW for the R/W# (WR#) pin and HIGH for the D/C# pin for both 6800-series parallel mode and 8080-series parallel mode. The serial interface mode is always in write mode. The GDDRAM column address pointer will be increased automatically by one after each data write.

Table 9-3 : Address increment table (Automatic)

D/C#	R/W# (WR#)	Comment	Address Increment
0	0	Write Command	No
0	1	Read Status	No
1	0	Write Data	Yes
1	1	Read Data	Yes (1)

Note
(1) If read-data command is issued in read-modify-write mode no address increase occurs.

10 COMMAND DESCRIPTIONS

10.1 Fundamental Command

10.1.1 Set Lower Column Start Address for Page Addressing Mode (00h~0Fh)

This command specifies the lower nibble of the 8-bit column start address for the display data RAM under Page Addressing Mode. The column address will be incremented by each data access. Please refer to Section Table 9-1 and Section 10.1.3 for details.

10.1.2 Set Higher Column Start Address for Page Addressing Mode (10h~1Fh)

This command specifies the higher nibble of the 8-bit column start address for the display data RAM under Page Addressing Mode. The column address will be incremented by each data access. Please refer to Section Table 9-1 and Section 10.1.3 for details.

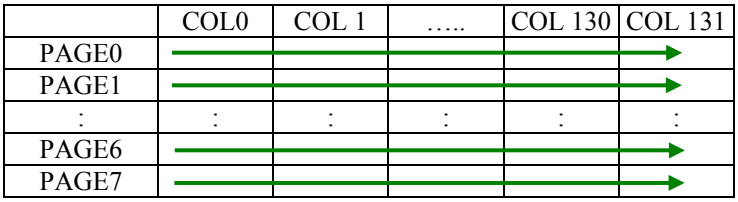
10.1.3 Set Memory Addressing Mode (20h)

There are 3 different memory addressing mode in SSD1305: page addressing mode, horizontal addressing mode and vertical addressing mode. This command sets the way of memory addressing into one of the above three modes. In there, "COL" means the graphic display data RAM column.

Page addressing mode (A[1:0]=10xb)

In page addressing mode, after the display RAM is read/written, the column address pointer is increased automatically by 1. If the column address pointer reaches column end address, the column address pointer is reset to column start address and page address pointer is not changed. Users have to set the new page and column addresses in order to access the next page RAM content The sequence of movement of the PAGE and column address point for page addressing mode is shown in Figure 10-1.

Figure 10-1 : Address Pointer Movement of Page addressing mode

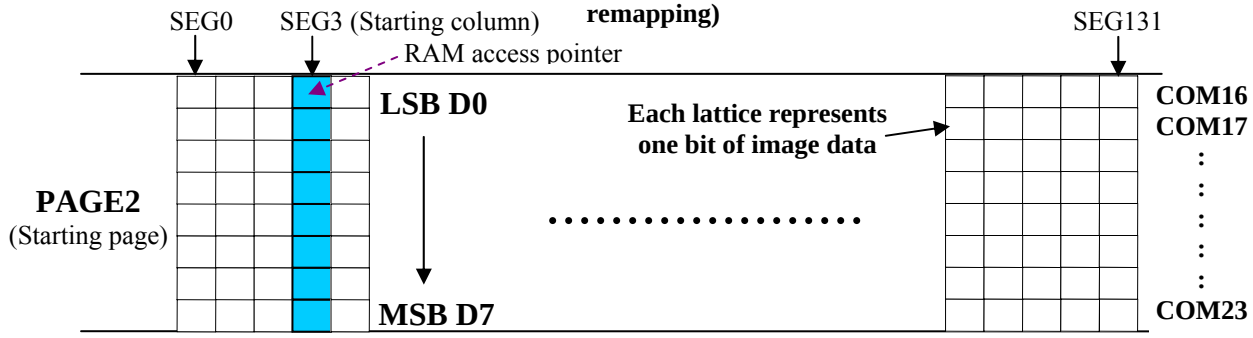


In normal display data RAM read or write and page addressing mode, the following steps are required to define the starting RAM access pointer location:

- Set the page start address of the target display location by command B0h to B7h.
- Set the lower start column address of pointer by command 00h~0Fh.
- Set the upper start column address of pointer by command 10h~1Fh.

For example, if the page address is set to B2h, lower column address is 03h and upper column address is 10h, then that means the starting column is SEG3 of PAGE2. The RAM access pointer is located as shown in Figure 10-2. The input data byte will be written into RAM position of column 3.

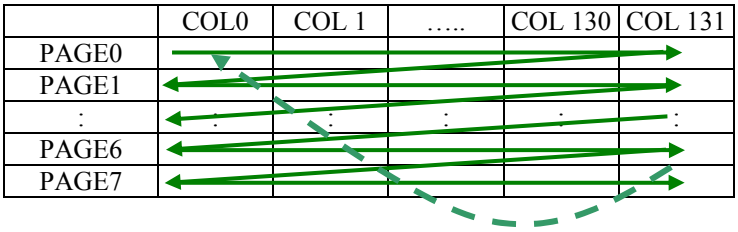
Figure 10-2 : Example of GDDRAM access pointer setting in Page Addressing Mode (No row and column-remapping)



Horizontal addressing mode (A[1:0]=00b)

In horizontal addressing mode, after the display RAM is read/written, the column address pointer is increased automatically by 1. If the column address pointer reaches column end address, the column address pointer is reset to column start address and page address pointer is increased by 1. The sequence of movement of the page and column address point for horizontal addressing mode is shown in Figure 10-3. When both column and page address pointers reach the end address, the pointers are reset to column start address and page start address (Dotted line in Figure 10-3.)

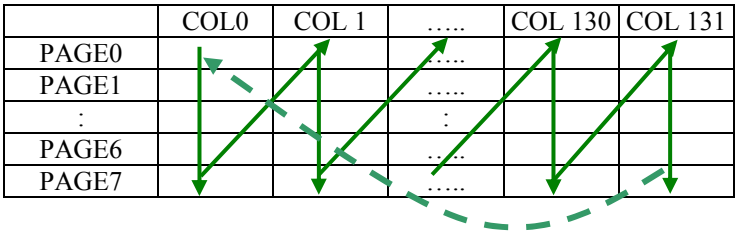
Figure 10-3 : Address Pointer Movement of Horizontal addressing mode



Vertical addressing mode: (A[1:0]=01b)

In vertical addressing mode, after the display RAM is read/written, the page address pointer is increased automatically by 1. If the page address pointer reaches the page end address, the page address pointer is reset to page start address and column address pointer is increased by 1. The sequence of movement of the page and column address point for vertical addressing mode is shown in Figure 10-4. When both column and page address pointers reach the end address, the pointers are reset to column start address and page start address (Dotted line in Figure 10-4.)

Figure 10-4 : Address Pointer Movement of Vertical addressing mode



In normal display data RAM read or write and horizontal / vertical addressing mode, the following steps are required to define the RAM access pointer location:

- Set the column start and end address of the target display location by command 21h.
- Set the page start and end address of the target display location by command 22h.

Example is shown in Figure 10-5.

10.1.4 Set Column Address (21h)

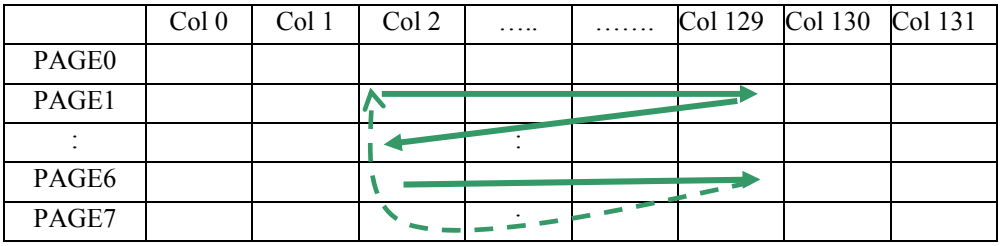
This triple byte command specifies column start address and end address of the display data RAM. This command also sets the column address pointer to column start address. This pointer is used to define the current read/write column address in graphic display data RAM. If horizontal address increment mode is enabled by command 20h, after finishing read/write one column data, it is incremented automatically to the next column address. Whenever the column address pointer finishes accessing the end column address, it is reset back to start column address and the row address is incremented to the next row.

10.1.5 Set Page Address (22h)

This triple byte command specifies page start address and end address of the display data RAM. This command also sets the page address pointer to page start address. This pointer is used to define the current read/write page address in graphic display data RAM. If vertical address increment mode is enabled by command 20h, after finishing read/write one page data, it is incremented automatically to the next page address. Whenever the page address pointer finishes accessing the end page address, it is reset back to start page address.

The figure below shows the way of column and page address pointer movement through the example: column start address is set to 2 and column end address is set to 129, page start address is set to 1 and page end address is set to 6; Horizontal address increment mode is enabled by command 20h. In this case, the graphic display data RAM column accessible range is from column 2 to column 129 and from page 1 to page 6 only. In addition, the column address pointer is set to 2 and page address pointer is set to 1. After finishing read/write one pixel of data, the column address is increased automatically by 1 to access the next RAM location for next read/write operation (*solid line in Figure 10-5*). Whenever the column address pointer finishes accessing the end column 129, it is reset back to column 2 and page address is automatically increased by 1 (*solid line in Figure 10-5*). While the end page 6 and end column 129 RAM location is accessed, the page address is reset back to 1 and the column address is reset back to 2 (*dotted line in Figure 10-5*). .

Figure 10-5 : Example of Column and Row Address Pointer Movement



10.1.6 Set Display Start Line (40h~7Fh)

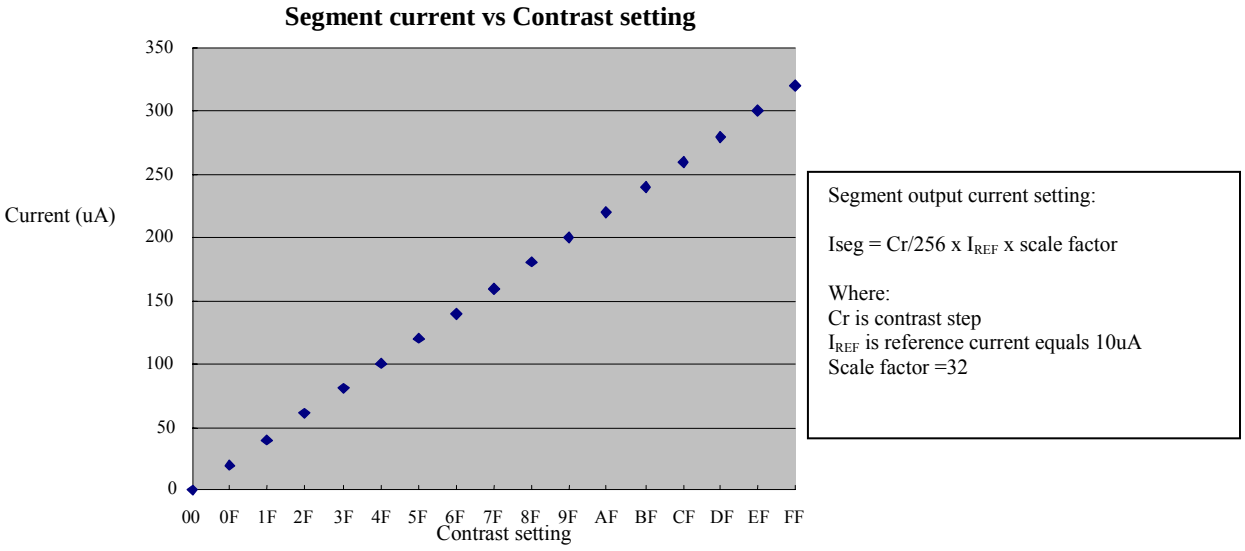
This command sets the Display Start Line register to determine starting address of display RAM, by selecting a value from 0 to 63. With value equal to 0, RAM row 0 is mapped to COM0. With value equal to 1, RAM row 1 is mapped to COM0 and so on.

Refer to Table 10-1 for more illustrations.

10.1.7 Set Contrast Control for BANK0 (81h)

This command sets the Contrast Setting of the display. The chip has 256 contrast steps from 00h to FFh. The segment output current increases as the contrast step value increases. See Figure 10-6 below.

Figure 10-6 : Segment current vs Contrast setting



10.1.8 Set Brightness for Area Color Banks (82h)

This command sets the Brightness Setting of the display for the area color banks. The chip has 256 brightness steps from 00h to FFh. The segment output current increases as the brightness step value increases.

This setting does not affect the contrast of BANK0, which is set by command 81h.

10.1.9 Set Look Up Table (LUT) (91h)

The SSD1305 provides 4 color settings - Colors A, B, C and D for the bank color of BANK1 to BANK32 under the area color mode. The color intensity (or grey scale) is defined by the current drive pulse width. This pulse width setting must be stored in the Look Up Table (LUT). The pulse width of colors A, B, C is programmable from 32 to 64 DCLKs. The color D is fixed at 64 DCLKs pulse width. For the grey scale in BANK0, the pulse width is programmable from 32 to 64 DCLKs. Please refer to 91h command in Table 9-1 for details of the LUT setting.

After setting the pulse widths for the color of A, B, C, D and BANK0, the next step is to define the color of each display area. Each bank can be programmable to any one of the 4 colors (A, B, C and D). The user can use 92h and 93h commands for the bank color setting. It should be notice that this is only applicable in area color mode.

10.1.10 Set Bank Color of BANK1 to BANK16 (PAGE0) (92h)

This command maps the bank color (pulse width) of BANK1~BANK16 to any one of the 4 colors: A, B, C and D. For details of the setting, please refer to 92h command in Table 9-1.

10.1.11 Set Bank Color of BANK17 to BANK32 (PAGE0) (93h)

This command maps the bank color (pulse width) of BANK17~BANK32 to any one of the 4 colors: A, B, C and D. For details of the setting, please refer to 93h command in Table 9-1.

10.1.12 Set Segment Re-map (A0h/A1h)

This command changes the mapping between the display data column address and the segment driver. It allows flexibility in OLED module design. Please refer to Table 9-1.

This command only affects subsequent data input. Data already stored in GDDRAM will have no changes.

10.1.13 Entire Display ON (A4h/A5h)

A4h command enable display outputs according to the GDDRAM contents.
If A5h command is issued, then by using A4h command, the display will resume to the GDDRAM contents. In other words, A4h command resumes the display from entire display "ON" stage.

A5h command forces the entire display to be "ON", regardless of the contents of the display data RAM.

10.1.14 Set Normal/Inverse Display (A6h/A7h)

This command sets the display to be either normal or inverse. In normal display a RAM data of 1 indicates an "ON" pixel while in inverse display a RAM data of 0 indicates an "ON" pixel.

10.1.15 Set Multiplex Ratio (A8h)

This command switches the default 63 multiplex mode to any multiplex ratio, ranging from 16 to 63. The output pads COM0~COM63 will be switched to the corresponding COM signal.

10.1.16 Reserved (AAh)

This command is reserved.

10.1.17 Dim Mode setting (ABh)

This command contains multiple bits to configure the contrast and brightness of color bank for the display in dim mode. The brightness setting of color bank can be set different to normal mode (AFh). The display can be set in dim mode through command ACh.

10.1.18 Master Configuration (ADh)

This command selects the external V_{CC} power supply by default. As external V_{CC} power supply is selected, external V_{CC} power should be connected to the V_{CC} pin.

10.1.19 Set Display ON/OFF (ACh/AEh/AFh)

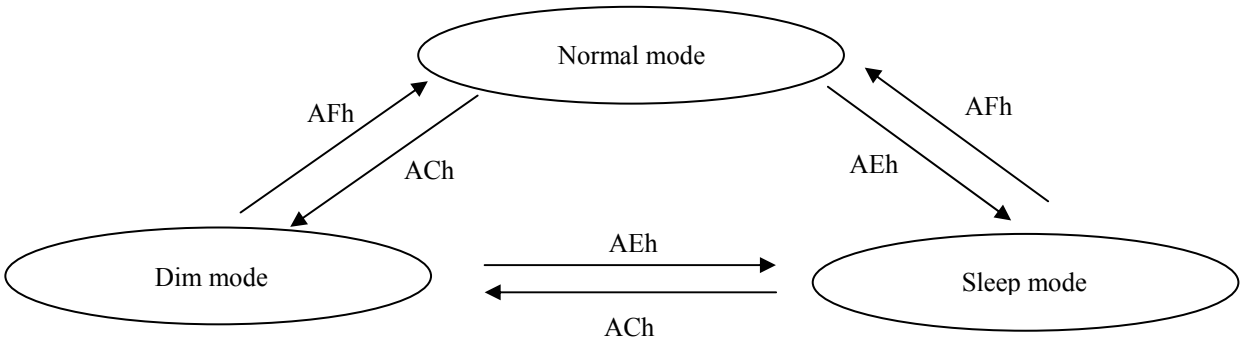
These single byte commands are used to turn the OLED panel display ON or OFF.
When the display is ON, the selected circuits by Set Master Configuration command will be turned ON.
When the display is OFF, those circuits will be turned OFF and the segment and common output are in high impedance state.

These commands set the display to one of the three states:

- ACh : Dim Mode Display ON
- AEh : Display OFF
- AFh : Normal Brightness Display ON

where the dim mode settings are controlled by command ABh.

Figure 10-7 :Transition between different modes



10.1.20 Set Page Start Address for Page Addressing Mode (B0h~B7h)

This command positions the page start address from 0 to 7 in GDDRAM under Page Addressing Mode. Please refer to Table 9-1 and Section 10.1.3 for details.

10.1.21 Set COM Output Scan Direction (C0h/C8h)

This command sets the scan direction of the COM output, allowing layout flexibility in the OLED module design. Additionally, the display will show once this command is issued. For example, if this command is sent during normal display then the graphic display will be vertically flipped immediately. Please refer to Table 10-3 for details.

10.1.22 Set Display Offset (D3h)

This is a double byte command. The second command specifies the mapping of the display start line to one of COM0~COM63 (assuming that COM0 is the display start line then the display start line register is equal to 0). For example, to move the COM16 towards the COM0 direction by 16 lines the 6-bit data in the second byte should be given as 010000b. To move in the opposite direction by 16 lines the 6-bit data should be given by 64 – 16, so the second byte would be 100000b.

The following two tables (Table 10-1, Table 10-2) show the example of setting the command C0h/C8h and D3h.

Table 10-1 : Example of Set Display Offset and Display Start Line with no Remap

	Output												
	64		64		64		56		56		56		Set MUX ratio(A8h)
	Normal		Normal		Normal		Normal		Normal		Normal		COM Normal / Remapped (C0h / C8h)
Hardware	0		8		0		0		8		0		Display offset (D3h)
pin name	0		0		8		0		0		8		Display start line (40h - 7Fh)
COM0	Row0	RAM0	Row8	RAM8	Row0	RAM8	Row0	RAM0	Row8	RAM8	Row0	RAM8	
COM1	Row1	RAM1	Row9	RAM9	Row1	RAM9	Row1	RAM1	Row9	RAM9	Row1	RAM9	
COM2	Row2	RAM2	Row10	RAM10	Row2	RAM10	Row2	RAM2	Row10	RAM10	Row2	RAM10	
COM3	Row3	RAM3	Row11	RAM11	Row3	RAM11	Row3	RAM3	Row11	RAM11	Row3	RAM11	
COM4	Row4	RAM4	Row12	RAM12	Row4	RAM12	Row4	RAM4	Row12	RAM12	Row4	RAM12	
COM5	Row5	RAM5	Row13	RAM13	Row5	RAM13	Row5	RAM5	Row13	RAM13	Row5	RAM13	
COM6	Row6	RAM6	Row14	RAM14	Row6	RAM14	Row6	RAM6	Row14	RAM14	Row6	RAM14	
COM7	Row7	RAM7	Row15	RAM15	Row7	RAM15	Row7	RAM7	Row15	RAM15	Row7	RAM15	
COM8	Row8	RAM8	Row16	RAM16	Row8	RAM16	Row8	RAM8	Row16	RAM16	Row8	RAM16	
COM9	Row9	RAM9	Row17	RAM17	Row9	RAM17	Row9	RAM9	Row17	RAM17	Row9	RAM17	
COM10	Row10	RAM10	Row18	RAM18	Row10	RAM18	Row10	RAM10	Row18	RAM18	Row10	RAM18	
COM11	Row11	RAM11	Row19	RAM19	Row11	RAM19	Row11	RAM11	Row19	RAM19	Row11	RAM19	
COM12	Row12	RAM12	Row20	RAM20	Row12	RAM20	Row12	RAM12	Row20	RAM20	Row12	RAM20	
COM13	Row13	RAM13	Row21	RAM21	Row13	RAM21	Row13	RAM13	Row21	RAM21	Row13	RAM21	
COM14	Row14	RAM14	Row22	RAM22	Row14	RAM22	Row14	RAM14	Row22	RAM22	Row14	RAM22	
COM15	Row15	RAM15	Row23	RAM23	Row15	RAM23	Row15	RAM15	Row23	RAM23	Row15	RAM23	
COM16	Row16	RAM16	Row24	RAM24	Row16	RAM24	Row16	RAM16	Row24	RAM24	Row16	RAM24	
COM17	Row17	RAM17	Row25	RAM25	Row17	RAM25	Row17	RAM17	Row25	RAM25	Row17	RAM25	
COM18	Row18	RAM18	Row26	RAM26	Row18	RAM26	Row18	RAM18	Row26	RAM26	Row18	RAM26	
COM19	Row19	RAM19	Row27	RAM27	Row19	RAM27	Row19	RAM19	Row27	RAM27	Row19	RAM27	
COM20	Row20	RAM20	Row28	RAM28	Row20	RAM28	Row20	RAM20	Row28	RAM28	Row20	RAM28	
COM21	Row21	RAM21	Row29	RAM29	Row21	RAM29	Row21	RAM21	Row29	RAM29	Row21	RAM29	
COM22	Row22	RAM22	Row30	RAM30	Row22	RAM30	Row22	RAM22	Row30	RAM30	Row22	RAM30	
COM23	Row23	RAM23	Row31	RAM31	Row23	RAM31	Row23	RAM23	Row31	RAM31	Row23	RAM31	
COM24	Row24	RAM24	Row32	RAM32	Row24	RAM32	Row24	RAM24	Row32	RAM32	Row24	RAM32	
COM25	Row25	RAM25	Row33	RAM33	Row25	RAM33	Row25	RAM25	Row33	RAM33	Row25	RAM33	
COM26	Row26	RAM26	Row34	RAM34	Row26	RAM34	Row26	RAM26	Row34	RAM34	Row26	RAM34	
COM27	Row27	RAM27	Row35	RAM35	Row27	RAM35	Row27	RAM27	Row35	RAM35	Row27	RAM35	
COM28	Row28	RAM28	Row36	RAM36	Row28	RAM36	Row28	RAM28	Row36	RAM36	Row28	RAM36	
COM29	Row29	RAM29	Row37	RAM37	Row29	RAM37	Row29	RAM29	Row37	RAM37	Row29	RAM37	
COM30	Row30	RAM30	Row38	RAM38	Row30	RAM38	Row30	RAM30	Row38	RAM38	Row30	RAM38	
COM31	Row31	RAM31	Row39	RAM39	Row31	RAM39	Row31	RAM31	Row39	RAM39	Row31	RAM39	
COM32	Row32	RAM32	Row40	RAM40	Row32	RAM40	Row32	RAM32	Row40	RAM40	Row32	RAM40	
COM33	Row33	RAM33	Row41	RAM41	Row33	RAM41	Row33	RAM33	Row41	RAM41	Row33	RAM41	
COM34	Row34	RAM34	Row42	RAM42	Row34	RAM42	Row34	RAM34	Row42	RAM42	Row34	RAM42	
COM35	Row35	RAM35	Row43	RAM43	Row35	RAM43	Row35	RAM35	Row43	RAM43	Row35	RAM43	
COM36	Row36	RAM36	Row44	RAM44	Row36	RAM44	Row36	RAM36	Row44	RAM44	Row36	RAM44	
COM37	Row37	RAM37	Row45	RAM45	Row37	RAM45	Row37	RAM37	Row45	RAM45	Row37	RAM45	
COM38	Row38	RAM38	Row46	RAM46	Row38	RAM46	Row38	RAM38	Row46	RAM46	Row38	RAM46	
COM39	Row39	RAM39	Row47	RAM47	Row39	RAM47	Row39	RAM39	Row47	RAM47	Row39	RAM47	
COM40	Row40	RAM40	Row48	RAM48	Row40	RAM48	Row40	RAM40	Row48	RAM48	Row40	RAM48	
COM41	Row41	RAM41	Row49	RAM49	Row41	RAM49	Row41	RAM41	Row49	RAM49	Row41	RAM49	
COM42	Row42	RAM42	Row50	RAM50	Row42	RAM50	Row42	RAM42	Row50	RAM50	Row42	RAM50	
COM43	Row43	RAM43	Row51	RAM51	Row43	RAM51	Row43	RAM43	Row51	RAM51	Row43	RAM51	
COM44	Row44	RAM44	Row52	RAM52	Row44	RAM52	Row44	RAM44	Row52	RAM52	Row44	RAM52	
COM45	Row45	RAM45	Row53	RAM53	Row45	RAM53	Row45	RAM45	Row53	RAM53	Row45	RAM53	
COM46	Row46	RAM46	Row54	RAM54	Row46	RAM54	Row46	RAM46	Row54	RAM54	Row46	RAM54	
COM47	Row47	RAM47	Row55	RAM55	Row47	RAM55	Row47	RAM47	Row55	RAM55	Row47	RAM55	
COM48	Row48	RAM48	Row56	RAM56	Row48	RAM56	Row48	RAM48	-	-	Row48	RAM56	
COM49	Row49	RAM49	Row57	RAM57	Row49	RAM57	Row49	RAM49	-	-	Row49	RAM57	
COM50	Row50	RAM50	Row58	RAM58	Row50	RAM58	Row50	RAM50	-	-	Row50	RAM58	
COM51	Row51	RAM51	Row59	RAM59	Row51	RAM59	Row51	RAM51	-	-	Row51	RAM59	
COM52	Row52	RAM52	Row60	RAM60	Row52	RAM60	Row52	RAM52	-	-	Row52	RAM60	
COM53	Row53	RAM53	Row61	RAM61	Row53	RAM61	Row53	RAM53	-	-	Row53	RAM61	
COM54	Row54	RAM54	Row62	RAM62	Row54	RAM62	Row54	RAM54	-	-	Row54	RAM62	
COM55	Row55	RAM55	Row63	RAM63	Row55	RAM63	Row55	RAM55	-	-	Row55	RAM63	
COM56	Row56	RAM56	Row0	RAM0	Row56	RAM0	-	-	Row0	RAM0	-	-	
COM57	Row57	RAM57	Row1	RAM1	Row57	RAM1	-	-	Row1	RAM1	-	-	
COM58	Row58	RAM58	Row2	RAM2	Row58	RAM2	-	-	Row2	RAM2	-	-	
COM59	Row59	RAM59	Row3	RAM3	Row59	RAM3	-	-	Row3	RAM3	-	-	
COM60	Row60	RAM60	Row4	RAM4	Row60	RAM4	-	-	Row4	RAM4	-	-	
COM61	Row61	RAM61	Row5	RAM5	Row61	RAM5	-	-	Row5	RAM5	-	-	
COM62	Row62	RAM62	Row6	RAM6	Row62	RAM6	-	-	Row6	RAM6	-	-	
COM63	Row63	RAM63	Row7	RAM7	Row63	RAM7	-	-	Row7	RAM7	-	-	
Display examples	(a)		(b)		(c)		(d)		(e)		(f)		

(a)

(b)

(c)

(d)

(e)

(f)

(RAM)

Table 10-2 :Example of Set Display Offset and Display Start Line with Remap

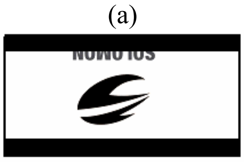
Hardware pin name	Output														
	64		64		64		48		48		48		48		Set MUX ratio(A8h)
	Remap		Remap		Remap		Remap		Remap		Remap		Remap		COM Normal / Remapped (C0h / C8h)
	0		8		0		0		8		0		8		Display offset (D3h)
	0		0		8		0		0		8		16		Display start line (40h - 7Fh)
COM0	Row 63	RAM63	Row 7	RAM7	Row 63	RAM7	Row 47	RAM47	-	-	Row 47	RAM55	-	-	
COM1	Row 62	RAM62	Row 6	RAM6	Row 62	RAM6	Row 46	RAM46	-	-	Row 46	RAM54	-	-	
COM2	Row 61	RAM61	Row 5	RAM5	Row 61	RAM5	Row 45	RAM45	-	-	Row 45	RAM53	-	-	
COM3	Row 60	RAM60	Row 4	RAM4	Row 60	RAM4	Row 44	RAM44	-	-	Row 44	RAM52	-	-	
COM4	Row 59	RAM59	Row 3	RAM3	Row 59	RAM3	Row 43	RAM43	-	-	Row 43	RAM51	-	-	
COM5	Row 58	RAM58	Row 2	RAM2	Row 58	RAM2	Row 42	RAM42	-	-	Row 42	RAM50	-	-	
COM6	Row 57	RAM57	Row 1	RAM1	Row 57	RAM1	Row 41	RAM41	-	-	Row 41	RAM49	-	-	
COM7	Row 56	RAM56	Row 0	RAM0	Row 56	RAM0	Row 40	RAM40	-	-	Row 40	RAM48	-	-	
COM8	Row 55	RAM55	Row 63	RAM63	Row 55	RAM63	Row 39	RAM39	Row 47	RAM47	Row 39	RAM47	Row 47	RAM63	
COM9	Row 54	RAM54	Row 62	RAM62	Row 54	RAM62	Row 38	RAM38	Row 46	RAM46	Row 38	RAM46	Row 46	RAM62	
COM10	Row 53	RAM53	Row 61	RAM61	Row 53	RAM61	Row 37	RAM37	Row 45	RAM45	Row 37	RAM45	Row 45	RAM61	
COM11	Row 52	RAM52	Row 60	RAM60	Row 52	RAM60	Row 36	RAM36	Row 44	RAM44	Row 36	RAM44	Row 44	RAM60	
COM12	Row 51	RAM51	Row 59	RAM59	Row 51	RAM59	Row 35	RAM35	Row 43	RAM43	Row 35	RAM43	Row 43	RAM59	
COM13	Row 50	RAM50	Row 58	RAM58	Row 50	RAM58	Row 34	RAM34	Row 42	RAM42	Row 34	RAM42	Row 42	RAM58	
COM14	Row 49	RAM49	Row 57	RAM57	Row 49	RAM57	Row 33	RAM33	Row 41	RAM41	Row 33	RAM41	Row 41	RAM57	
COM15	Row 48	RAM48	Row 56	RAM56	Row 48	RAM56	Row 32	RAM32	Row 40	RAM40	Row 32	RAM40	Row 40	RAM56	
COM16	Row 47	RAM47	Row 55	RAM55	Row 47	RAM55	Row 31	RAM31	Row 39	RAM39	Row 31	RAM39	Row 39	RAM55	
COM17	Row 46	RAM46	Row 54	RAM54	Row 46	RAM54	Row 30	RAM30	Row 38	RAM38	Row 30	RAM38	Row 38	RAM54	
COM18	Row 45	RAM45	Row 53	RAM53	Row 45	RAM53	Row 29	RAM29	Row 37	RAM37	Row 29	RAM37	Row 37	RAM53	
COM19	Row 44	RAM44	Row 52	RAM52	Row 44	RAM52	Row 28	RAM28	Row 36	RAM36	Row 28	RAM36	Row 36	RAM52	
COM20	Row 43	RAM43	Row 51	RAM51	Row 43	RAM51	Row 27	RAM27	Row 35	RAM35	Row 27	RAM35	Row 35	RAM51	
COM21	Row 42	RAM42	Row 50	RAM50	Row 42	RAM50	Row 26	RAM26	Row 34	RAM34	Row 26	RAM34	Row 34	RAM50	
COM22	Row 41	RAM41	Row 49	RAM49	Row 41	RAM49	Row 25	RAM25	Row 33	RAM33	Row 25	RAM33	Row 33	RAM49	
COM23	Row 40	RAM40	Row 48	RAM48	Row 40	RAM48	Row 24	RAM24	Row 32	RAM32	Row 24	RAM32	Row 32	RAM48	
COM24	Row 39	RAM39	Row 47	RAM47	Row 39	RAM47	Row 23	RAM23	Row 31	RAM31	Row 23	RAM31	Row 31	RAM47	
COM25	Row 38	RAM38	Row 46	RAM46	Row 38	RAM46	Row 22	RAM22	Row 30	RAM30	Row 22	RAM30	Row 30	RAM46	
COM26	Row 37	RAM37	Row 45	RAM45	Row 37	RAM45	Row 21	RAM21	Row 29	RAM29	Row 21	RAM29	Row 29	RAM45	
COM27	Row 36	RAM36	Row 44	RAM44	Row 36	RAM44	Row 20	RAM20	Row 28	RAM28	Row 20	RAM28	Row 28	RAM44	
COM28	Row 35	RAM35	Row 43	RAM43	Row 35	RAM43	Row 19	RAM19	Row 27	RAM27	Row 19	RAM27	Row 27	RAM43	
COM29	Row 34	RAM34	Row 42	RAM42	Row 34	RAM42	Row 18	RAM18	Row 26	RAM26	Row 18	RAM26	Row 26	RAM42	
COM30	Row 33	RAM33	Row 41	RAM41	Row 33	RAM41	Row 17	RAM17	Row 25	RAM25	Row 17	RAM25	Row 25	RAM41	
COM31	Row 32	RAM32	Row 40	RAM40	Row 32	RAM40	Row 16	RAM16	Row 24	RAM24	Row 16	RAM24	Row 24	RAM40	
COM32	Row 31	RAM31	Row 39	RAM39	Row 31	RAM39	Row 15	RAM15	Row 23	RAM23	Row 15	RAM23	Row 23	RAM39	
COM33	Row 30	RAM30	Row 38	RAM38	Row 30	RAM38	Row 14	RAM14	Row 22	RAM22	Row 14	RAM22	Row 22	RAM38	
COM34	Row 29	RAM29	Row 37	RAM37	Row 29	RAM37	Row 13	RAM13	Row 21	RAM21	Row 13	RAM21	Row 21	RAM37	
COM35	Row 28	RAM28	Row 36	RAM36	Row 28	RAM36	Row 12	RAM12	Row 20	RAM20	Row 12	RAM20	Row 20	RAM36	
COM36	Row 27	RAM27	Row 35	RAM35	Row 27	RAM35	Row 11	RAM11	Row 19	RAM19	Row 11	RAM19	Row 19	RAM35	
COM37	Row 26	RAM26	Row 34	RAM34	Row 26	RAM34	Row 10	RAM10	Row 18	RAM18	Row 10	RAM18	Row 18	RAM34	
COM38	Row 25	RAM25	Row 33	RAM33	Row 25	RAM33	Row 9	RAM9	Row 17	RAM17	Row 9	RAM17	Row 17	RAM33	
COM39	Row 24	RAM24	Row 32	RAM32	Row 24	RAM32	Row 8	RAM8	Row 16	RAM16	Row 8	RAM16	Row 16	RAM32	
COM40	Row 23	RAM23	Row 31	RAM31	Row 23	RAM31	Row 7	RAM7	Row 15	RAM15	Row 7	RAM15	Row 15	RAM31	
COM41	Row 22	RAM22	Row 30	RAM30	Row 22	RAM30	Row 6	RAM6	Row 14	RAM14	Row 6	RAM14	Row 14	RAM30	
COM42	Row 21	RAM21	Row 29	RAM29	Row 21	RAM29	Row 5	RAM5	Row 13	RAM13	Row 5	RAM13	Row 13	RAM29	
COM43	Row 20	RAM20	Row 28	RAM28	Row 20	RAM28	Row 4	RAM4	Row 12	RAM12	Row 4	RAM12	Row 12	RAM28	
COM44	Row 19	RAM19	Row 27	RAM27	Row 19	RAM27	Row 3	RAM3	Row 11	RAM11	Row 3	RAM11	Row 11	RAM27	
COM45	Row 18	RAM18	Row 26	RAM26	Row 18	RAM26	Row 2	RAM2	Row 10	RAM10	Row 2	RAM10	Row 10	RAM26	
COM46	Row 17	RAM17	Row 25	RAM25	Row 17	RAM25	Row 1	RAM1	Row 9	RAM9	Row 1	RAM9	Row 9	RAM25	
COM47	Row 16	RAM16	Row 24	RAM24	Row 16	RAM24	Row 0	RAM0	Row 8	RAM8	Row 0	RAM8	Row 8	RAM24	
COM48	Row 15	RAM15	Row 23	RAM23	Row 15	RAM23	-	-	Row 7	RAM7	-	-	Row 7	RAM23	
COM49	Row 14	RAM14	Row 22	RAM22	Row 14	RAM22	-	-	Row 6	RAM6	-	-	Row 6	RAM22	
COM50	Row 13	RAM13	Row 21	RAM21	Row 13	RAM21	-	-	Row 5	RAM5	-	-	Row 5	RAM21	
COM51	Row 12	RAM12	Row 20	RAM20	Row 12	RAM20	-	-	Row 4	RAM4	-	-	Row 4	RAM20	
COM52	Row 11	RAM11	Row 19	RAM19	Row 11	RAM19	-	-	Row 3	RAM3	-	-	Row 3	RAM19	
COM53	Row 10	RAM10	Row 18	RAM18	Row 10	RAM18	-	-	Row 2	RAM2	-	-	Row 2	RAM18	
COM54	Row 9	RAM9	Row 17	RAM17	Row 9	RAM17	-	-	Row 1	RAM1	-	-	Row 1	RAM17	
COM55	Row 8	RAM8	Row 16	RAM16	Row 8	RAM16	-	-	Row 0	RAM0	-	-	Row 0	RAM16	
COM56	Row 7	RAM7	Row 15	RAM15	Row 7	RAM15	-	-	-	-	-	-	-	-	
COM57	Row 6	RAM6	Row 14	RAM14	Row 6	RAM14	-	-	-	-	-	-	-	-	
COM58	Row 5	RAM5	Row 13	RAM13	Row 5	RAM13	-	-	-	-	-	-	-	-	
COM59	Row 4	RAM4	Row 12	RAM12	Row 4	RAM12	-	-	-	-	-	-	-	-	
COM60	Row 3	RAM3	Row 11	RAM11	Row 3	RAM11	-	-	-	-	-	-	-	-	
COM61	Row 2	RAM2	Row 10	RAM10	Row 2	RAM10	-	-	-	-	-	-	-	-	
COM62	Row 1	RAM1	Row 9	RAM9	Row 1	RAM9	-	-	-	-	-	-	-	-	
COM63	Row 0	RAM0	Row 8	RAM8	Row 0	RAM8	-	-	-	-	-	-	-	-	
Display examples	(a)		(b)		(c)		(d)		(e)		(f)		(g)		

(a)

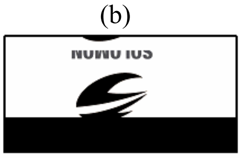
(b)

(c)

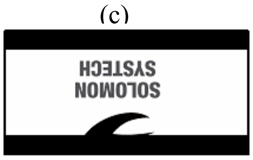
(d)



(e)



(f)



(g)

(RAM)

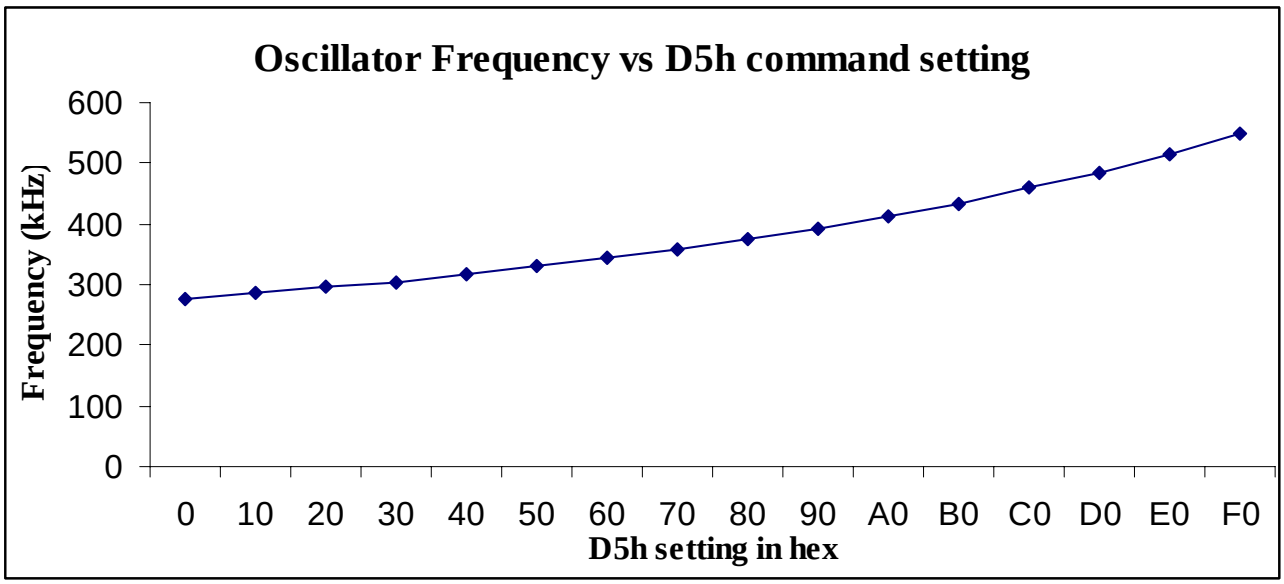
10.1.23 Set Display Clock Divide Ratio/ Oscillator Frequency (D5h)

This command consists of two functions:

- Display Clock Divide Ratio (D)(A[3:0])
  Set the divide ratio to generate DCLK (Display Clock) from CLK. The divide ratio is from 1 to 16, with reset value = 1. Please refer to section 8.3 for the details relationship of DCLK and CLK.

- Oscillator Frequency (A[7:4])
  Program the oscillator frequency Fosc that is the source of CLK if CLS pin is pulled high. The 4-bit value results in 16 different frequency settings available as shown below. The default setting is 0111b.

Figure 10-8 : Typical Oscillator frequency adjustment by D5 command (V_{DD} =2.8V)



Note
(1) There is 10% tolerance in the above frequency values

10.1.24 Set Area Color Mode ON/OFF & Low Power Display Mode (D8h)

This command is used to enable area color mode. RESET is monochrome mode. The low power display mode can reduce power consumption during IC operation.

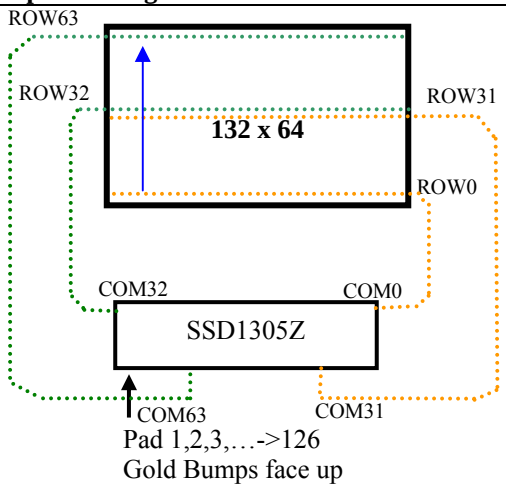
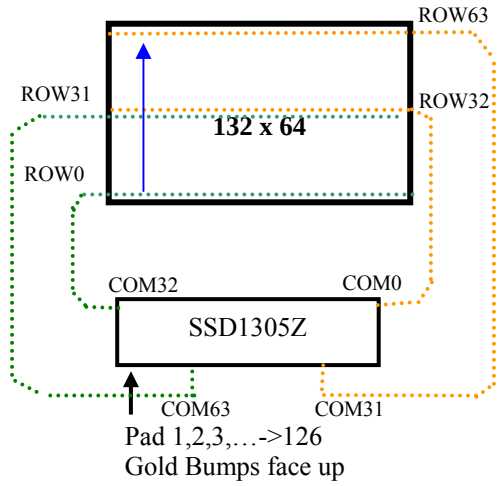
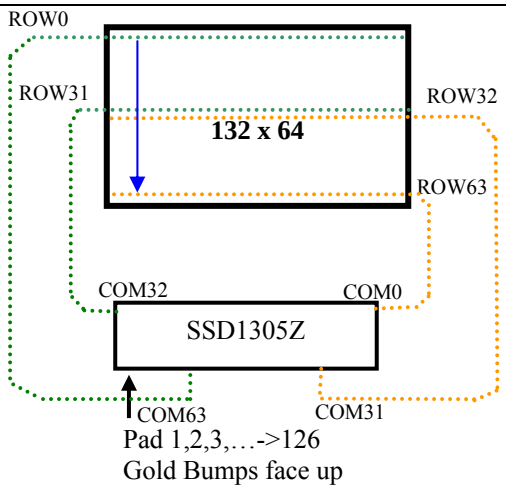
10.1.25 Set Pre-charge Period (D9h)

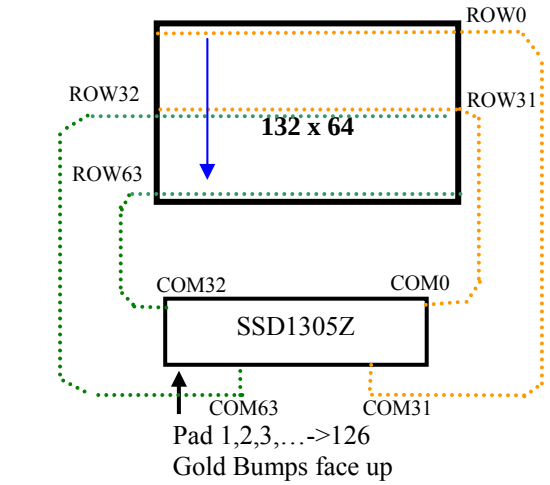
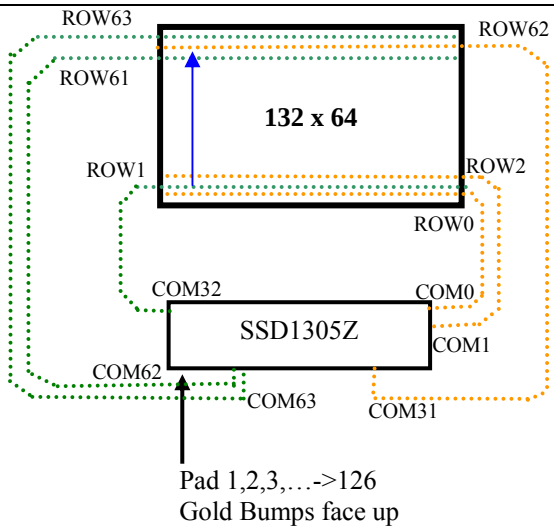
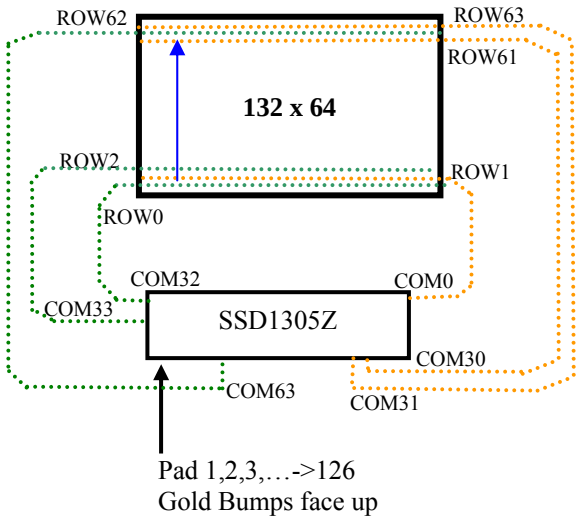
This command is used to set the duration of the pre-charge period. The interval is counted in number of DCLK, where RESET equals 2 DCLKs.

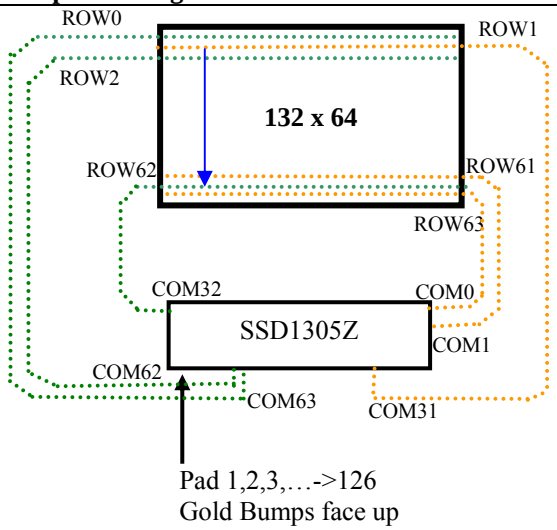
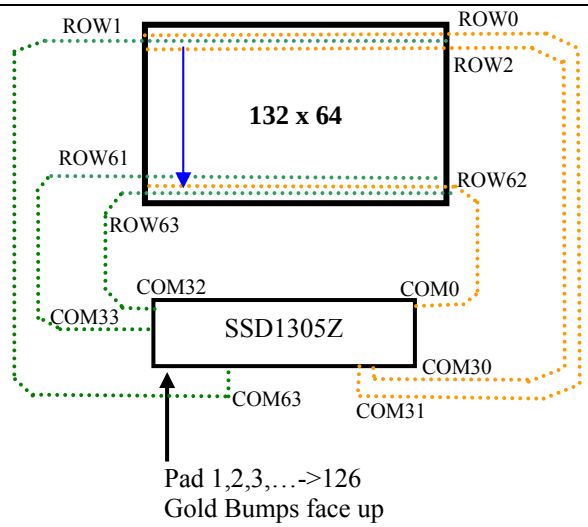
10.1.26 Set COM Pins Hardware Configuration (DAh)

This command sets the COM signals pin configuration to match the OLED panel hardware layout. The table below shows the COM pin configuration under different conditions (for MUX ratio =64):

Table 10-3 : COM Pins Hardware Configuration

Conditions	COM pins Configurations
1 Sequential COM pin configuration (DAh X[4] =0) COM output Scan direction: from COM0 to COM63 (C0h) Disable COM Left/Right remap (DAh X[5] =0)	
2 Sequential COM pin configuration (DAh X[4] =0) COM output Scan direction: from COM0 to COM63 (C0h) Enable COM Left/Right remap (DAh X[5] =1)	
3 Sequential COM pin configuration (DAh X[4] =0) COM output Scan direction: from COM63 to COM0 (C8h) Disable COM Left/Right remap (DAh X[5] =0)	

Conditions	COM pins Configurations
4 Sequential COM pin configuration (DAh X[4] =0) COM output Scan direction: from COM63 to COM0 (C8h) Enable COM Left/Right remap (DAh X[5] =1)	
5 Alternative COM pin configuration (DAh X[4] =1) COM output Scan direction: from COM0 to COM63 (C0h) Disable COM Left/Right remap (DAh X[5] =0)	
6 Alternative COM pin configuration (DAh X[4] =1) COM output Scan direction: from COM0 to COM63 (C0h) Enable COM Left/Right remap (DAh X[5] =1)	

Conditions	COM pins Configurations
7 Alternative COM pin configuration (DAh X[4] =1) COM output Scan direction: from COM63 to COM0(C8h) Disable COM Left/Right remap (DAh X[5] =0)	
8 Alternative COM pin configuration (DAh X[4] =1) COM output Scan direction: from COM63 to COM0(C8h) Enable COM Left/Right remap (DAh X[5] =1)	

10.1.27 Set V_{COMH} Deselect Level (DBh)

This command adjusts the V_{COMH} regulator output.

10.1.28 Enter Read Modify Write (E0h)

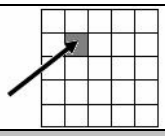
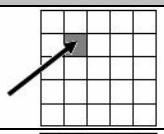
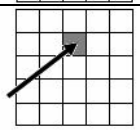
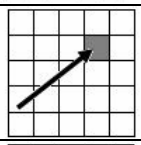
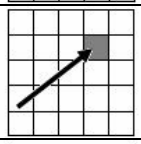
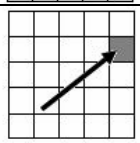
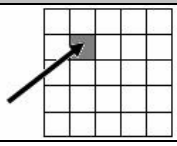
This single byte command is used to enter the Read Modify Write mode.
During the Read Modify Write mode:

The RAM address pointer will not be incremented when there is data read.
The RAM address pointer will be increased by one automatically after each data write.

After exit the Read Modify Write Mode by command EEh, the RAM address pointer returns back to the original location before enter the Read Modify Write mode.

For instance, when reading the data from the RAM and re-writing a new data to the same location, there is no need to re-enter the column and page addresses again under this mode.

Table 10-4 : Example of Read Modify Write Mode

Condition	RAM & address pointer (under Horizontal addressing mode)
Originally, Address Pointer point to address A	
Enter Read Modify Write Mode by command E0h	
Data read : address pointer does not change	
Data Write: address pointer increases by one automatically after each data write	
Data Write: address pointer increases by one automatically after each data write	
Data read : address pointer does not change	
Data Write: address pointer increases by one automatically after each data write	
Exit Read Modify Write Mode by command EEh	
Address Pointer point to address A after exit Read Modify Write Mode	

10.1.29 NOP (E3h)

No Operation Command

10.1.30 Exit Read Modify Write (EEh)

This single byte command is used to exit the Read Modify Write mode (Please refer to Section 10.1.28. for details of the Read Modify Write Mode).

10.1.31 Status register Read

This command is issued by setting D/C# ON LOW during a data read (See Figure 13-1 to Figure 13-3 for parallel interface waveform). It allows the MCU to monitor the internal status of the chip. No status read is provided for serial mode.

10.2 Graphic Acceleration Command

10.2.1 Horizontal Scroll Setup (26h/27h)

This command consists of 5 consecutive bytes to set up the horizontal scroll parameters and determines the scrolling start page, end page and scrolling speed.

Before issuing this command the horizontal scroll must be deactivated (2Eh). Otherwise, RAM content may be corrupted.

The SSD1305 horizontal scroll is designed for 132 columns scrolling. The following three figures (Figure 10-9, Figure 10-10, Figure 10-11) show the examples of using the horizontal scroll:

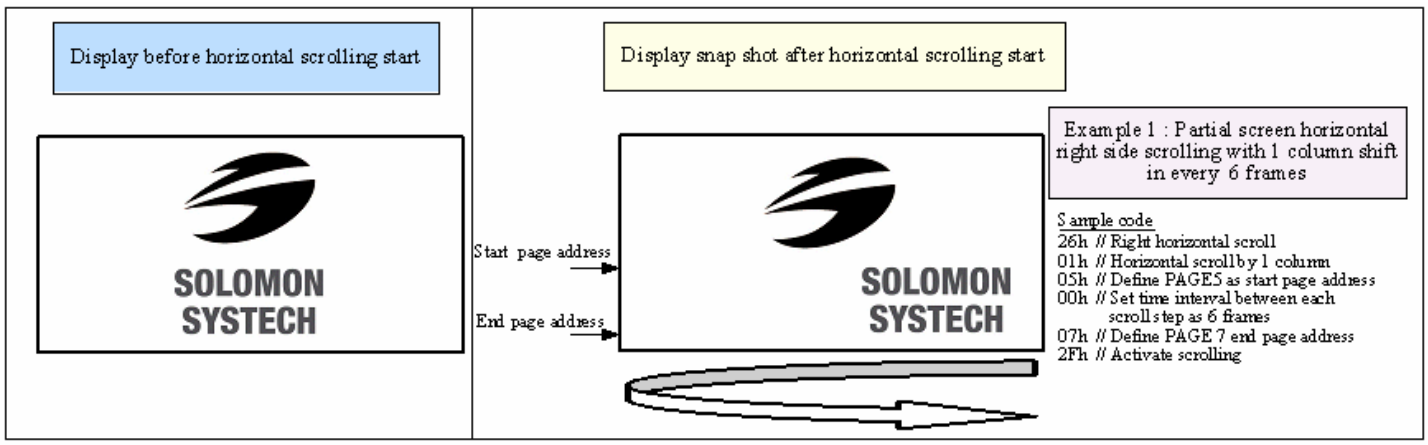
Figure 10-9 : Horizontal scroll example: Scroll RIGHT by 4 columns

Original Setting	SEG0	SEG1	SEG2	SEG3	SEG4	SEG5	…	…	…	SEG126	SEG127	SEG128	SEG129	SEG130	SEG131
After one scroll step	SEG128	SEG129	SEG130	SEG131	SEG0	SEG1	…	…	…	SEG122	SEG123	SEG124	SEG125	SEG126	SEG127

Figure 10-10 : Horizontal scroll example: Scroll LEFT by 2 columns

Original Setting	SEG0	SEG1	SEG2	SEG3	SEG4	SEG5	…	…	…	SEG126	SEG127	SEG128	SEG129	SEG130	SEG131
After one scroll step	SEG2	SEG3	SEG4	SEG5	SEG6	SEG7	…	…	…	SEG128	SEG129	SEG130	SEG131	SEG0	SEG1

Figure 10-11 : Horizontal scrolling setup example



10.2.2 Continuous Vertical and Horizontal Scroll Setup (29h/2Ah)

This command consists of 6 consecutive bytes to set up the continuous vertical and horizontal scroll parameters and determines the scrolling start page, end page, scrolling speed and vertical scrolling offset.

The bytes A[2:0], B[2:0], C[2:0] and D[2:0] of command 29h/2Ah are for the setting of the continuous horizontal scrolling. The byte E[5:0] is for the setting of the continuous vertical scrolling offset. All these bytes together are for the setting of continuous diagonal (horizontal + vertical) scrolling. If the vertical scrolling offset byte E[5:0] is set to zero, then only horizontal scrolling is performed (like command 26/27h). Alternatively, if the byte A[2:0] is set to zero and E[5:0] is not set to zero, then only vertical scrolling is performed.

Before issuing this command the scroll must be deactivated (2Eh). Otherwise, RAM content may be corrupted. The following two figures (Figure 10-12 , Figure 10-13) show the examples of using the continuous vertical and horizontal scroll:

Figure 10-12 : Continuous Vertical and Horizontal scrolling setup examples

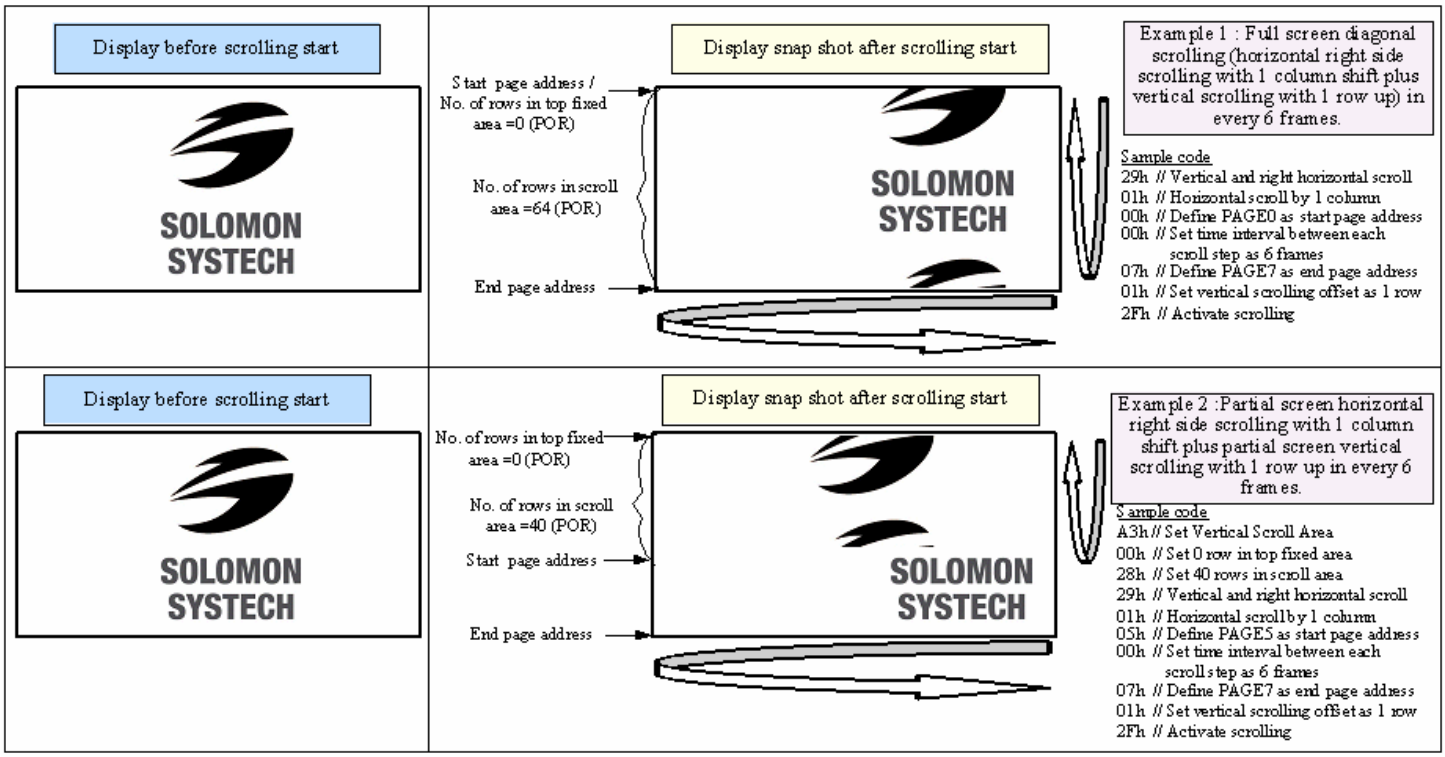
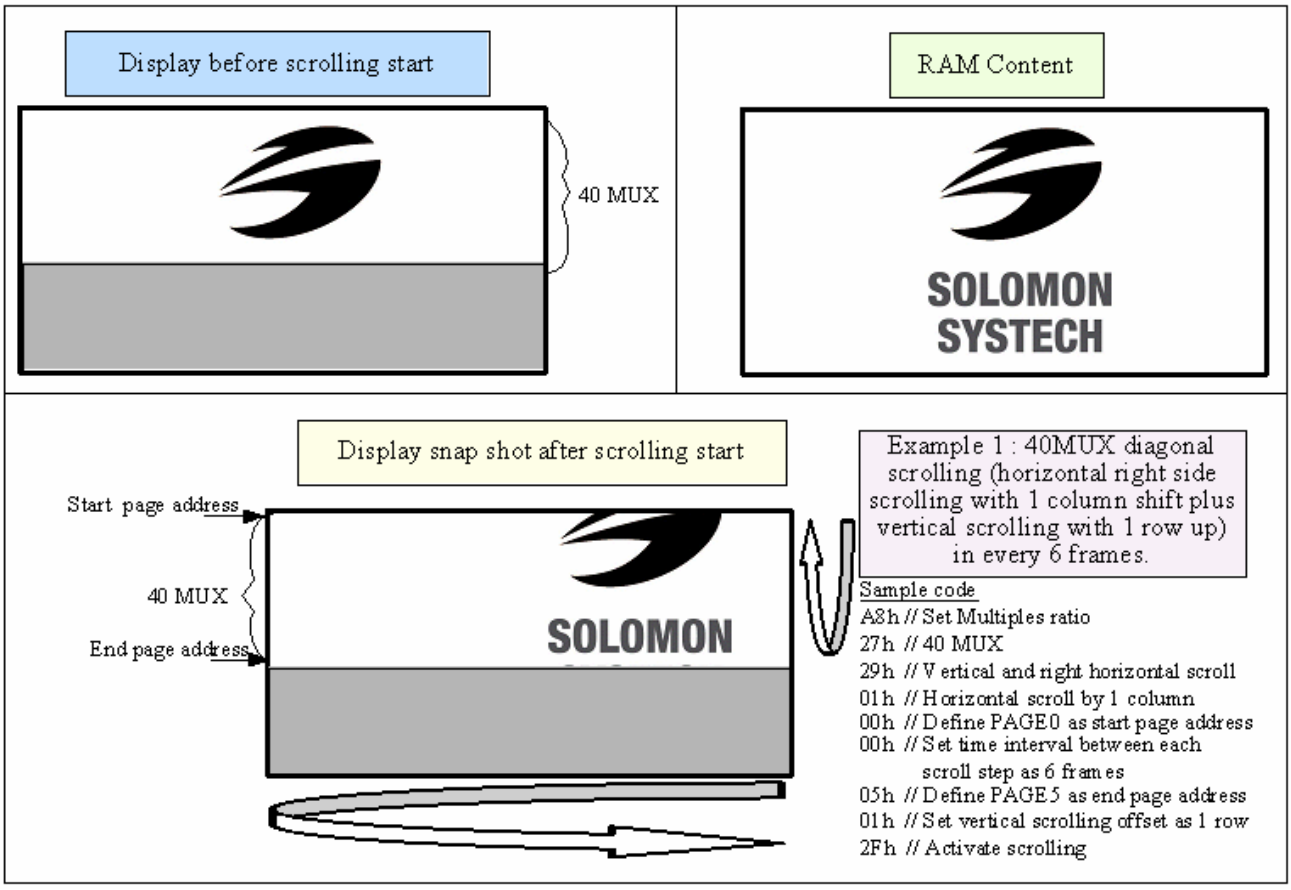


Figure 10-13 : Continuous Vertical and Horizontal scrolling example: With setting in MUX ratio

As shown in Figure 10-13, the whole RAM content is displayed during scrolling regardless of the MUX ratio.



10.2.3 Deactivate Scroll (2Eh)

This command stops the motion of scrolling. After sending 2Eh command to deactivate the scrolling action, the ram data needs to be rewritten.

10.2.4 Activate Scroll (2Fh)

This command starts the motion of scrolling and should only be issued after the scroll setup parameters have been defined by the scrolling setup commands :26h/27h/29h/2Ah . The setting in the last scrolling setup command overwrites the setting in the previous scrolling setup commands.

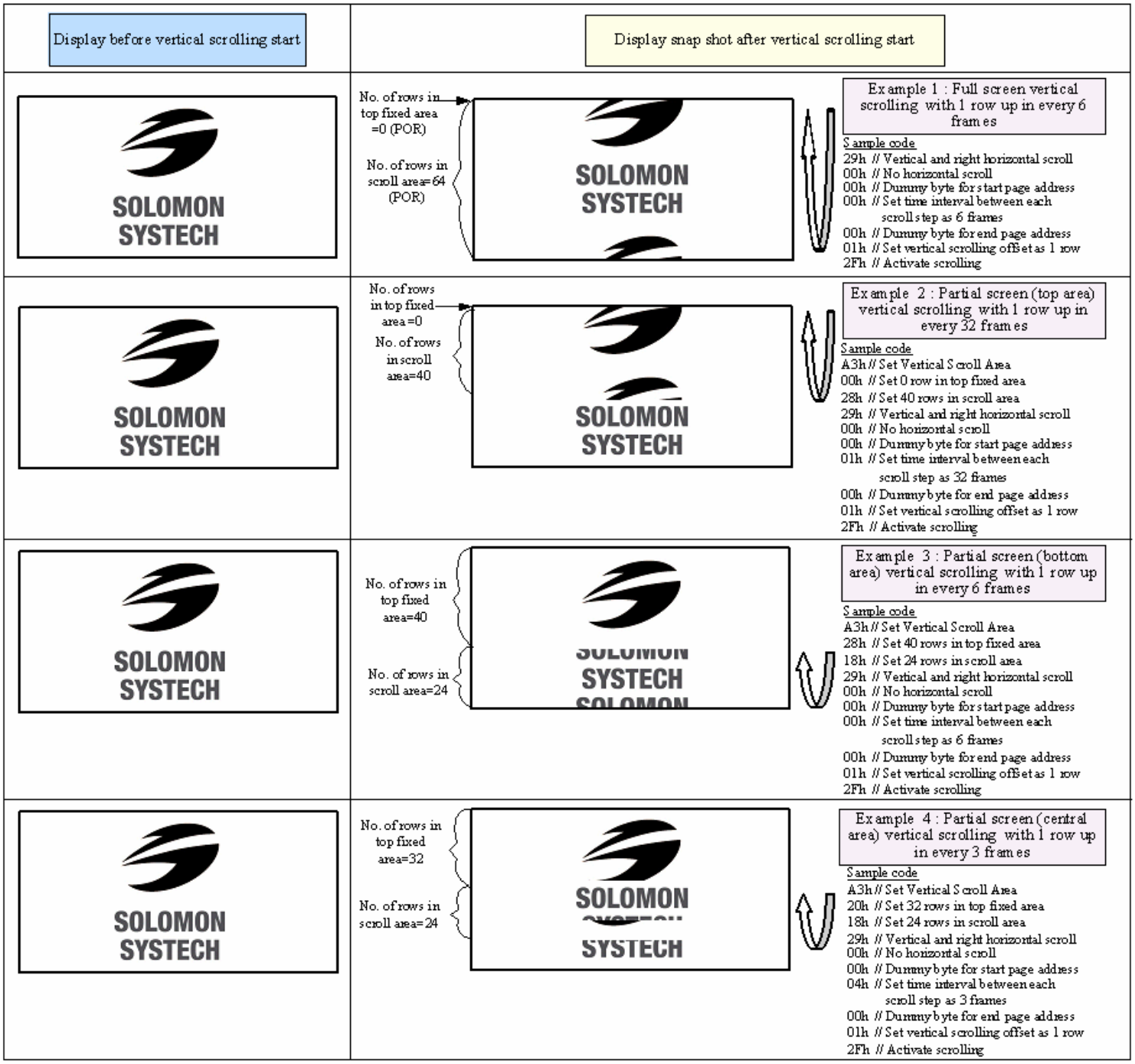
The following actions are prohibited after the scrolling is activated

1. RAM access (Data write or read)
2. Changing the horizontal scroll setup parameters

10.2.5 Set Vertical Scroll Area(A3h)

This command consists of 3 consecutive bytes to set up the vertical scroll area. For the continuous vertical scroll function (command 29/2Ah), the number of rows that in vertical scrolling can be set smaller or equal to the MUX ratio. Figure 10-14 shows some vertical scrolling example with different settings in vertical scroll area.

Figure 10-14 : Vertical scroll area setup examples



11 MAXIMUM RATINGS

Table 11-1 : Maximum Ratings (Voltage Referenced to V_{SS})

Symbol	Parameter	Value	Unit
V_{DD}	Supply Voltage	-0.3 to +4	V
V_{DDIO}		-0.3 to V_{DD}+0.5	V
V_{CC}		0 to 16	V
V_{SEG}	SEG output voltage	0 to V_{CC}	V
V_{COM}	COM output voltage	0 to 0.9*V_{CC}	V
V_{in}	Input voltage	V_{SS}-0.3 to V_{DD}+0.3	V
T_A	Operating Temperature	-40 to +85	ºC
T_{stg}	Storage Temperature Range	-65 to +150	ºC

Maximum ratings are those values beyond which damages to the device may occur. Functional operation should be restricted to the limits in the Electrical Characteristics tables or Pin Description section

This device may be light sensitive. Caution should be taken to avoid exposure of this device to any light source during normal operation. This device is not radiation protected.

12 DC CHARACTERISTICS

Condition (Unless otherwise specified):

Voltage referenced to V_{SS}

V_{DD} = 2.4 to 3.5V

T_A = 25°C

Table 12-1 : DC Characteristics

Symbol	Parameter	Test Condition	Min	Typ	Max	Unit
V_{CC}	Operating Voltage	-	7	-	15	V
V_{DD}	Logic Supply Voltage	-	2.4	-	3.5	V
V_{DDIO}	Logic Supply Voltage for MCU interface	-	1.6	-	V_{DD}	V
V_{OH}	High Logic Output Level	I_{OUT} = 100uA, 3.3MHz	0.9 x V_{DDIO}	-	-	V
V_{OL}	Low Logic Output Level	I_{OUT} = 100uA, 3.3MHz	-	-	0.1 x V_{DDIO}	V
V_{IH}	High Logic Input Level	-	0.8 x V_{DDIO}	-	-	V
V_{IL}	Low Logic Input Level	-	-	-	0.2 x V_{DDIO}	V
$I_{CC, SLEEP}$	I_{CC} Sleep mode Current	V_{DDIO} =1.6V~3.3V, V_{DD} = 2.4V ~3.5V, V_{CC} = 7V~15V Display OFF, No panel attached	-	-	10	uA
$I_{DD, SLEEP}$	I_{DD} Sleep mode Current	V_{DDIO} =1.6V~3.3V, V_{DD} = 2.4V ~3.5V, V_{CC} = 7V~15V Display OFF, No panel attached	-	-	10	uA
$I_{DDIO, SLEEP}$	I_{DDIO} Sleep mode Current	V_{DDIO} =1.6V~3.3V, V_{DD} = 2.4V ~3.5V, V_{CC} = 7V~15V Display OFF, No panel attached	-	-	10	uA
I_{CC}	V_{CC} Supply Current V_{DD} = 2.7V, V_{CC} = 12V, I_{REF} = 10uA No loading, Display ON, All ON	Contrast = FFh	-	550	1000	uA
I_{DD}	V_{DD} Supply Current V_{DD} = 2.7V, V_{CC} = 12V, I_{REF} = 10uA No loading, Display ON, All ON		-	100	300	uA
I_{SEG}	Segment Output Current V_{DD}=2.7V, V_{CC}=12V, I_{REF}=10uA, Display ON.	Contrast=FFh	294	320	346	uA
		Contrast=AFh	-	220	-	
		Contrast=7Fh	-	159	-	
		Contrast=3Fh	-	79	-	
		Contrast=0Fh	-	19	-	
Dev	Segment output current uniformity	Dev = (I_{SEG} – I_{MID})/I_{MID} I_{MID} = (I_{MAX} + I_{MIN})/2 I_{SEG}[0:131] = Segment current at contrast = FFh	-3	-	+3	%
Adj. Dev	Adjacent pin output current uniformity (contrast = FF)	Adj Dev = (I[n]-I[n+1]) / (I[n]+I[n+1])	-2	-	+2	%

13 AC CHARACTERISTICS

Conditions:

Voltage referenced to V_{SS}
V_{DD}=2.4 to3.5V
T_A = 25°C

Table 13-1 : AC Characteristics

Symbol	Parameter	Test Condition	Min	Typ	Max	Unit
F_{OSC} [(1)]	Oscillation Frequency of Display Timing Generator	V_{DD} = 2.8V	324	360	396	kHz
F_{FRM}	Frame Frequency for 64 MUX Mode	132x64 Graphic Display Mode, Display ON, Internal Oscillator Enabled	-	F_{OSC} x 1/(DxKx64) [(2)]	-	Hz
RES#	Reset low pulse width		3	-	-	us

Note

(1) F_{OSC} stands for the frequency value of the internal oscillator and the value is measured when command D5h A[7:4] is in default value.

(2) D: divide ratio (default value = 1)
K: number of display clocks (default value = 54)
Please refer to Table 9-1 (Set Display Clock Divide Ratio/Oscillator Frequency, D5h) for detailed description

Table 13-2 : 6800-Series MCU Parallel Interface Timing Characteristics

(V_{DD} - V_{SS} = 2.4V to 3.5V, V_{DDIO} = V_{DD}, T_A = 25°C)

Symbol	Parameter	Min	Typ	Max	Unit
t_{cycle}	Clock Cycle Time	300	-	-	ns
t_{AS}	Address Setup Time	0	-	-	ns
t_{AH}	Address Hold Time	0	-	-	ns
t_{DSW}	Write Data Setup Time	40	-	-	ns
t_{DHW}	Write Data Hold Time	7	-	-	ns
t_{DHR}	Read Data Hold Time	20	-	-	ns
t_{OH}	Output Disable Time	-	-	70	ns
t_{ACC}	Access Time	-	-	140	ns
PW_{CSL}	Chip Select Low Pulse Width (read) Chip Select Low Pulse Width (write)	120 60	-	-	ns
PW_{CSH}	Chip Select High Pulse Width (read) Chip Select High Pulse Width (write)	60 60	-	-	ns
t_R	Rise Time	-	-	40	ns
t_F	Fall Time	-	-	40	ns

Figure 13-1 : 6800-series MCU parallel interface characteristics

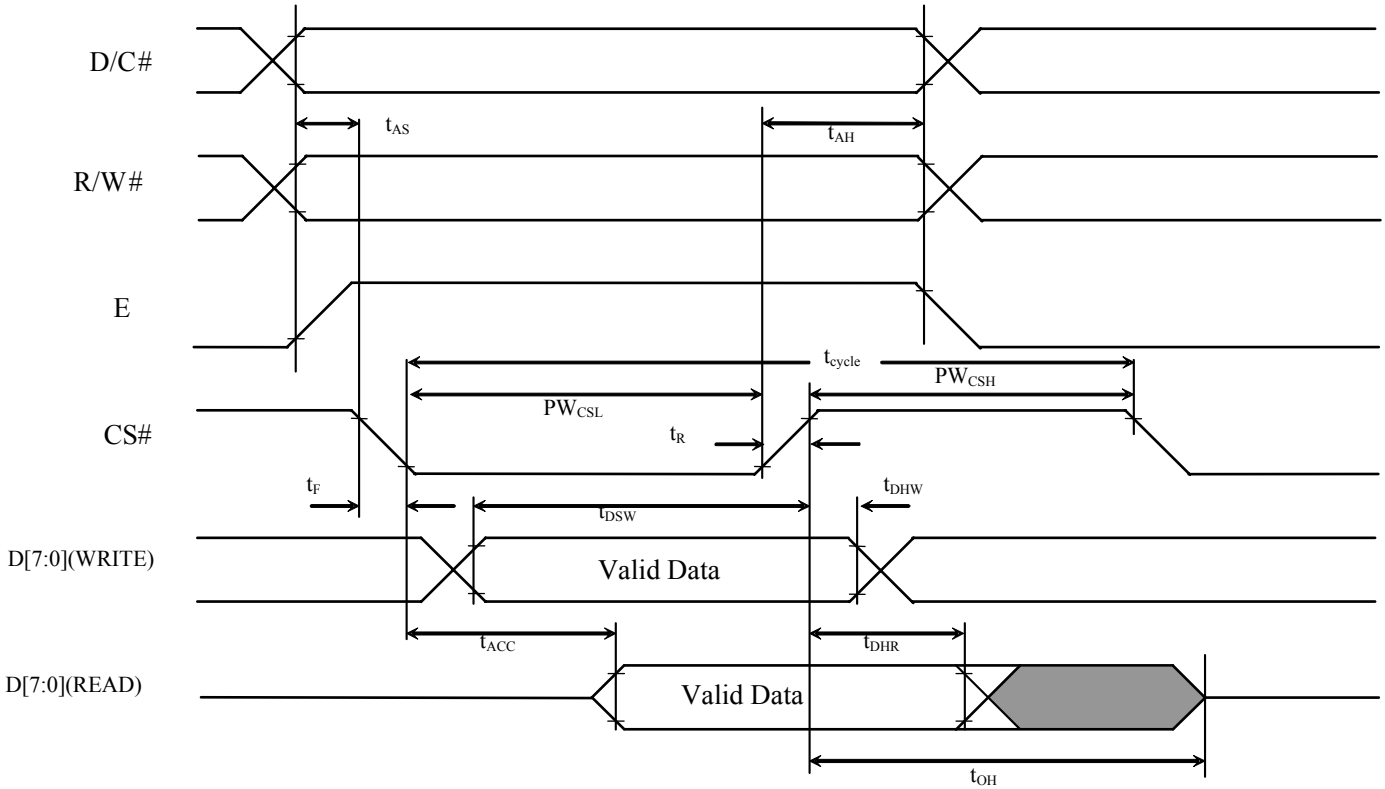


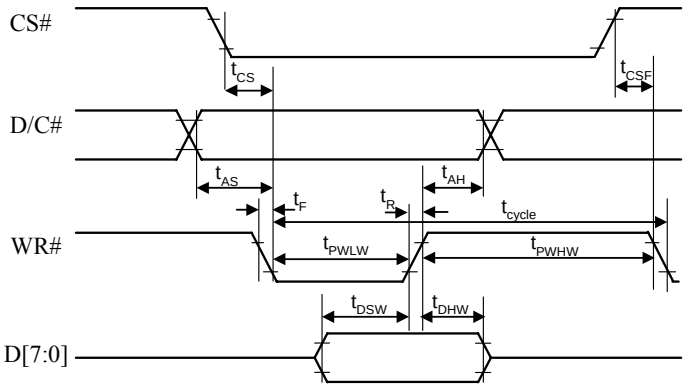
Table 13-3 : 8080-Series MCU Parallel Interface Timing Characteristics

(V_{DD} - V_{SS} = 2.4V to 3.5V, V_{DDIO} = V_{DD}, T_A = 25°C)

Symbol	Parameter	Min	Typ	Max	Unit
t_{cycle}	Clock Cycle Time	300	-	-	ns
t_{AS}	Address Setup Time	10	-	-	ns
t_{AH}	Address Hold Time	0	-	-	ns
t_{DSW}	Write Data Setup Time	40	-	-	ns
t_{DHW}	Write Data Hold Time	7	-	-	ns
t_{DHR}	Read Data Hold Time	20	-	-	ns
t_{OH}	Output Disable Time	-	-	70	ns
t_{ACC}	Access Time	-	-	140	ns
t_{PWLR}	Read Low Time	120	-	-	ns
t_{PWLW}	Write Low Time	60	-	-	ns
t_{PWHR}	Read High Time	60	-	-	ns
t_{PWHW}	Write High Time	60	-	-	ns
t_R	Rise Time	-	-	40	ns
t_F	Fall Time	-	-	40	ns
t_{CS}	Chip select setup time	0	-	-	ns
t_{CSH}	Chip select hold time to read signal	0	-	-	ns
t_{CSF}	Chip select hold time	20	-	-	ns

Figure 13-2 : 8080-series parallel interface characteristics (Form 1)

Write cycle (Form 1)



Read cycle (Form 1)

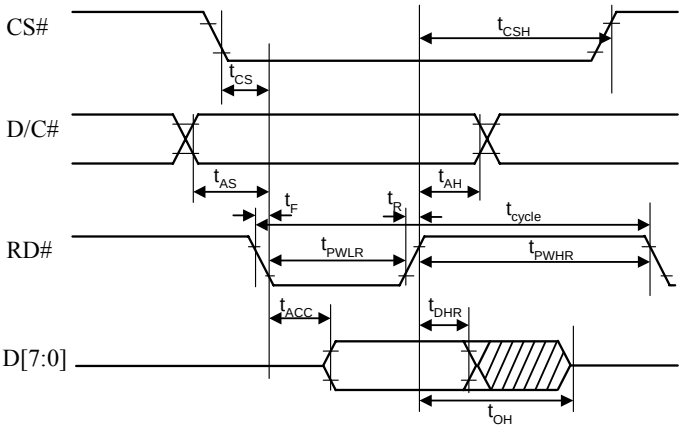
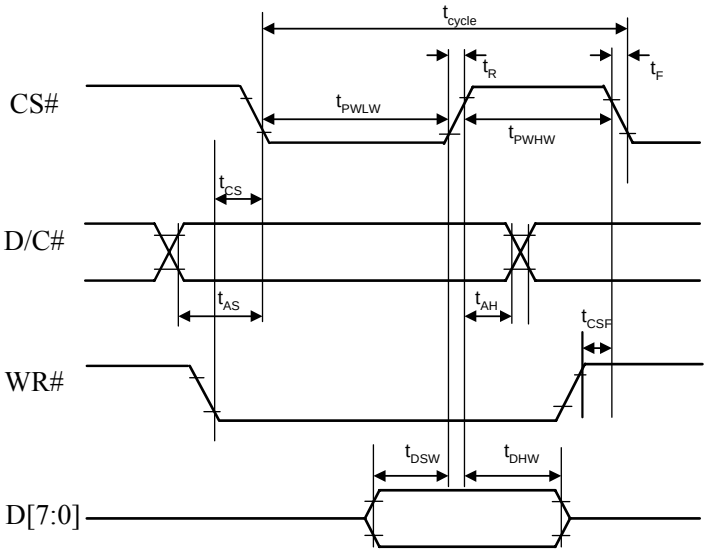


Figure 13-3 : 8080-series parallel interface characteristics (Form 2)

Write cycle (Form 2)



Read cycle (Form 2)

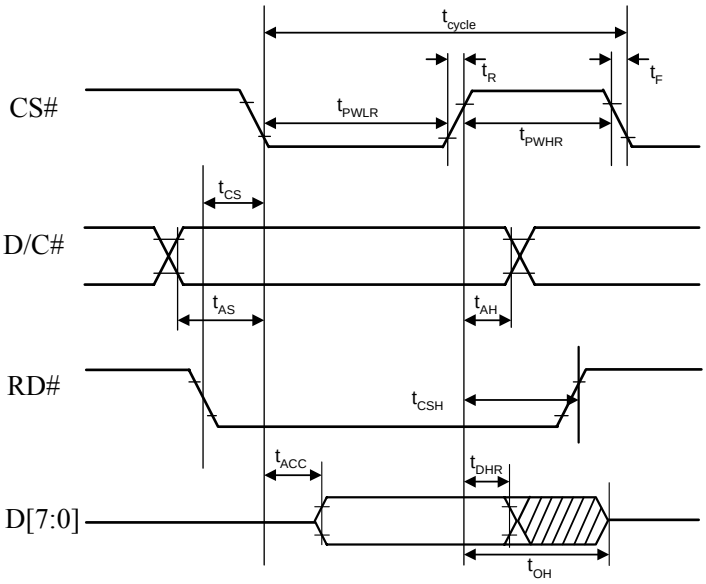
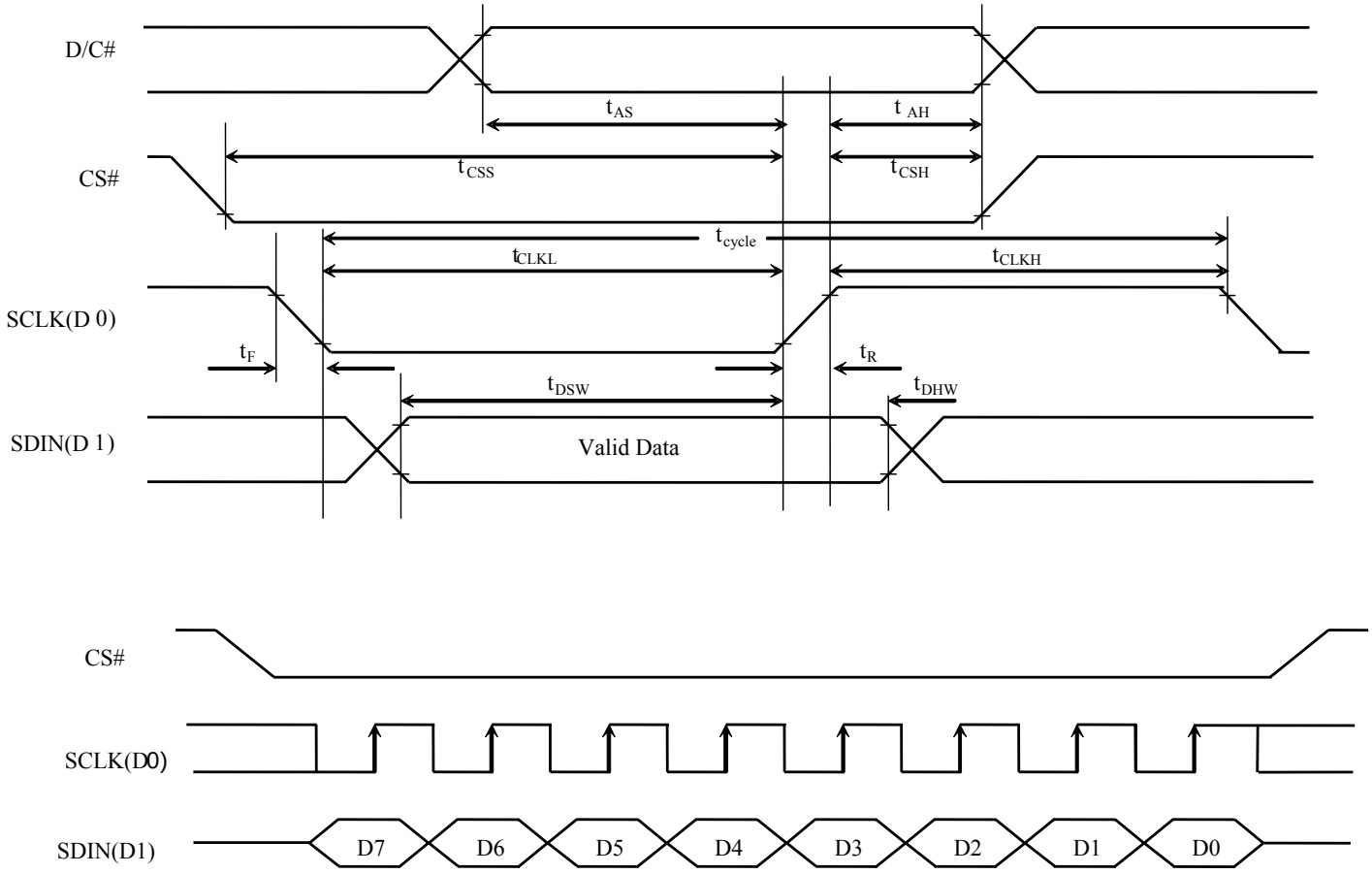


Table 13-4 : Serial Interface Timing Characteristics

(V_{DD} - V_{SS} = 2.4V to 3.5V , V_{DDIO} = V_{DD} ,T_A = 25°C)

Symbol	Parameter	Min	Typ	Max	Unit
t_{cycle}	Clock Cycle Time	250	-	-	ns
t_{AS}	Address Setup Time	150	-	-	ns
t_{AH}	Address Hold Time	150	-	-	ns
t_{CSS}	Chip Select Setup Time	120	-	-	ns
t_{CSH}	Chip Select Hold Time	60	-	-	ns
t_{DSW}	Write Data Setup Time	50	-	-	ns
t_{DHW}	Write Data Hold Time	15	-	-	ns
t_{CLKL}	Clock Low Time	100	-	-	ns
t_{CLKH}	Clock High Time	100	-	-	ns
t_R	Rise Time	-	-	40	ns
t_F	Fall Time	-	-	40	ns

Figure 13-4 : Serial interface characteristics



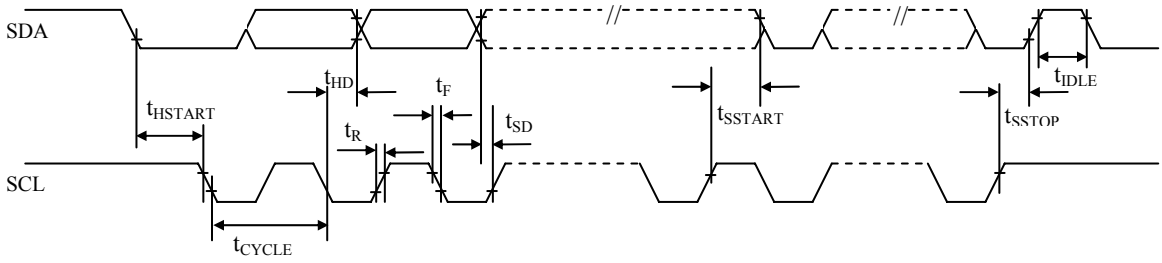
Conditions:

V_{DD} - V_{SS} = 2.4 to 3.5V
V_{DDIO} = V_{DD}
T_A = 25°C

Table 13-5 :I²C Interface Timing Characteristics

Symbol	Parameter	Min	Typ	Max	Unit
t_{cycle}	Clock Cycle Time	2.5	-	-	us
t_{HSTART}	Start condition Hold Time	0.6	-	-	us
t_{HD}	Data Hold Time (for "SDA_{OUT}" pin)	0	-	-	ns
	Data Hold Time (for "SDA_{IN}" pin)	300	-	-	ns
t_{SD}	Data Setup Time	100	-	-	ns
t_{SSTART}	Start condition Setup Time (Only relevant for a repeated Start condition)	0.6	-	-	us
t_{SSTOP}	Stop condition Setup Time	0.6	-	-	us
t_R	Rise Time for data and clock pin	-	-	300	ns
t_F	Fall Time for data and clock pin	-	-	300	ns
t_{IDLE}	Idle Time before a new transmission can start	1.3	-	-	us

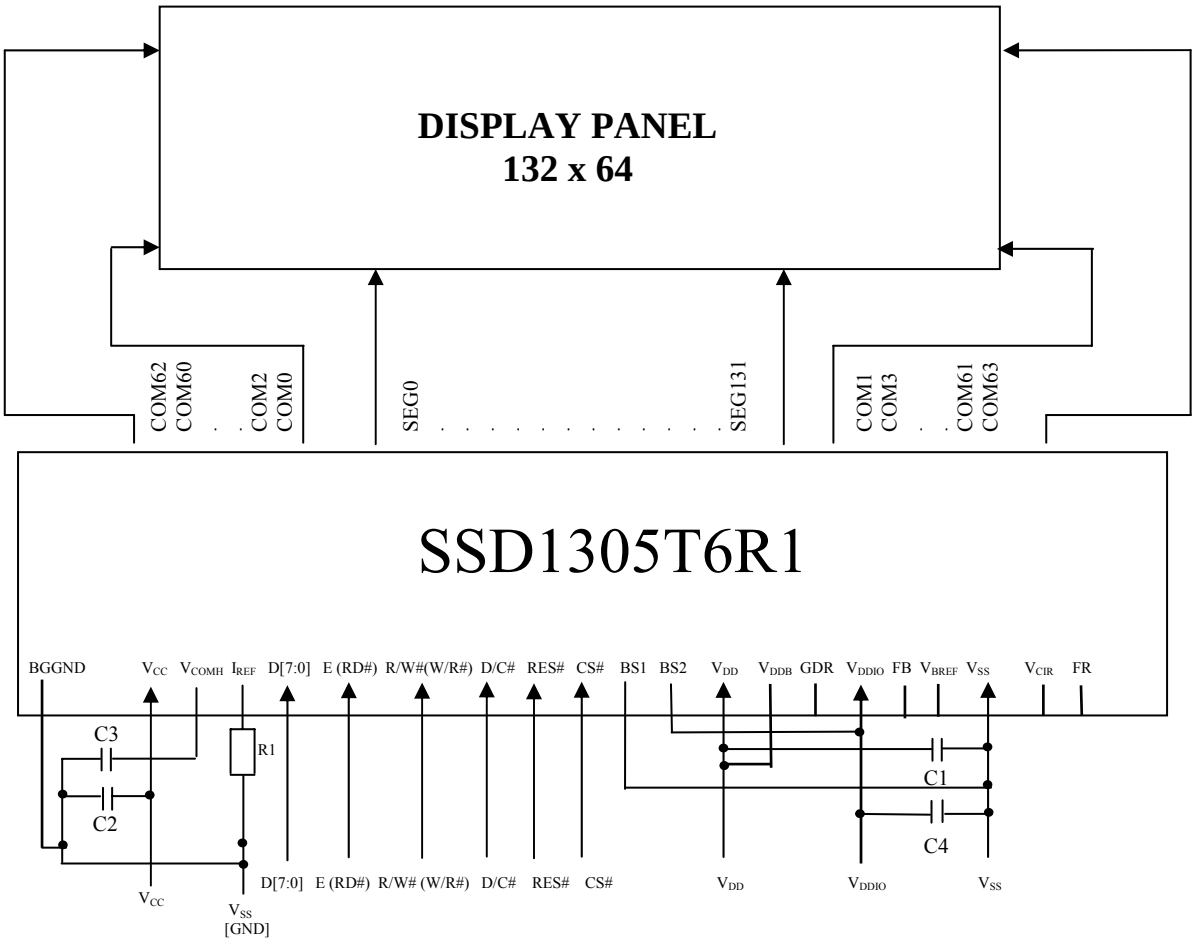
Figure 13-5 : I²C interface Timing characteristics



14 APPLICATION EXAMPLE

Figure 14-1 : Application Example of SSD1305T6R1

The configuration for 6800-parallel interface mode, external V_{CC} is shown in the following diagram:
(V_{DD}=2.7V, V_{CC} =12V, I_{REF}=10uA)



Pin connected to MCU interface: D[7:0], E, R/W#, D/C#, CS#, RES#
Pin internally connected to V_{SS}: BS0, V_{SSB}
GDR, V_{BREF}, FB should be left open.

C1: 4.7uF (1)
C2: 4.7uF (1)
C3: 4.7uF (1)
C4: 4.7uF (1)

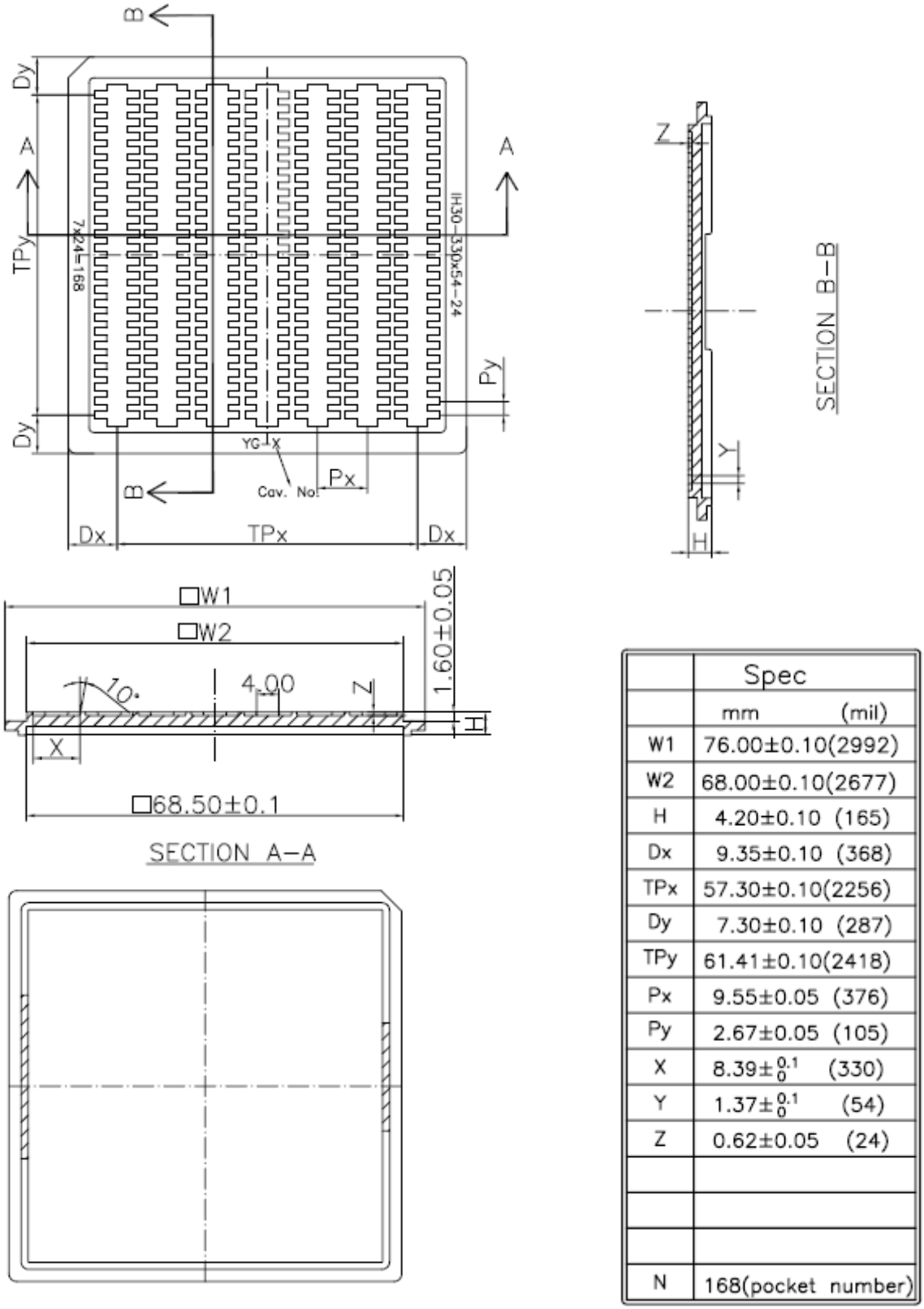
R1: 910kΩ, R1= (Voltage at I_{REF} pin-V_{SS})/I_{REF}
Voltage at I_{REF} pin = V_{CC}-3V

Note
(1) The capacitor value is recommended value. Select appropriate value against module application.

15 PACKAGE INFORMATION

15.1 SSD1305Z Die Tray Information

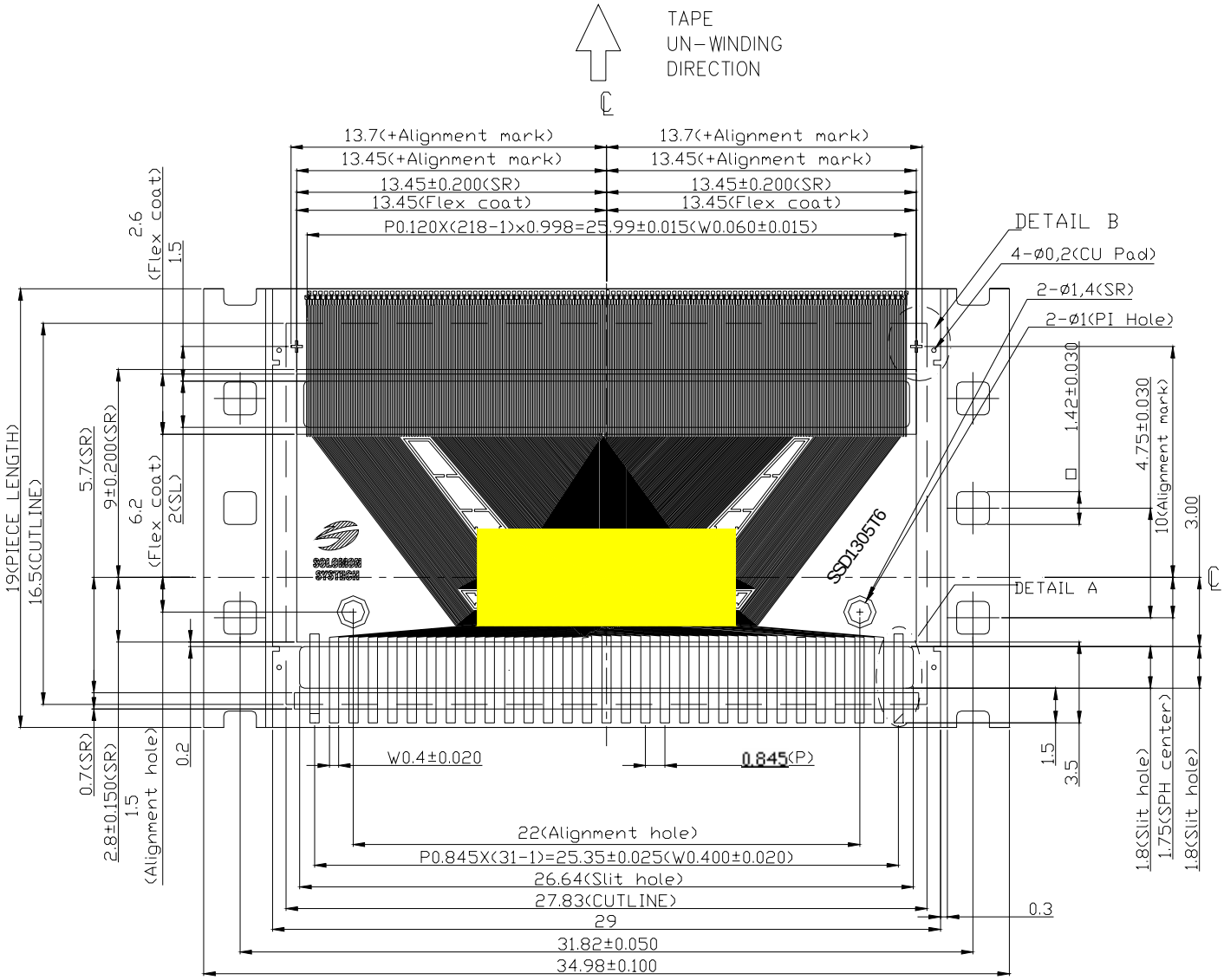
Figure 15-1 SSD1305Z die tray information

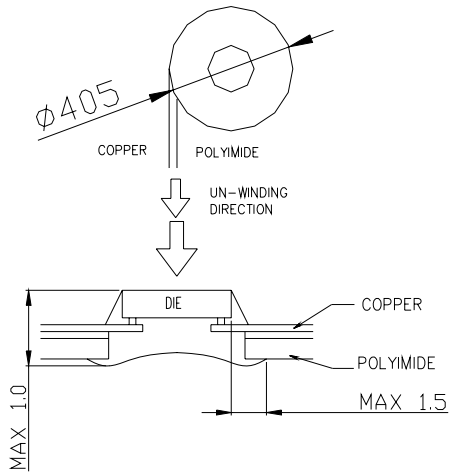


	Spec
	mm (mil)
W1	76.00±0.10(2992)
W2	68.00±0.10(2677)
H	4.20±0.10 (165)
Dx	9.35±0.10 (368)
TPx	57.30±0.10(2256)
Dy	7.30±0.10 (287)
TPy	61.41±0.10(2418)
Px	9.55±0.05 (376)
Py	2.67±0.05 (105)
X	$8.39\pm^{0.1}_{0}$ (330)
Y	$1.37\pm^{0.1}_{0}$ (54)
Z	0.62±0.05 (24)
N	168(pocket number)

15.2 SSD1305T6R1 Detail Dimension

Figure 15-2 SSD1305T6R1 Detail Dimension

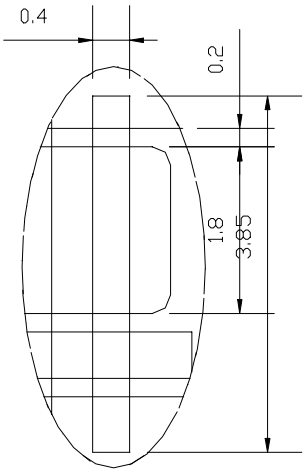




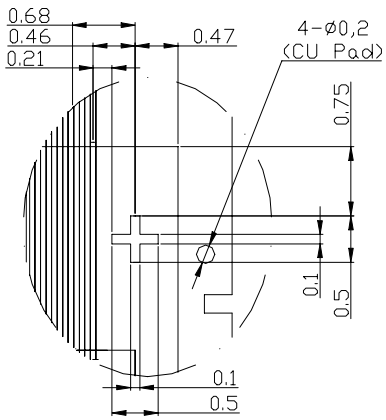
MIRROR DESIGN

NOTE:

1. GENERAL TOLERANCE: ±0.05MM
2. MATERIAL
   PI: 75±6um
   Adhesive: 12±2um thickness
   CU: 18±5um
   SR:26±14um
   TOLERANCE±0.200
   Flex coating :Min 10um
   TOLERANCE ±0.300
3. SN PLATING: 0.200±0.05um
4. TAPESITE: 4 SPH,19mm



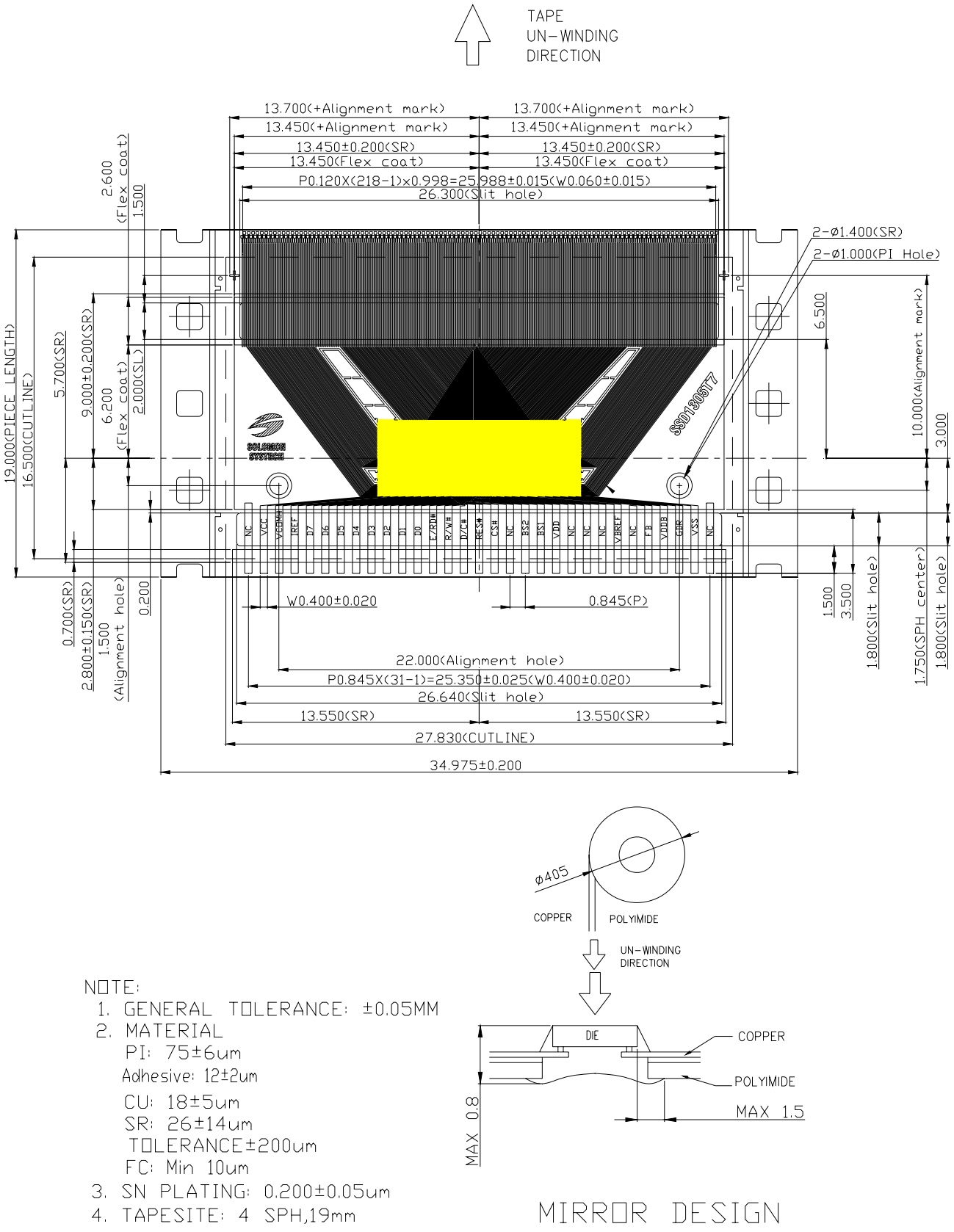
DETAIL A



DETAIL B

15.3 SSD1305T7R1 Detail Dimension

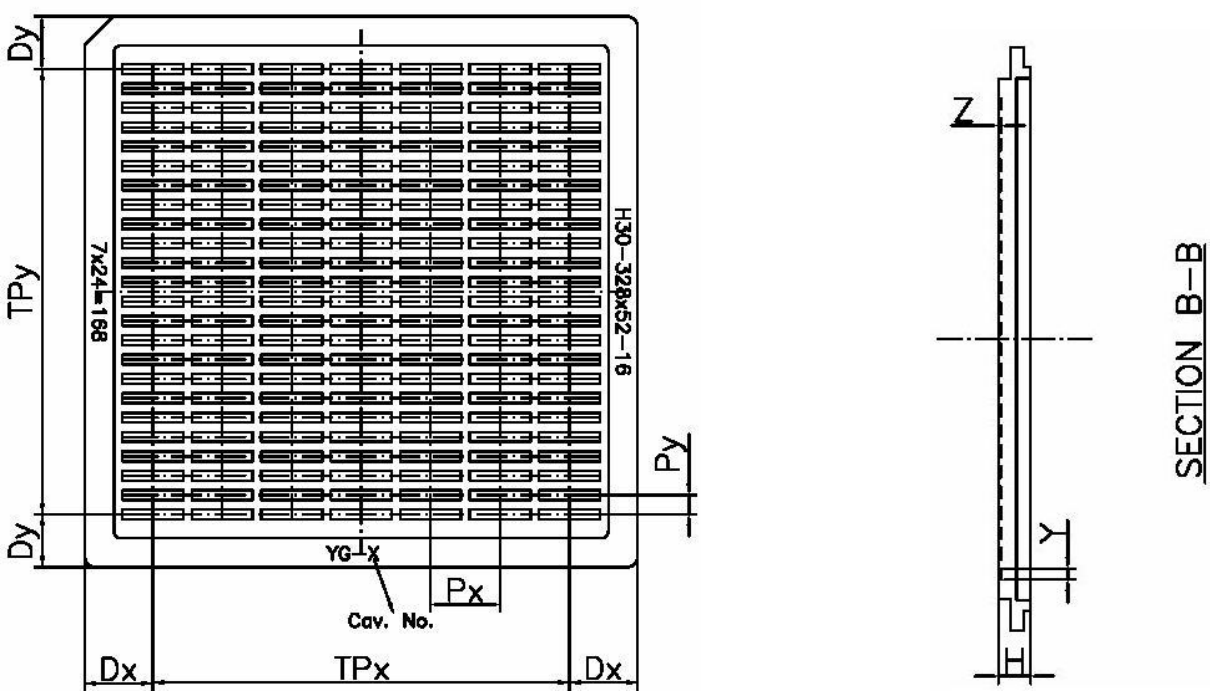
Figure 15-3 SSD1305T7R1 Detail Dimension

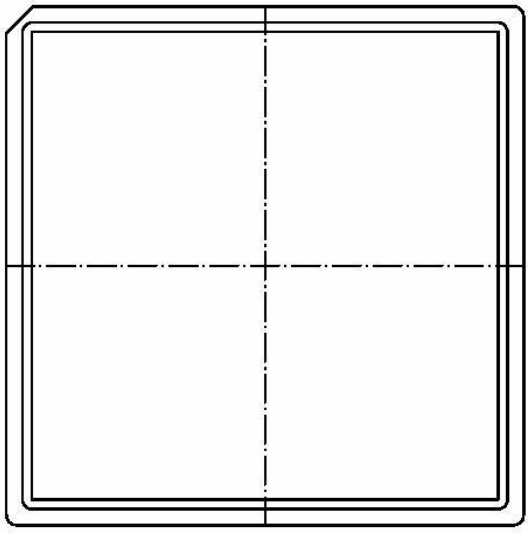


NOTE:
1. GENERAL TOLERANCE: ±0.05MM
2. MATERIAL
   PI: 75±6um
   Adhesive: 12±2um
   CU: 18±5um
   SR: 26±14um
   TOLERANCE±200um
   FC: Min 10um
3. SN PLATING: 0.200±0.05um
4. TAPESITE: 4 SPH,19mm

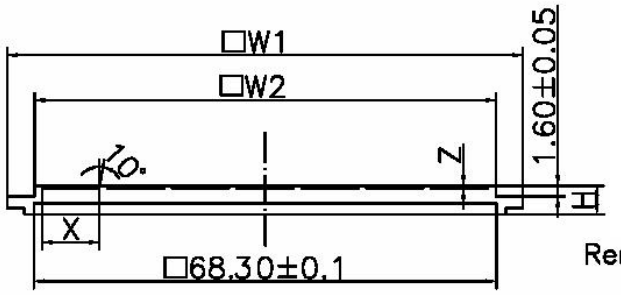
15.4 SSD1305Z3 Die Tray Information

Figure 15-4 SSD1305Z3 die tray information





	Spec
	mm (mil)
W1	76.00±0.10(2992)
W2	68.00±0.10(2677)
H	4.20±0.10 (165)
Dx	9.35±0.10 (368)
TPx	57.30±0.10(2256)
Dy	7.30±0.10 (287)
TPy	61.41±0.10(2418)
Px	9.55±0.05 (376)
Py	2.67±0.05 (105)
X	8.34±0.05 (328)
Y	1.32±0.05 (52)
Z	0.40±0.05 (16)
N	168(pocket number)



SECTION A-A

Remark:

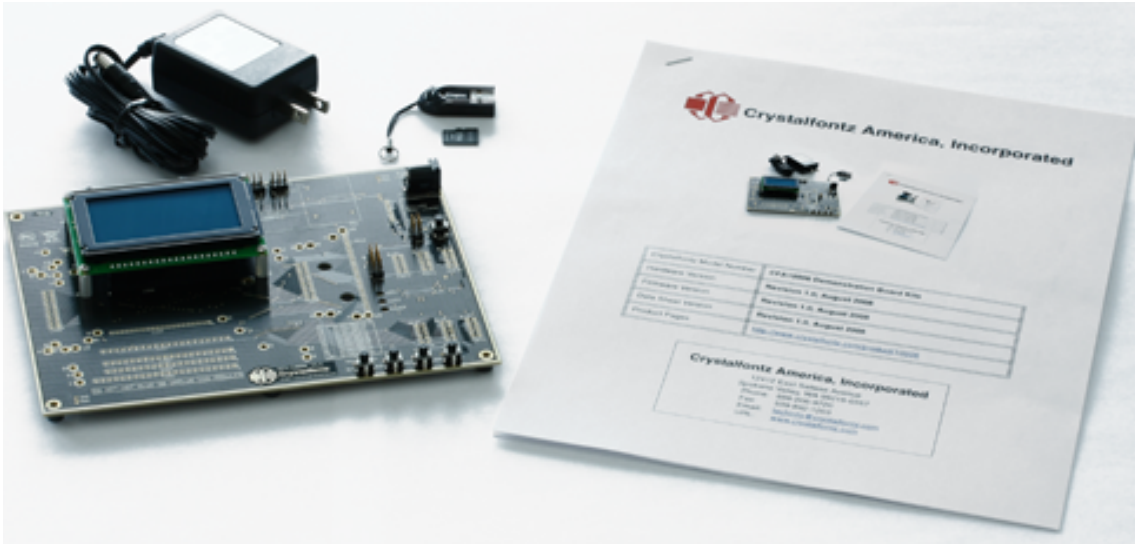
1. Tray Material : ABS
2. Tray Color Code: Black
3. Surface Resistance: 10^{9}~10^{12} Ω/cm
4. Pocket Bottom: Rough Surface

All Solomon Systech Products complied with six (6) hazardous substances limitation requirement per European Union (EU) “Restriction of Hazardous Substance (RoHS) Directive (2002/95/EC)” and China standard “电子信息产品污染控制标识要求 (SJ/T11364-2006)” with control Marking Symbol . Hazardous Substances test report is available upon requested.

http://www.solomon-systech.com

Crystalfontz America, Incorporated

CFA10009 Demonstration Board Kits
User Guide



Crystalfontz Model Number	**CFA10009 Demonstration Board Kits (for OLEDs)**
Hardware Version	**Revision 1.1, June 2009**
Firmware Version	**Revision 1.0, June 2009**
Data Sheet Version	**Revision 1.0, June 2009**
Product Pages	www.crystalfontz.com/product/CFA10009.html

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Email: techinfo@crystalfontz.com
URL: www.crystalfontz.com

REVISION HISTORY

CFA10009 DEMONSTATION BOARD	
2009/06/25	Current demonstration board version: **v1.1** New demonstration board.

CFA10009 DEMONSTRATION BOARD KITS FIRMWARE	
2009/06/25	Current firmware version (series): **v1.0** Initial release.

CFA10009 DEMONSTRATION BOARD KITS USER GUIDE	
2009/06/25	Current Data Sheet version: **v1.0** New Data Sheet.

QUICK START

The CFA10009 demonstration board is shipped with a compatible OLED module of your choice installed and tested. Simply plug the power supply (included) into an AC outlet. The CFA10009 will initialize and turn on the display, then run the demonstration script from the included microSD card.

INTRODUCTION

The CFA10009 Demonstration Board Kit has everything you need to easily demonstrate and experiment with one compatible Crystalfontz OLED module.The kit can also be used as a reference for your designs that use a Crystalfontz OLED module listed in the table on the next page.

You can easily modify the miniBASIC scripts and bitmaps on the microSD card to make your own test screens, or even to model user interface functions. All that is needed is the included microSD USB reader, a text editor (Notepad will do), an image editor (MS Paint will do), and a simple, open-source format conversion utility (Image2Code) that we offer free of charge.

Beyond demonstrations, the CFA10009 allows you to easily measure current of the different portions of the circuit under operation.

The schematic, bill of materials, and even the PCB layout is available for download from our site. (As always, no registration is required.) Since the design materials are available before purchase, there is no risk of being "surprised" late in the design.

The CFA10009 is preprogrammed with a microSD boot loader. You can load our simple C example code, the miniBASIC interpreter, or build your own application for the CFA10009's versatile Atmel ATMEGA2561 microcontroller using AVR Studio and WinAVR (both free).

The board has a JTAG port for more advanced programming and debugging. All the ports are on 0.1" centers so you can connect them to anything you need. The CFA10009 is so versatile that you may want to use it as a base development platform for your projects.

CFA10009 KIT CONFIGURATIONS

FOR OLED MODULE	WITH THIS CONTROLLER	ORDER THIS DEMONSTRATION BOARD KIT	BLOCK DIAGRAM
CFAL12822A-Y-B	Solomon SSD1305	DMO-L12822AYB	Figure 2.
CFAL12822A-Y-B1	Solomon SSD1305	DMO-L12822AYB1	Figure 1.
CFAL12832C-W-B1	Sino Wealth SH1101A	DMO-L12832CWB1	Figure 1.
CFAL12864C-Y-B1	Solomon SSD1305	DMO-L12864CYB1	Figure 1.
CFAL12864L-G-B2	Solomon SSD1305	DMO-L12864LGB2	Figure 2.
CFAL12864L-Y-B2	Solomon SSD1305	DMO-L12864LYB2	Figure 2.
CFAL12864L-G-B2TS	Solomon SSD1305	DMO-L12864LGB2TS	Figure 4.
CFAL12864L-Y-B2TS	Solomon SSD1305	DMO-L12864LYB2TS	Figure 4.
CFAL12864L-G-B4	Solomon SSD1305	DMO-L12864LGB4	Figure 2.
CFAL12864L-Y-B4	Solomon SSD1305	DMO-L12864LYB4	Figure 2.
CFAL12864L-G-B6	Solomon SSD1305	DMO-L12864LGB6	Figure 2.
CFAL12864L-G- B6TS	Solomon SSD1305	DMO-L12864LGB6TS	Figure 3.
CFAL12864L-Y- B6TS	Solomon SSD1305	DMO-L12864LYB6TS	Figure 3.
CFAL12864L-W- B6TS	Solomon SSD1305	DMO-L12864LWB6TS	Figure 3.
CFAL12864N-A-B1	Sino Wealth SH1101A	DMO-L12864NAB1	Figure 1.
CFAL12864S-Y-B1	Solomon SSD1303	DMO-L12864SYB1	Figure 1.
CFAL12864U-W-B1	Solomon SSD1303	DMO-L12864UWB1	Figure 1.
CFAL12864Z-G-B2	Solomon SSD1325	DMO-L12864ZGB2	Figure 2.
CFAL12864Z-Y-B2	Solomon SSD1325	DMO-L12864ZYB2	Figure 2.
CFAL12864Z-G-B2TS	Solomon SSD1325	DMO-L12864ZGB2TS	Figure 4.
CFAL12864Z-Y-B2TS	Solomon SSD1325	DMO-L12864YB2TS	Figure 4.
CFAL12864Z-G-B4	Solomon SSD1325	DMO-L12864ZGB4	Figure 2.
CFAL12864Z-Y-B4	Solomon SSD1325	DMO-L12864ZYB4	Figure 2.
CFAL12864Z-G-B6	Solomon SSD1325	DMO-L12864ZGB6	Figure 2.
CFAL12864Z-W-B6	Solomon SSD1325	DMO-L12864ZWB6	Figure 2.
CFAL12864Z-Y-B6	Solomon SSD1325	DMO-L12864ZYB6	Figure 2.

FOR OLED MODULE	WITH THIS CONTROLLER	ORDER THIS DEMONSTRATION BOARD KIT	BLOCK DIAGRAM
CFAL12864Z-G-B6TS	Solomon SSD1325	DMO-L12864ZGB6TS	Figure 3.
CFAL12864Z-W-B6TS	Solomon SSD1325	DMO-L12864ZWB6TS	Figure 3.
CFAL12864Z-Y-B6TS	Solomon SSD1325	DMO-L12864ZYB6TS	Figure 3.
CFAL25664A-Y-B1	ST STV8105	DMO-L25664AYB1	Figure 1.
CFAL9664A-W-B1	Solomon SSD1305	DMO-L9664AWB1	Figure 1.

CONTENTS OF DEMONSTRATION BOARD KIT

- ❑ CFA10009 Demonstration Board (PCB).
- ❑ Installed OLED module of your choice. (Selected at time of ordering. See choices in the table above.)
- ❑ Power adapter.
- ❑ MicroSD memory card loaded with BASIC demonstration program and bitmap images.
- ❑ USB reader for the microSD memory card.

In addition to the kit contents, a zipped folder of hardware design and program files is available at http://www.crystalfontz.com/product/CFA10009.html. (Free download.)

HOW TO MAKE A CUSTOM DEMONSTRATION

The CFA10009 is programmed with firmware that will read a BASIC program file from the microSD memory card. The BASIC program can read bitmap image files from the microSD memory card and display them on the OLED module. The BASIC program can also read the four demonstration board buttons and change the brightness settings.

By using the USB reader, a text editor, and a graphic conversion utility (provided), you can customize the demonstration to include your own bitmap images. The large capacity of the microSD card allows you to create complex demonstrations.

For the most recent version of the graphic conversion utility, sample scripts, and sample images for customizing the demonstration, download the zipped folder at http://www.crystalfontz.com/product/CFA10009.html.

LOADING A CUSTOM HEX FILE

The CFA10009 Demonstration Board Kit is shipped with the miniBasic-AVR interpreter loaded into the microcontroller Atmel ATMEGA2561's flash memory.

If you want to load our simple demonstration or your own program, simply name the hex file "cfa10009.hex" and copy it into the root the directory of the microSD card. When the CFA10009 boots, the boot loader will program the ATMEGA2561's flash with "cfa10009.hex" and then execute it.

Acknowledgement Note: The miniBASIC-AVR is a derivative of this (see http://www.personal.leeds.ac.uk/~bgy1mm/Minibasic/MiniBasicHome.html). The miniBASIC-AVR also includes the EFSL embedded filesystems library (see http://efsl.be/.

HARDWARE DESIGN INFORMATION

BLOCK DIAGRAM

Here are block diagrams of the CFA10009 Demonstration Board with different types of installed modules:

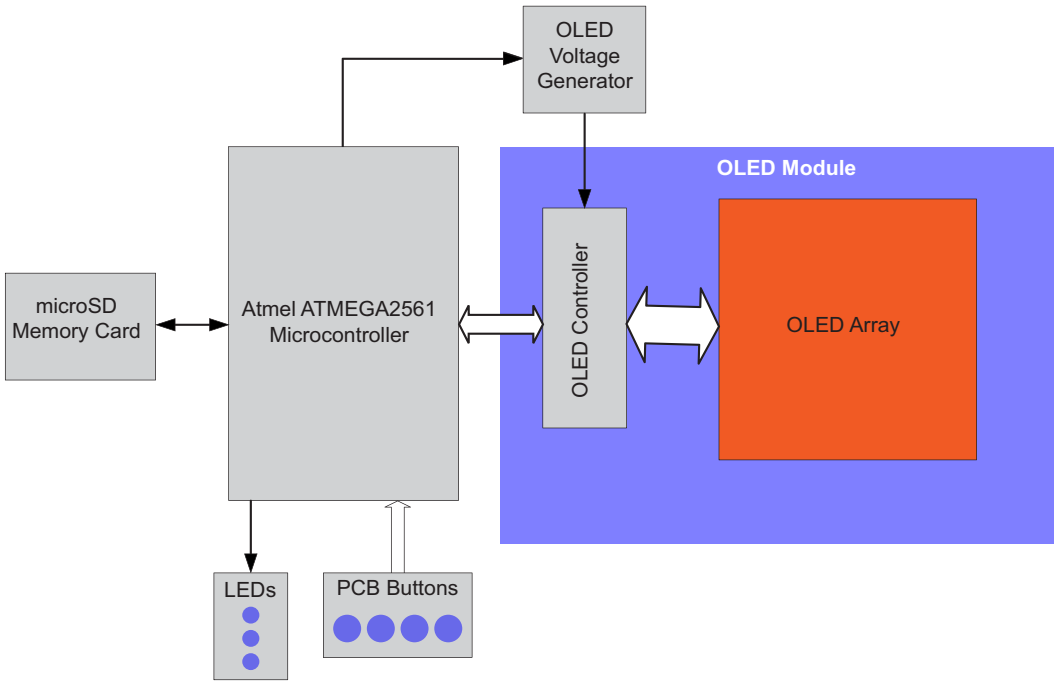

Figure 1. For kits with CFAL12822A-Y-B1,CFAL12832C-W-B1,CFAL12864C-Y-B1,CFAL12864N-A-B1, CFAL12864S-Y-B1, CFAL25664A-Y-B1, and CFAL9664A-W-B1

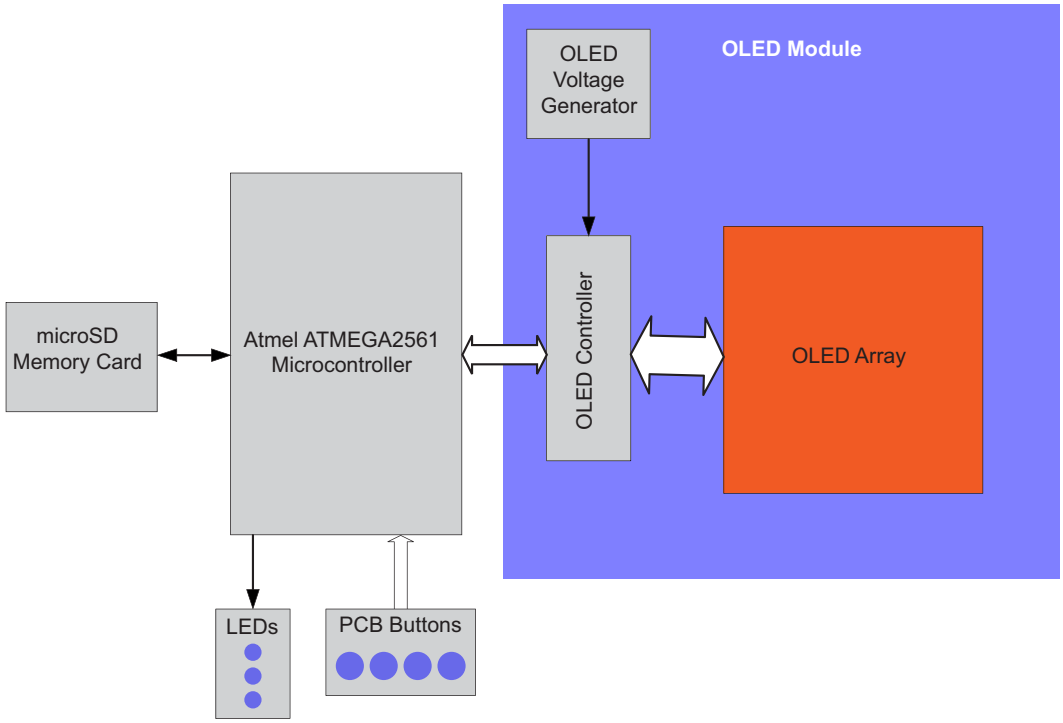

Figure 2. For kits with CFAL12822A-Y-B, CFAL12864L-G-B2, CFAL12864L-Y-B2, CFAL12864L-G-B4,CFAL12864L-Y-B4, CFAL12864L-G-B6, CFAL12864Z-G-B2, CFAL12864Z-Y-B2, CFAL12864Z-G-B4, CFAL12864Z-Y-B4, CFAL12864Z-G-B6,CFAL12864Z-W-B6, and CFAL12864Z-Y-B6

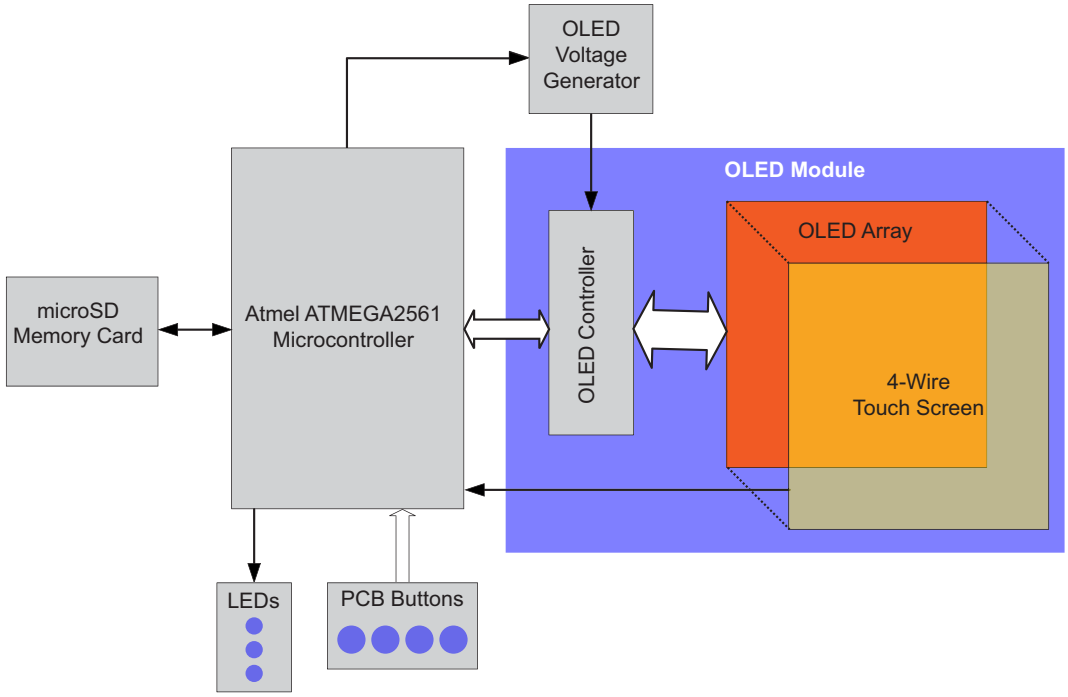

Figure 3. For kits with CFAL12864L-G- B6TS, CFAL12864L-Y- B6TS, and CFAL12864L-W- B6TS

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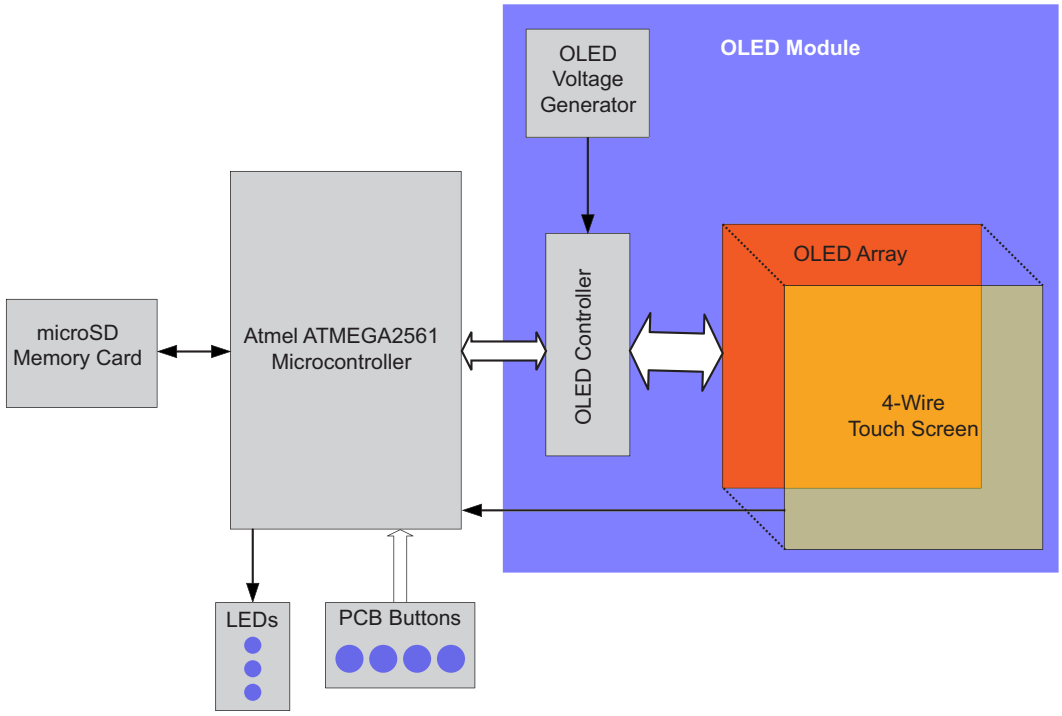

Figure 4. CFAL12864L-G-B2TS,CFAL12864L-Y-B2TS,CFAL12864L-G- B6TS, CFAL12864L-Y- B6TS, CFAL12864Z-G-B2TS, CFAL12864Z-Y-B2TS, CFAL12864Z-G-B6TS, CFAL12864Z-W-B6TS, and CFAL12864Z-Y-B6TS

CONTENTS OF HARDWARE DESIGN FOLDER

The zipped folder at http://www.crystalfontz.com/product/CFA10009.html includes the complete hardware design of the CFA10009 Demonstration Board.

- ❑ Schematic.
- ❑ PCB layout.
- ❑ Bill Of Materials (BOM) as an XLS spreadsheet.
- ❑ Simple OLED initialization code and bitmap display code.

The schematic and PCB layout were created with CadSoft EAGLE. EAGLE is a capable and low-cost electrical CAD system. You can download a freeware light edition of EAGLE from http://www.cadsoft.de/ to load, view, and print the schematic and layout files.

CARE AND HANDLING PRECAUTIONS

The kit is sold with a module mounted on it. If you attempt to modify the board to work with other modules, the warranty is void. Do not disassemble or modify the CFA10009 Demonstration Board Kit.

For optimum operation of the module and demonstration board and to prolong their life, please follow the precautions below.

ESD (ELECTRO-STATIC DISCHARGE)

The circuitry is industry standard CMOS logic and susceptible to ESD damage. Please use industry standard antistatic precautions as you would for any other PCB such as expansion cards or motherboards. Ground your body, work surfaces, and equipment.

AVOID SHOCK, IMPACT, TORQUE, OR TENSION

- Do not expose the demonstration board and module to strong mechanical shock, impact, torque, or tension.
- Do not drop, toss, bend, or twist the demonstration board and module.
- Do not place weight or pressure on the demonstration board and module.

OPERATION

- The module ships with a protective film over the display. Please peel off the protective film slowly. Peeling off the protective film abruptly may generate static electricity.
- Use only the included AC adapter to power the board.
- Observe the operating temperature limitations for the module: from -20°C minimum to +70°C maximum with minimal fluctuations. Operation outside of these limits may shorten the life and/or harm the display.
- Operate away from dust, moisture, and direct sunlight.

CLEANING

- The polarizer (laminated to the glass) is soft plastic. The soft plastic is easily scratched or damaged. Be very careful when you clean the polarizer.
- Do not clean the polarizer with liquids. Do not wipe the polarizer with any type of cloth or swab (for example, Q-tips).
- Use the removable protective film to remove smudges (for example, fingerprints) and any foreign matter. If you no longer have the protective film, use standard transparent office tape (for example, Scotch® brand “Crystal Clear Tape”). If the polarizer is dusty, you may carefully blow it off with clean, dry, oil-free compressed air.

STORAGE AND RECYCLING

- Store in an ESD-approved container away from dust, moisture, and direct sunlight.
- Observe the storage temperature limitations: from -30°C minimum to +80°C maximum with minimal fluctuations. Rapid temperature changes can cause moisture to form, resulting in permanent damage.
- Do not allow weight to be placed on the modules while they are in storage.
- Please recycle the demonstration board and module at an approved facility.